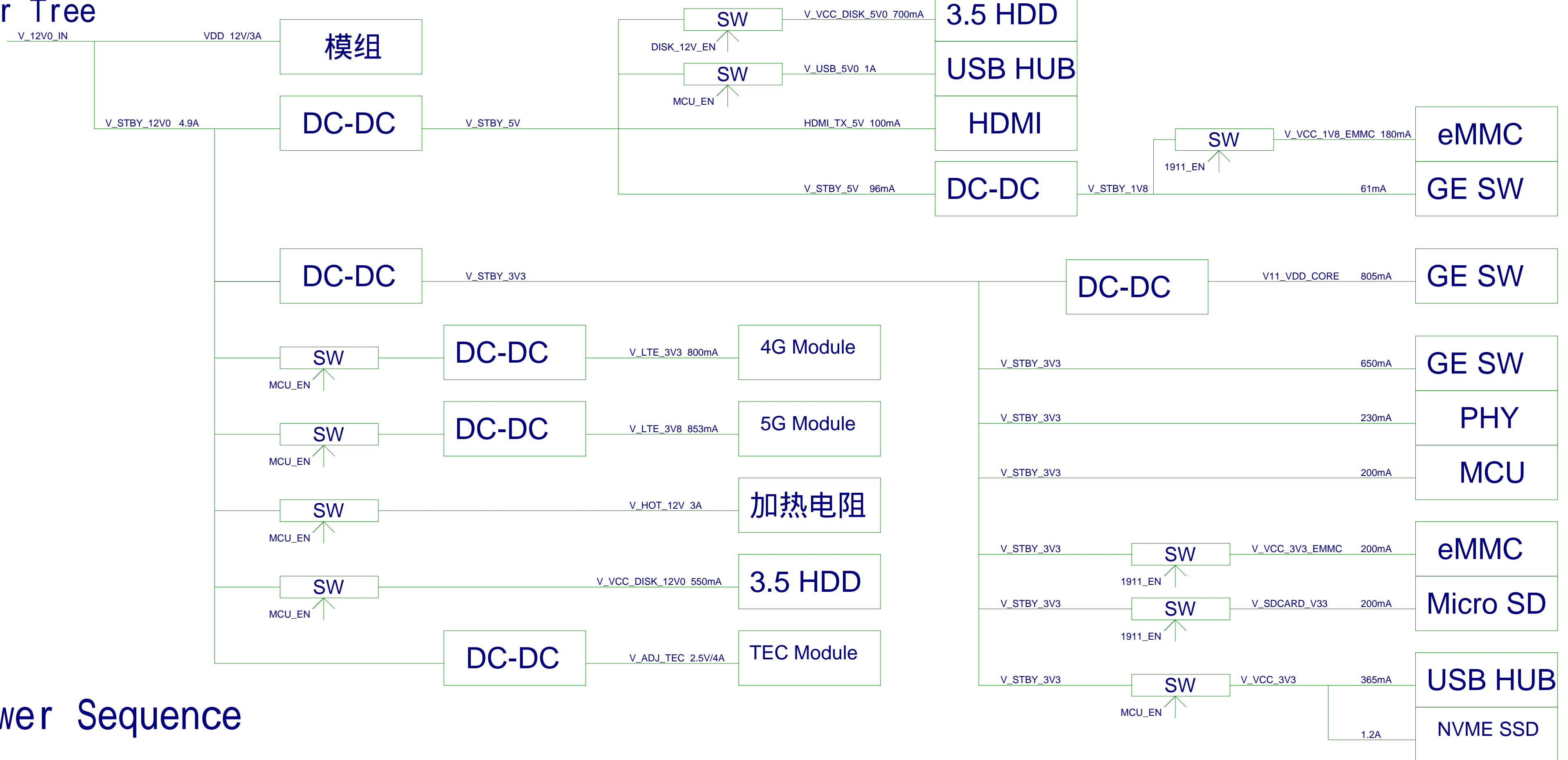


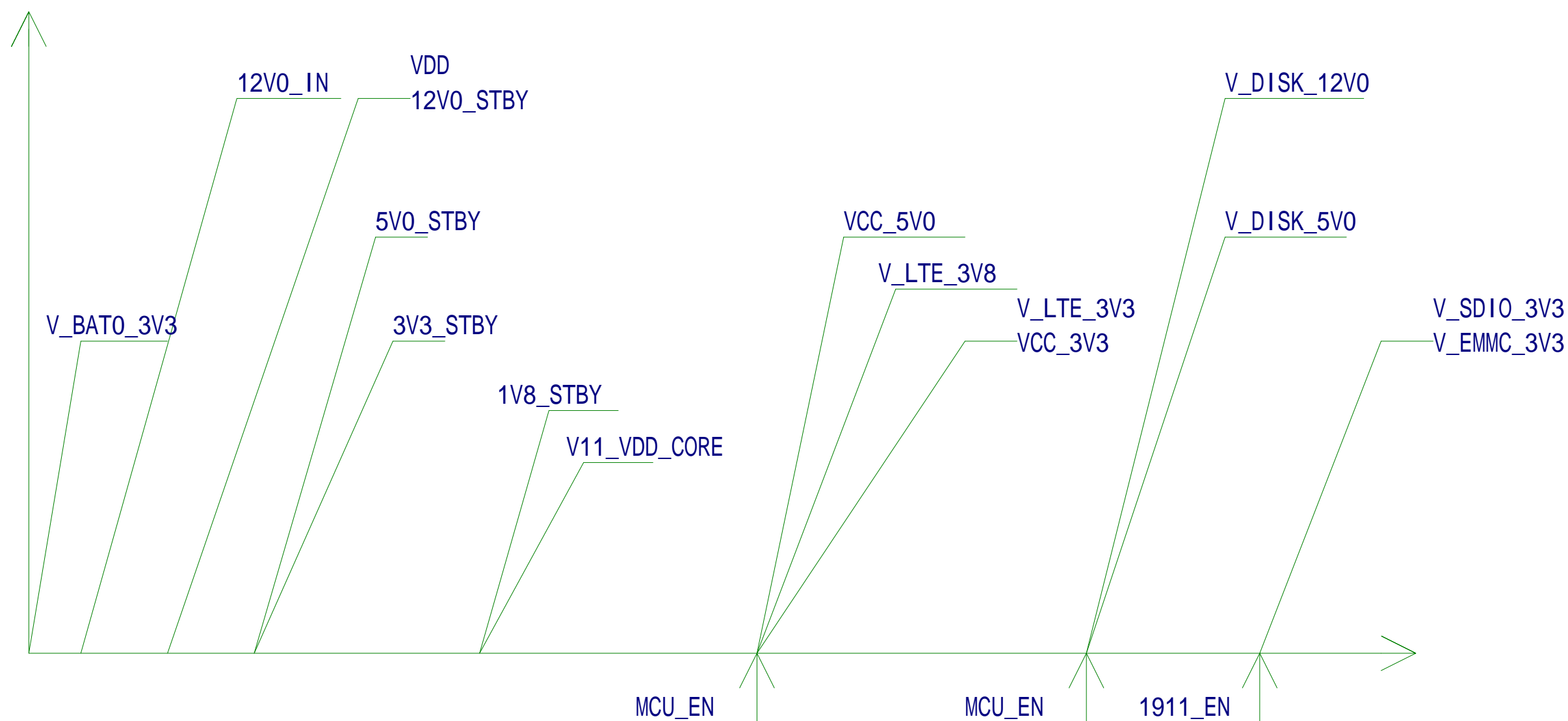
Atlas 200I A2 底板电路参考设计

Department : Ascend Computing Hardware Program

Power Tree



Power Sequence



Block Diagram

A

A

B

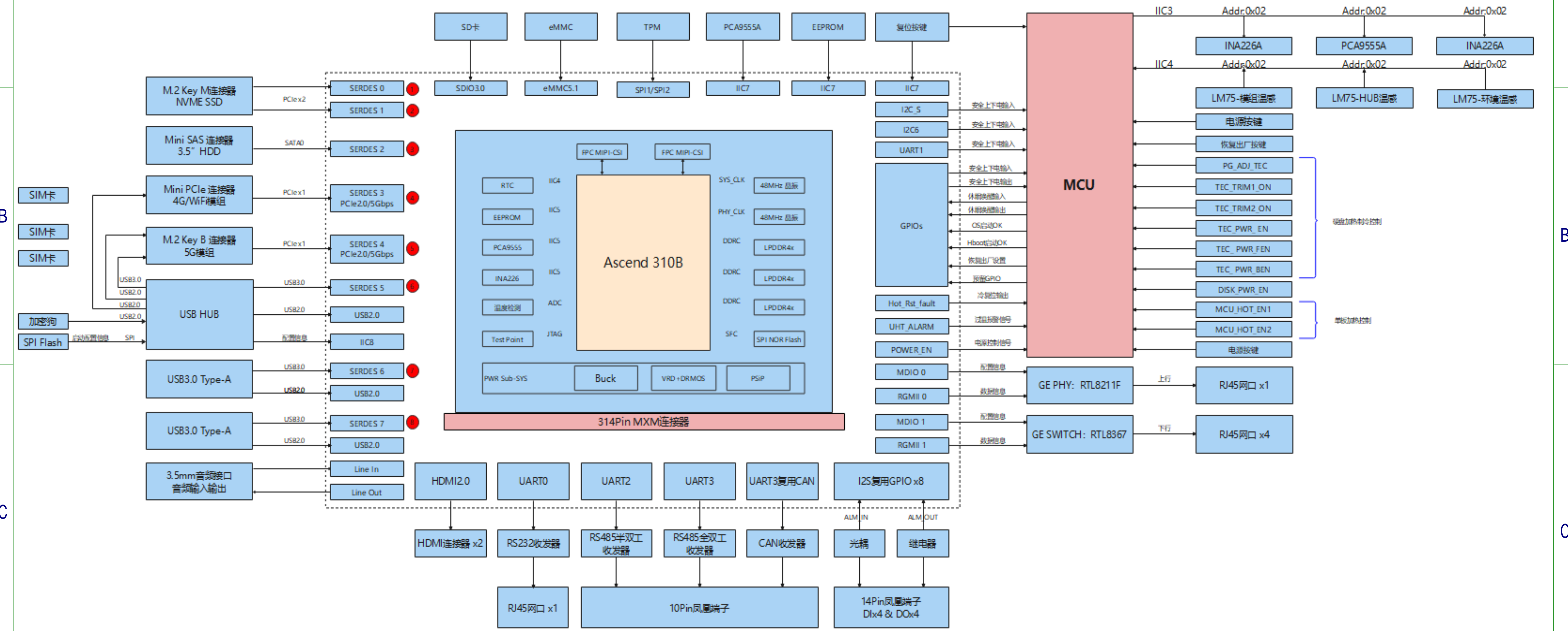
B

C

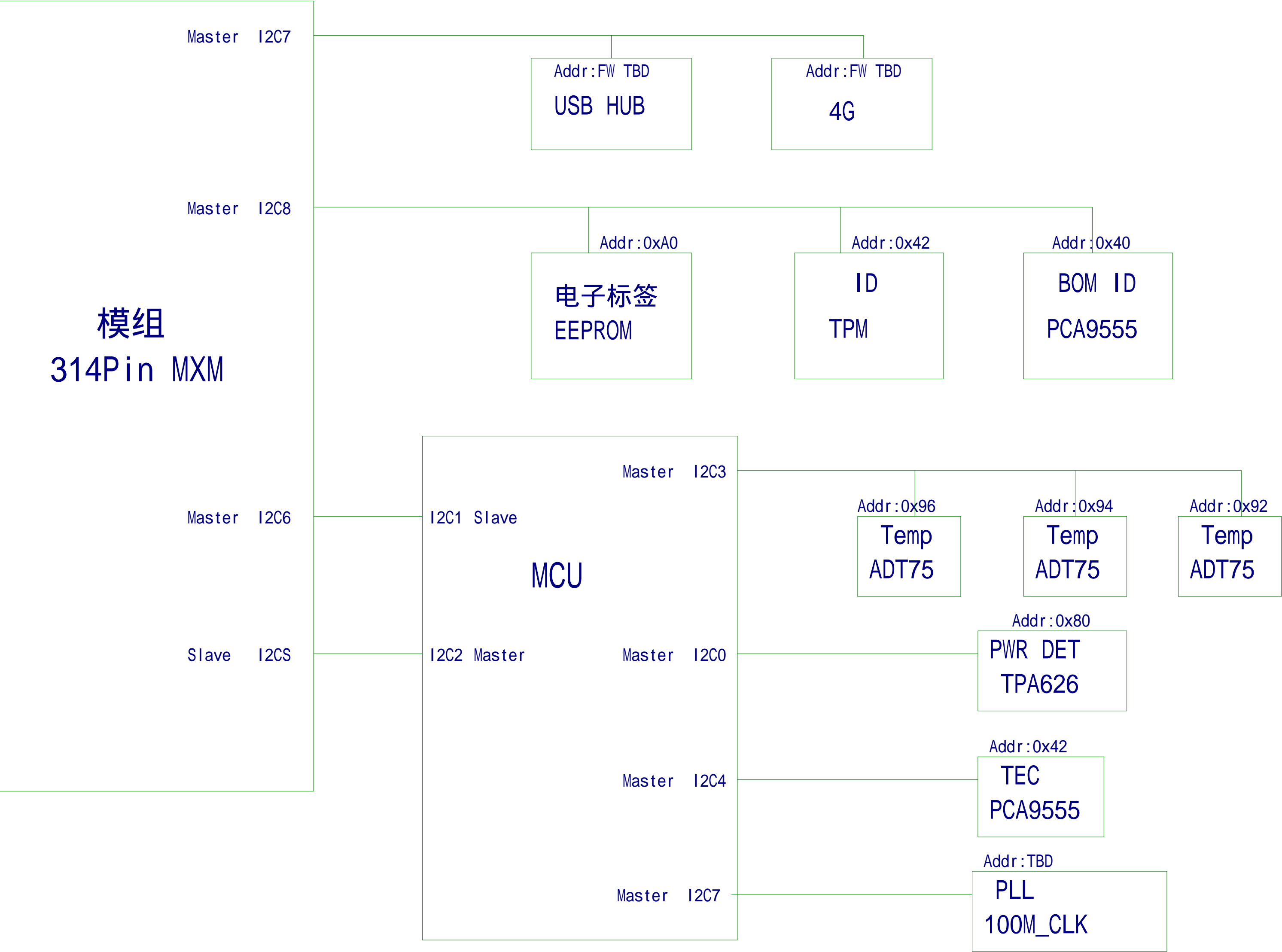
C

D

D



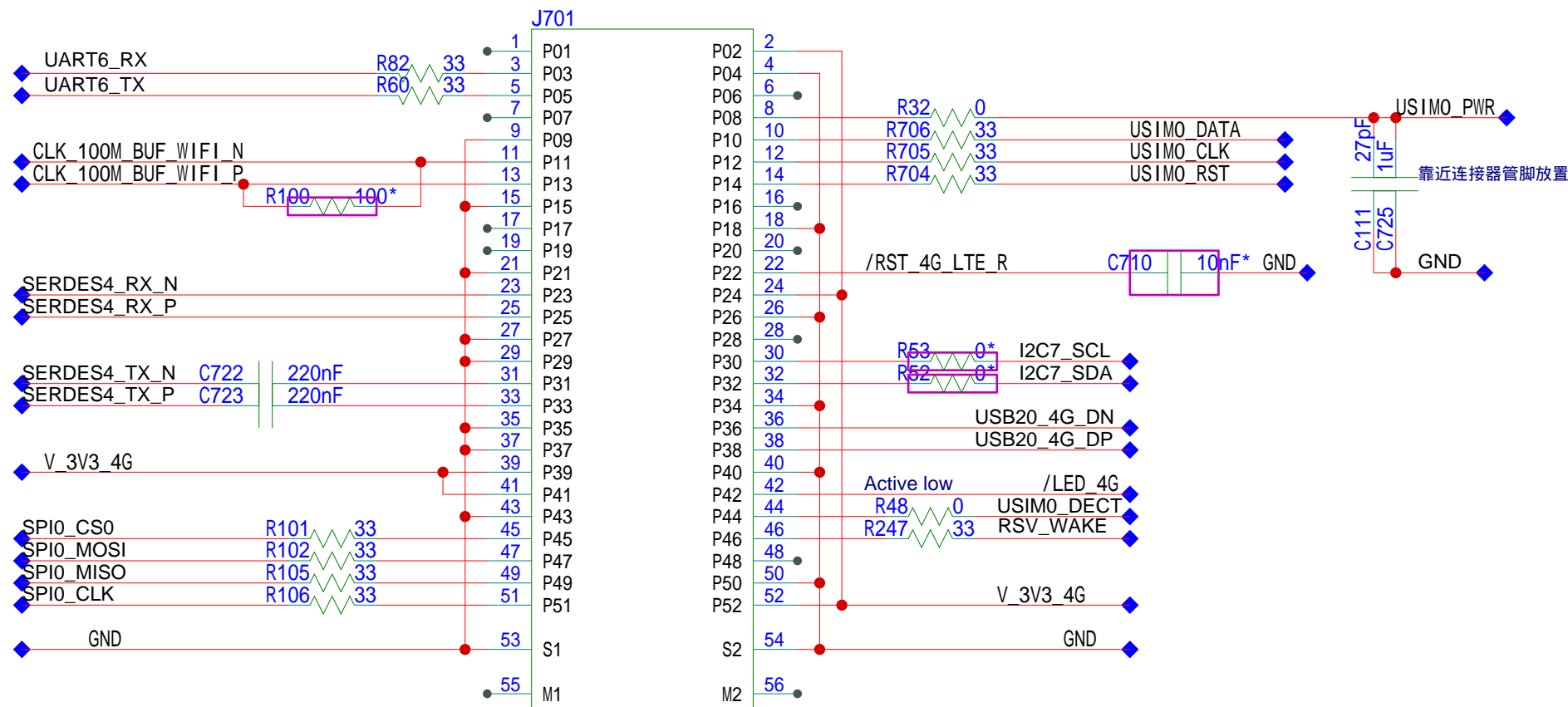
I2C Block Diagram



A

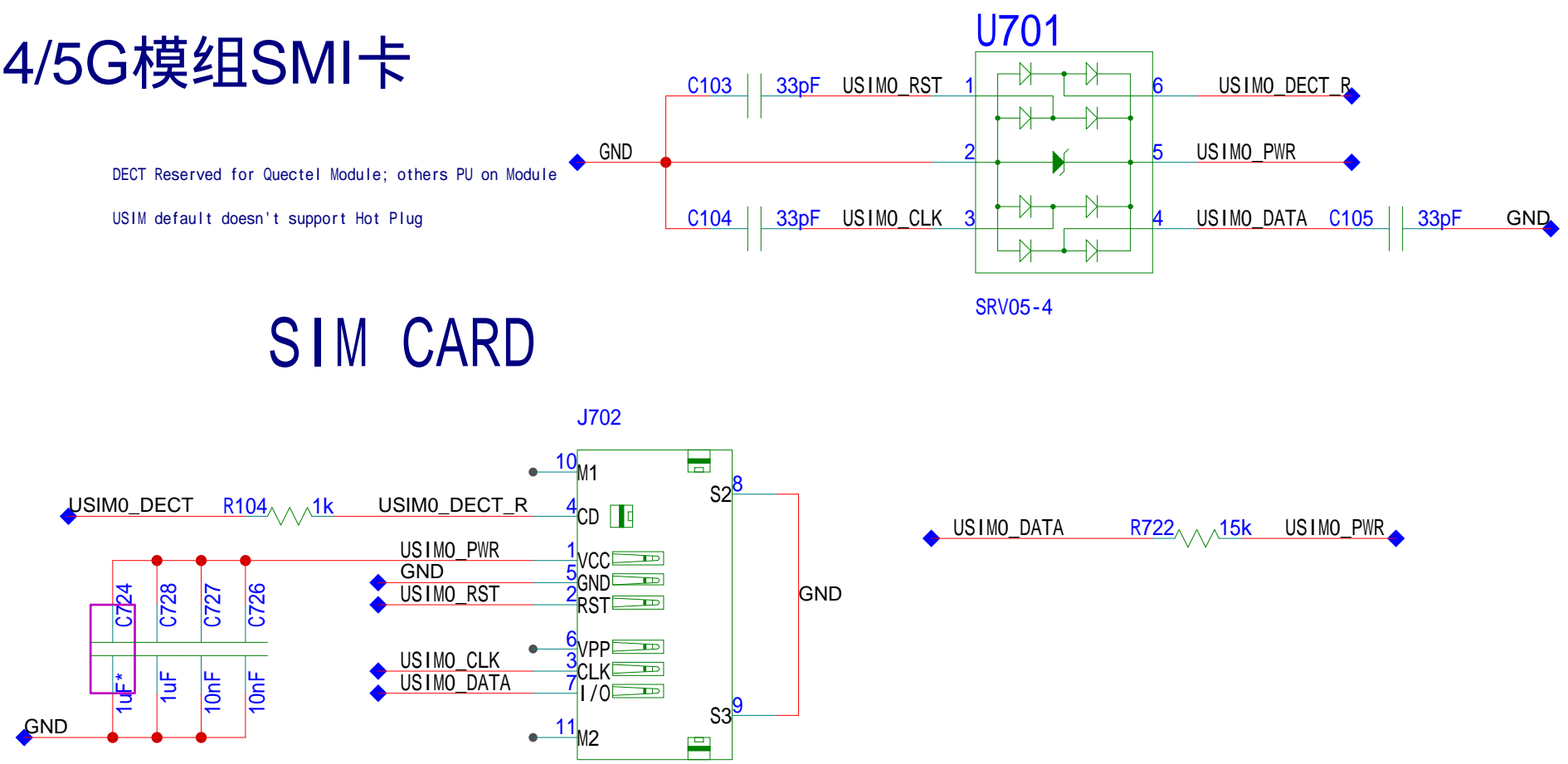


Mini WiFi/4G

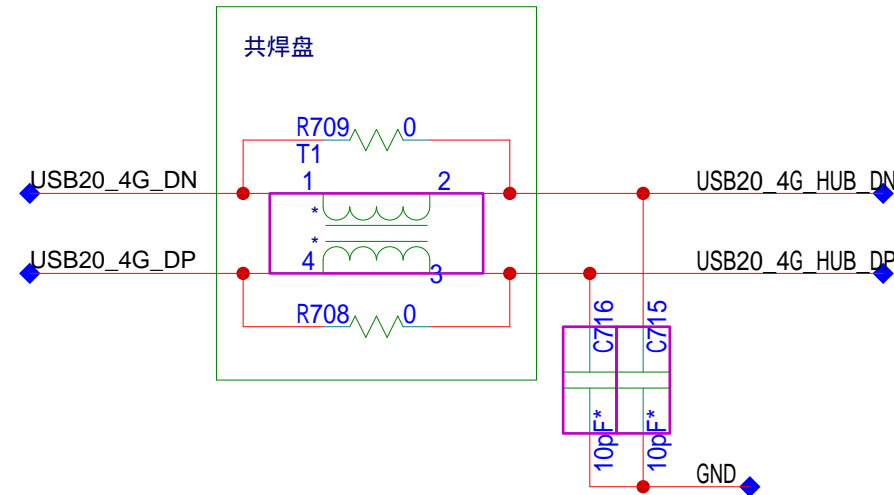
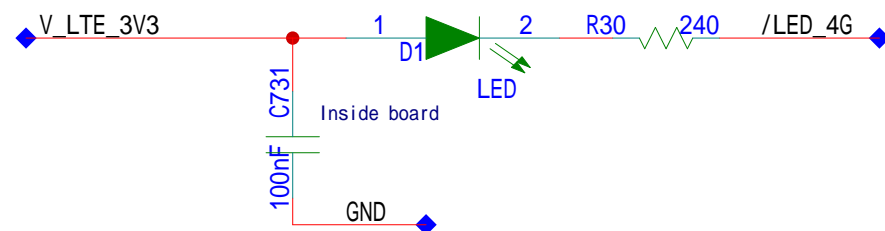


4/5G模组SMI卡

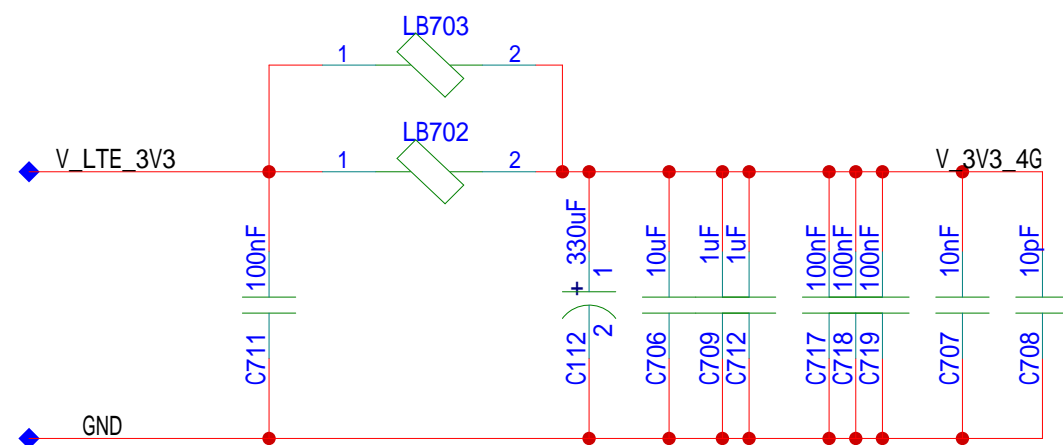
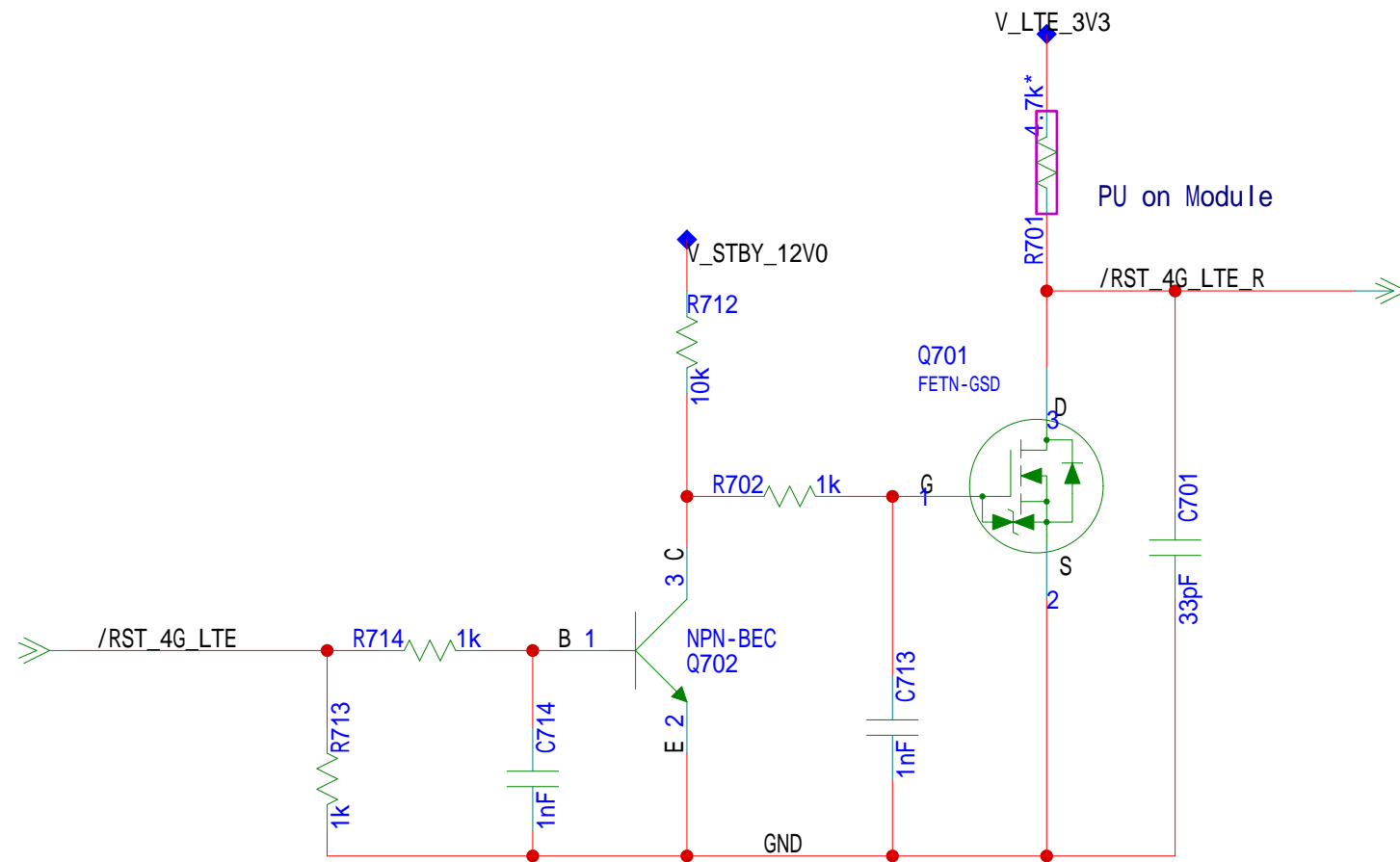
SIM CARD



模块状态指示灯



RST



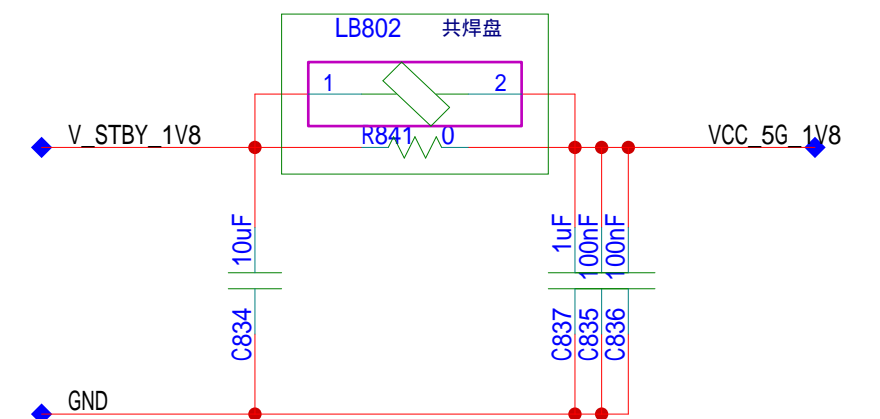
A



B



C



C

D

D

A

B

C

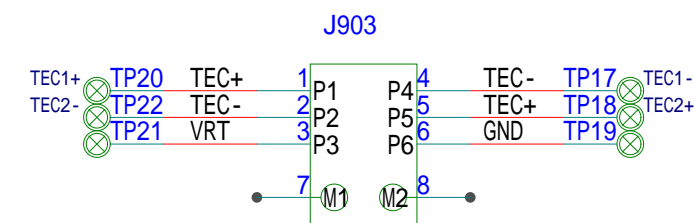
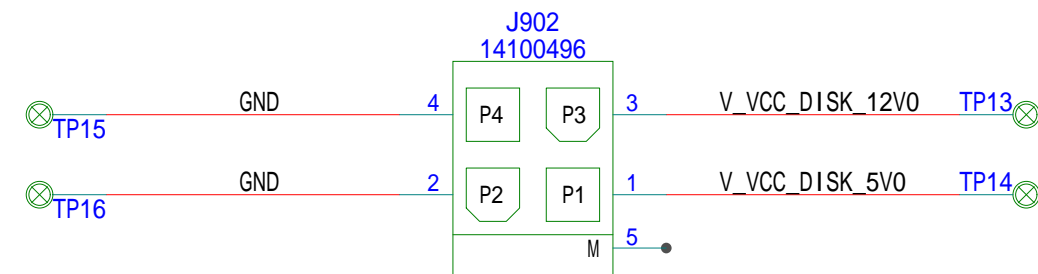
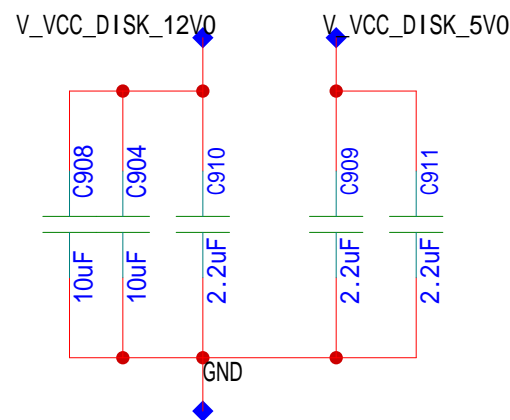
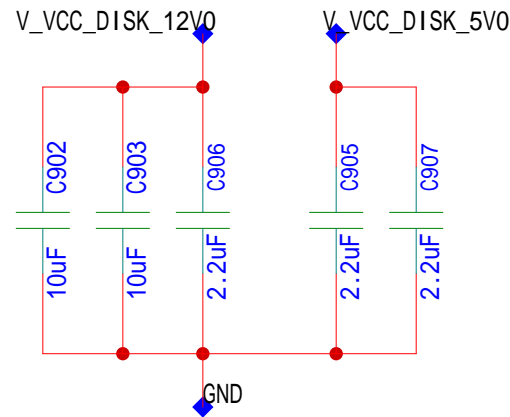
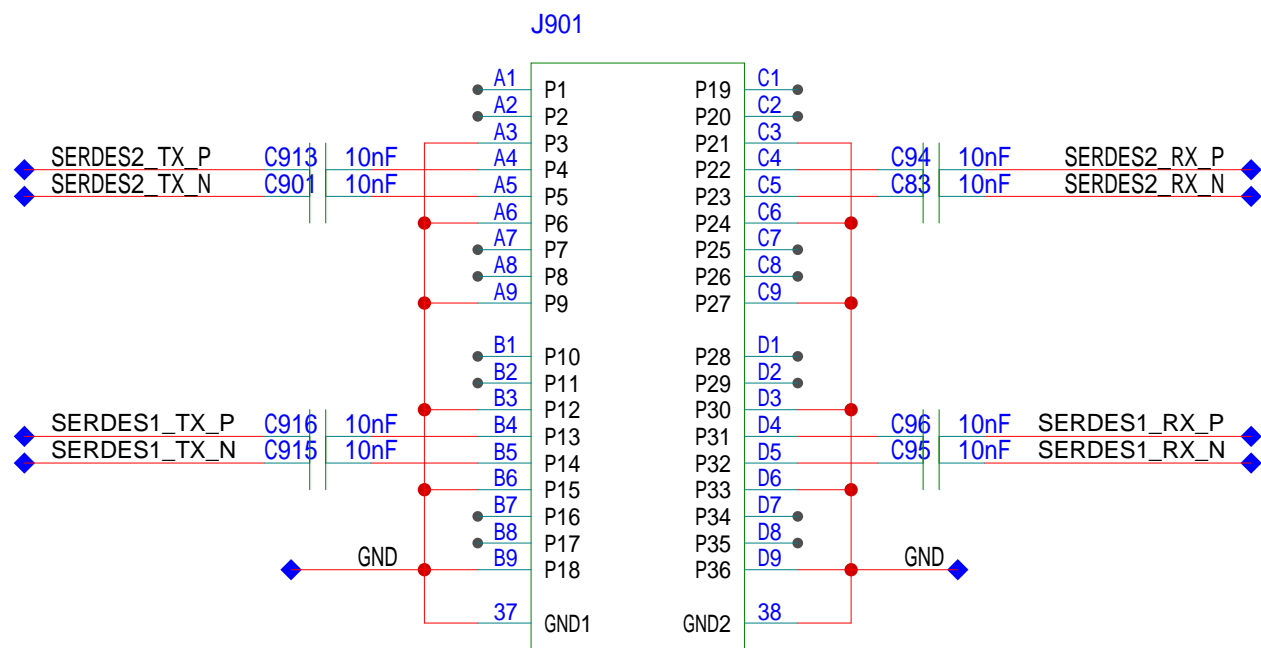
D

A

B

C

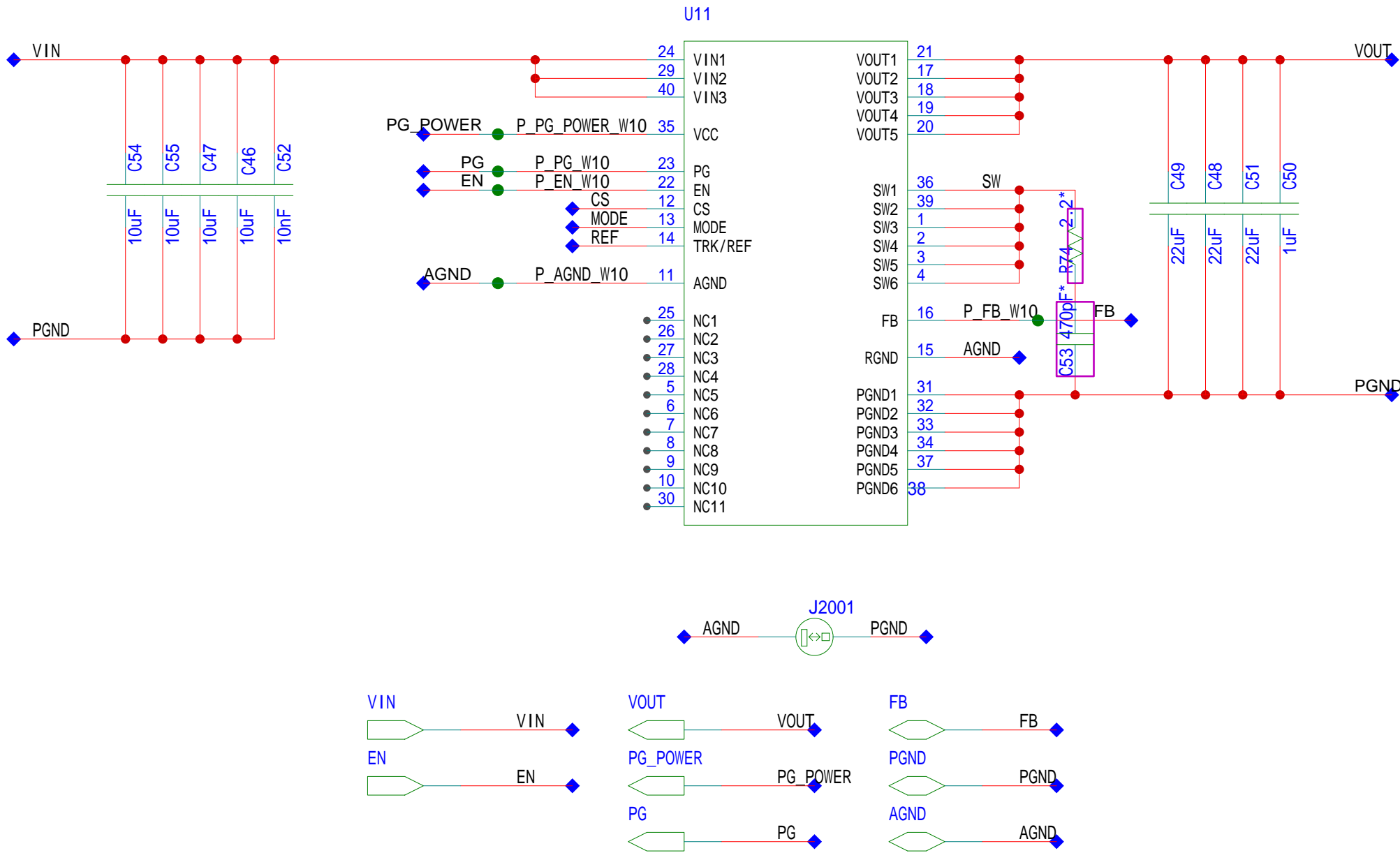
D



A

C

DC-DC CBB

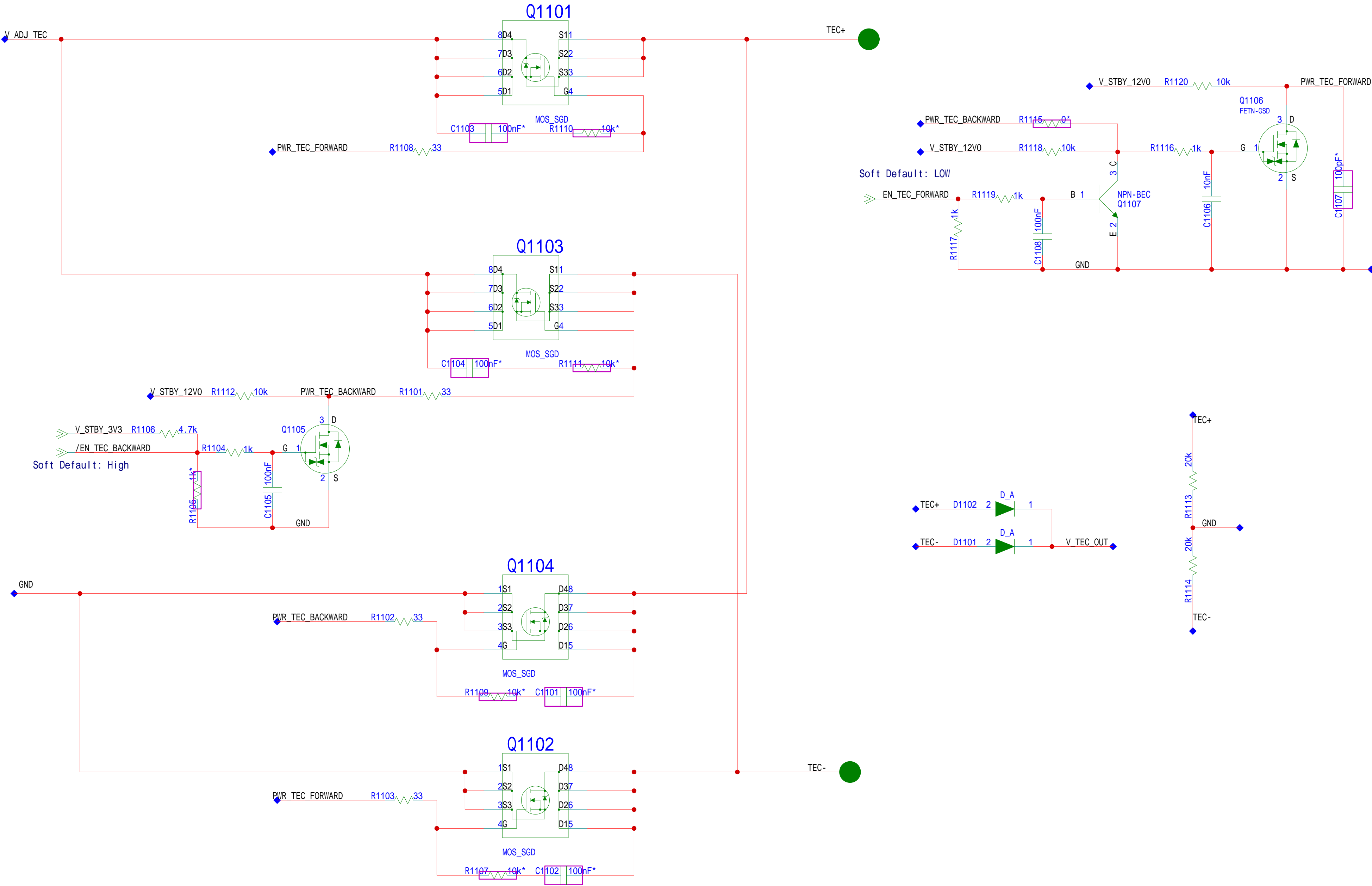


NOTE:详细资料参考应用设计指导书

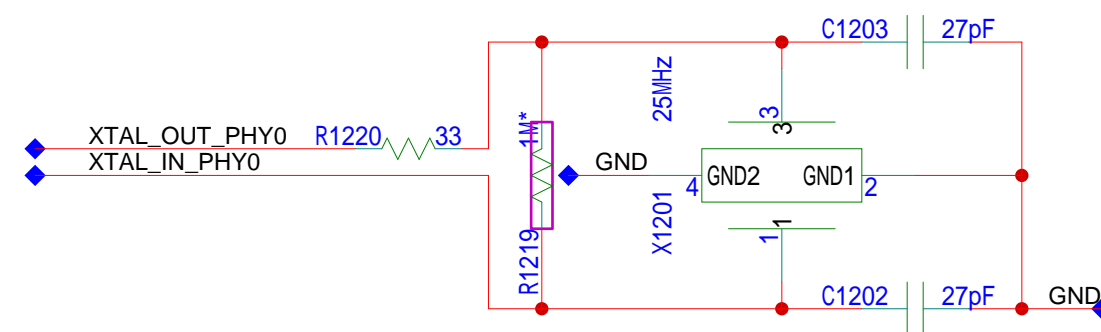
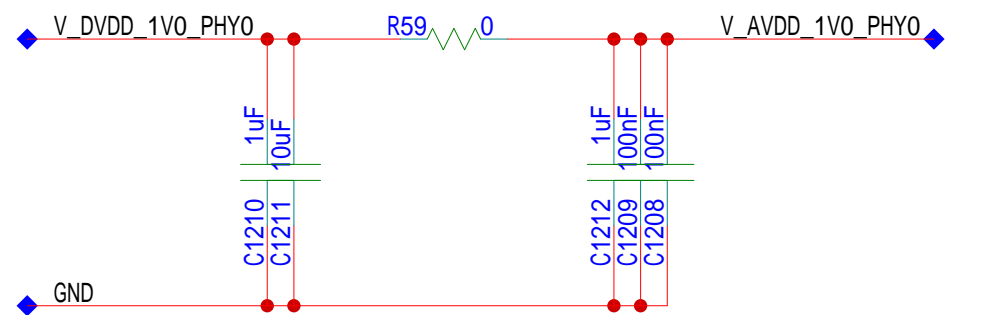
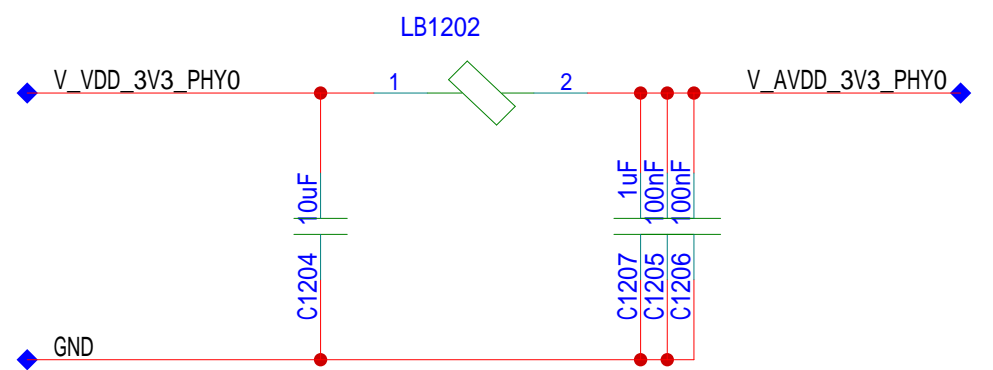
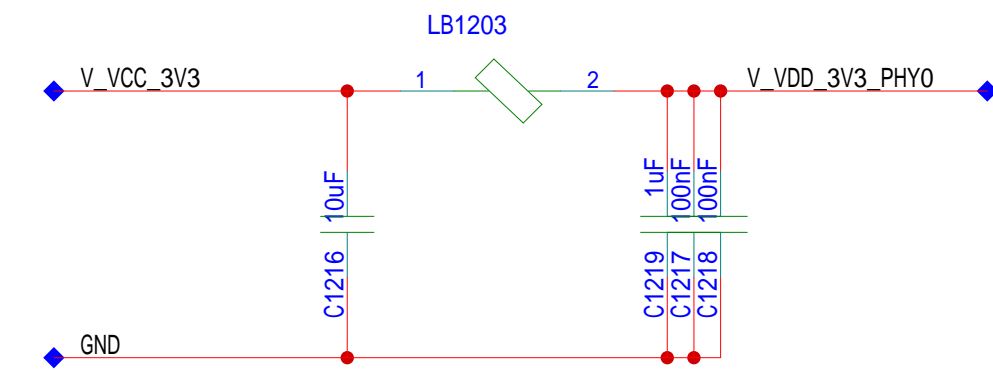
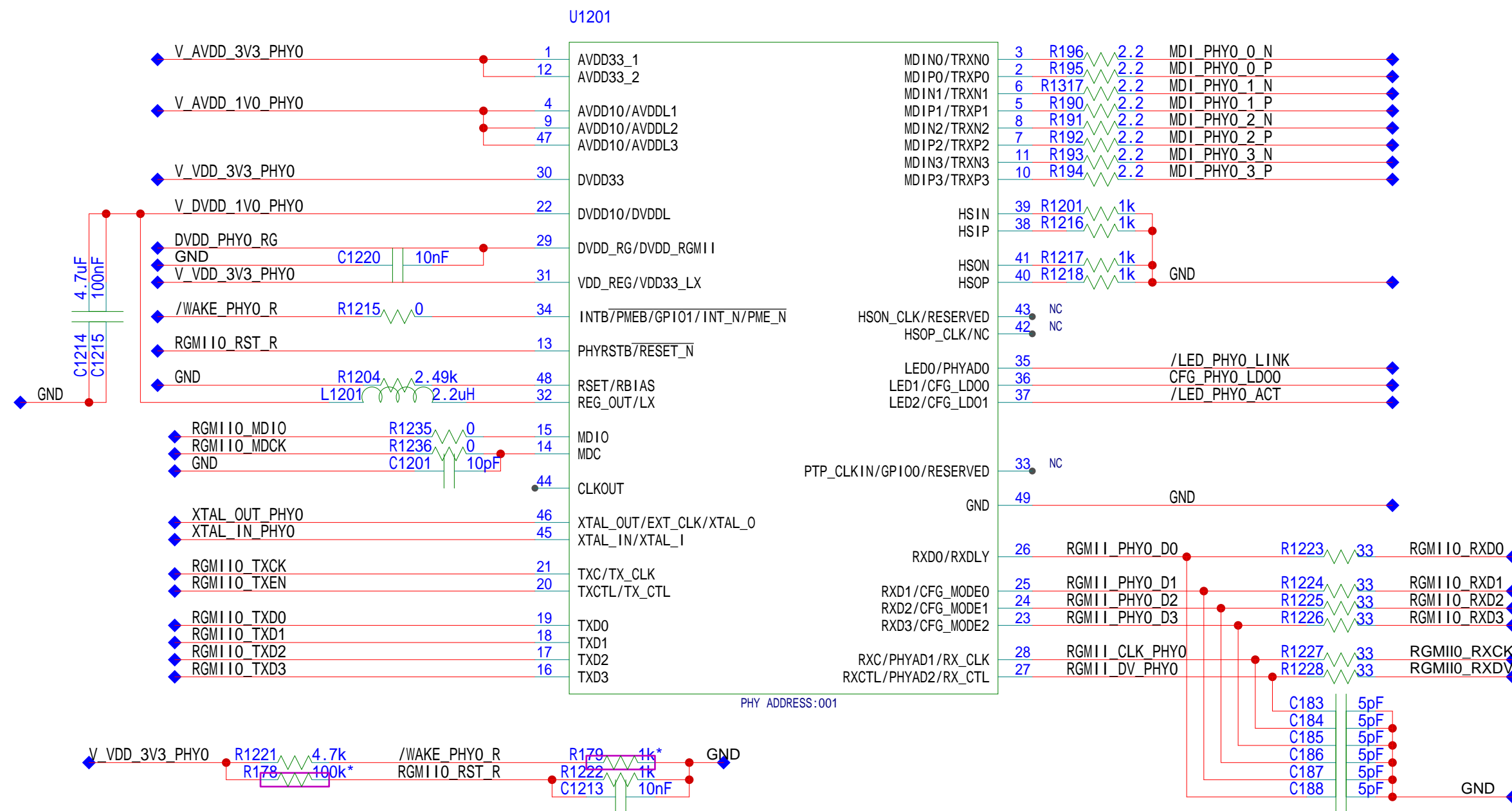
- 1、 Vin : Cin最小值为20uF+10nF瓷片电容；
- 2、 EN下拉电阻外置；在5V输出及以上场景时，CBB中EN下拉电阻R2001=17.4k（注：如要使用在5V输出以下场景，则需取R2001=20k）；该管脚不要外加电容
- 3、 VCC:默认悬空，使用PG时必须上拉到该管脚（3V）
- 4、 FB:输出调节，通过FB和RGND之间的电阻来调节输出电压，TRIM调节电阻R1和R2必须选择1%精度电阻。
- 5、 PG:不使用PG时悬空，使用时上拉大于等于3K电阻至VCC（3V），且串联一个1K电阻至I/O口，不推荐外部电源（小于3.6V）上拉，外部上拉在EN使能前会有一个0.6V电平；
- 6、 MODE:默认悬空，频率设定管脚
- 7、 CS:默认悬空，OCP点设定管脚，过流点电阻Rcs（59K）已内置
- 8、 Vout : Cout最小值为44uF瓷片电容；
- 9、 输出电压与输出电容配置见下表：输出电容选型，请与单板电源工程师讨论

输出电压	0.7V	1.2V	1.8V	3.3V	5.4V
输出电源	9*22UF	7*22UF	5*22UF	4*22UF	3*22UF

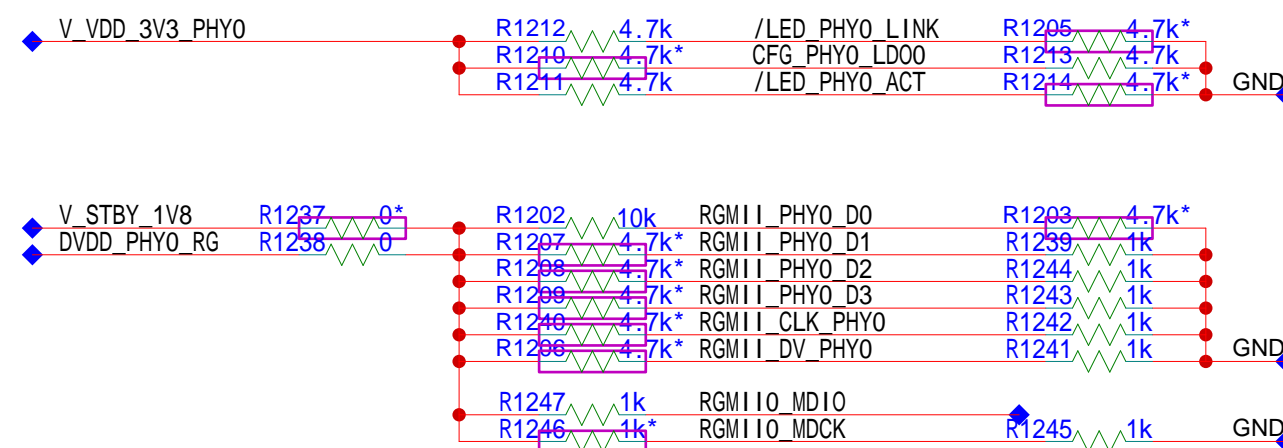
TEC_DRIVER (TEC为硬盘加热、降温模块)



GE PHY



PIN	CFG		PIN	CFG
LED0	PHY_ADD0		RXD1	CFG_MODE0
RXC	PHY_ADD1		RXD2	CFG_MODE1
RXCTL	PHY_ADD2		RXD3	CFG_MODE2
RXD0	RXDLY			
LED1	CFG_LD0(0)			
LED2	CFG_LD0(1)			



10	CFG_LDO[1:0]	LED2 LED1 STBY_12V0 01: 2.5V 10: 1.8V 11: 1.5V
000	CFG_MODE[2:0]	RXD3 RXD2 RXD1 000: UTP<->-RGMII 001: FIBER<->-RGMII 010: UTP/FIBER<->-RGMII 011: UTP<->-SGMII 100: SGMII (PHY)<->-RGMII (MAC) 101: SGMII (MAC)<->-RGMII (PHY) 110: UTP<->-FIBER(AUTO, MODE) 111: UTP<->-FIBER(FORCE, MODE)
011	PHY_ADD[2:0]	RXCTL RXC LED0
0*	RXDLY	RXDO 1: add 2ns dly to RXC for RXD 0: no delay

GE SWITCH

A

B

C

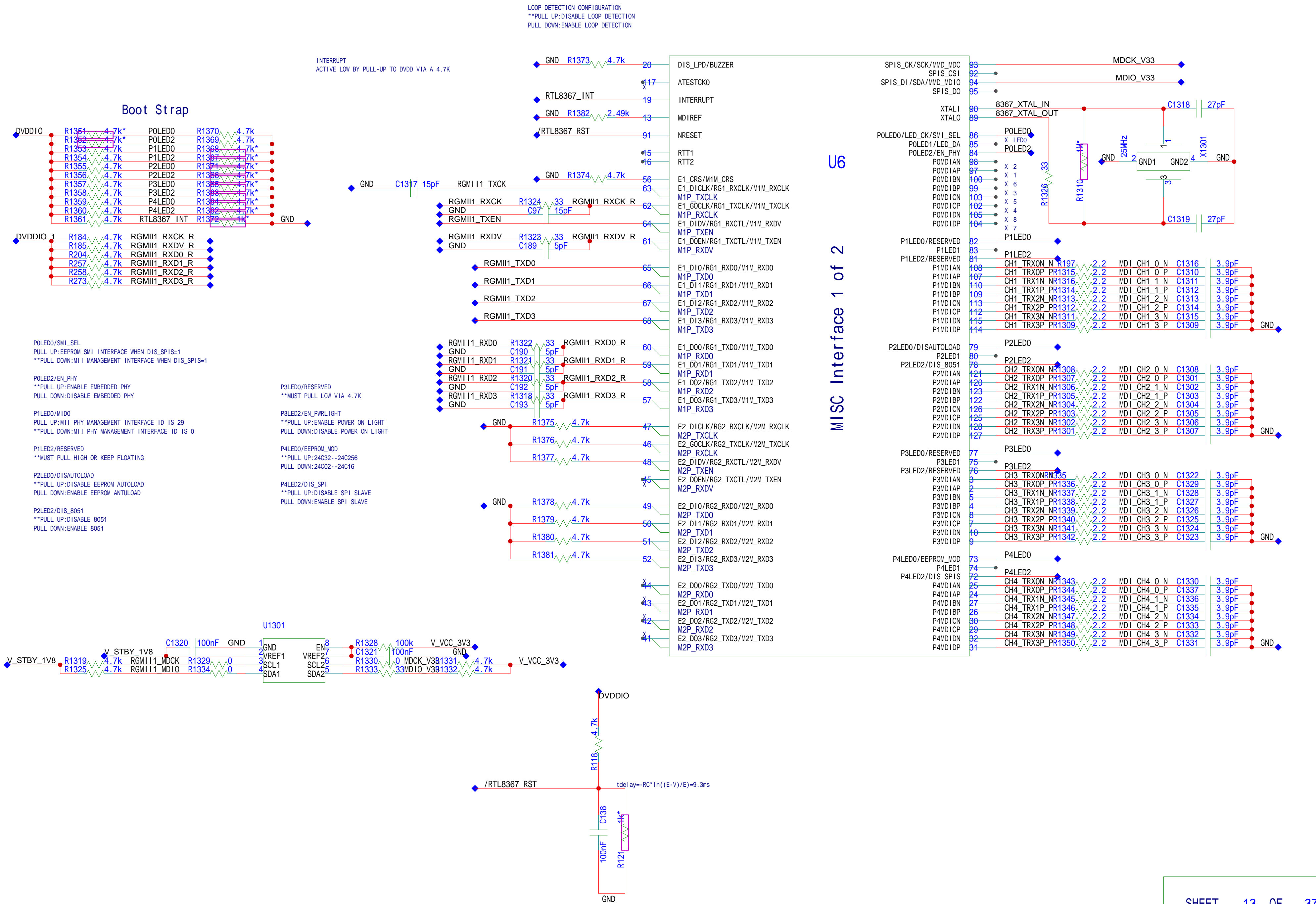
D

A

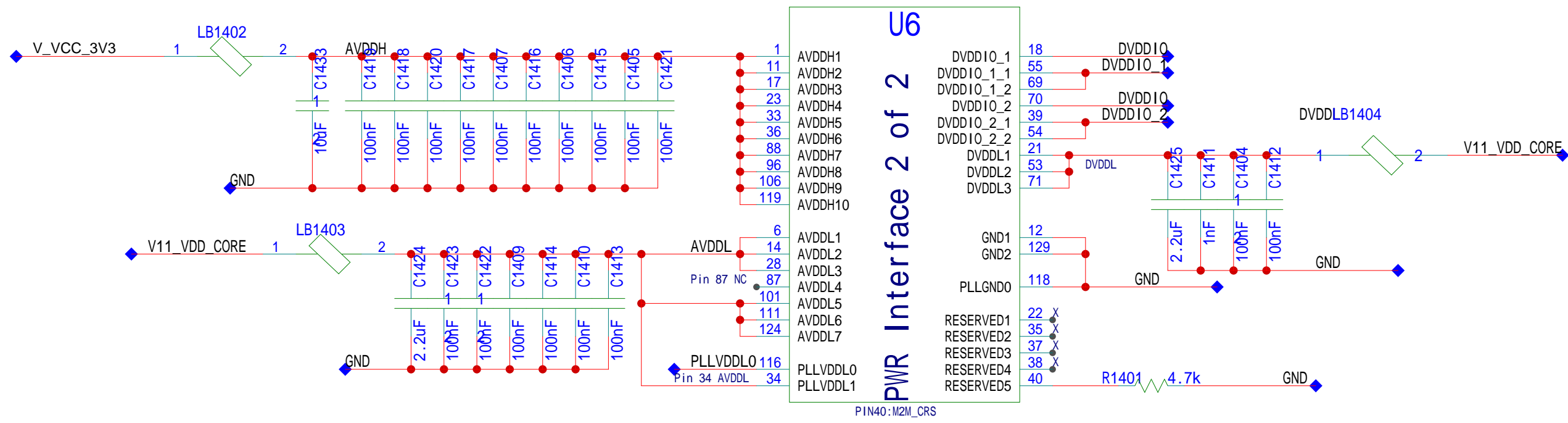
B

C

D

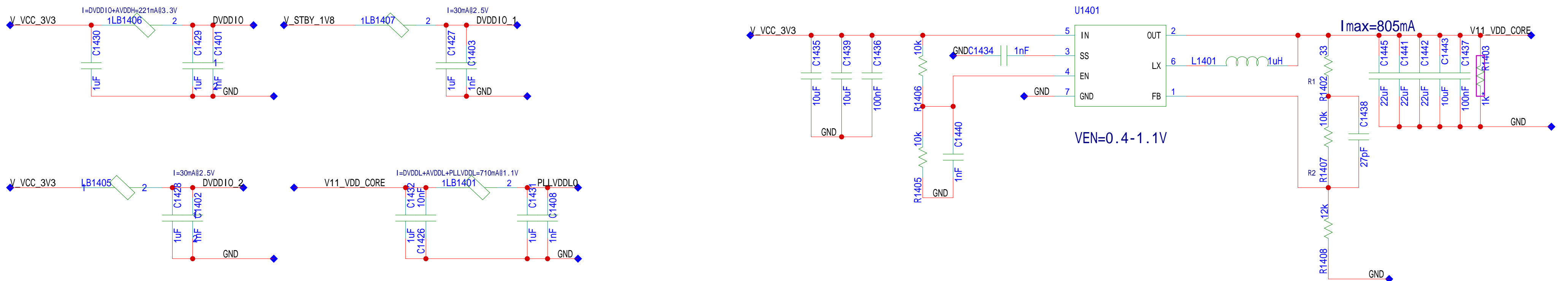


GE SWITCH PWR



DC/DC V33->V11_VDD_CORE

$$V_{out} = V_{REF} * (1 + R_1/R_2) = 0.6 * (1 + 10/12) = 1.1V$$



A

B

C

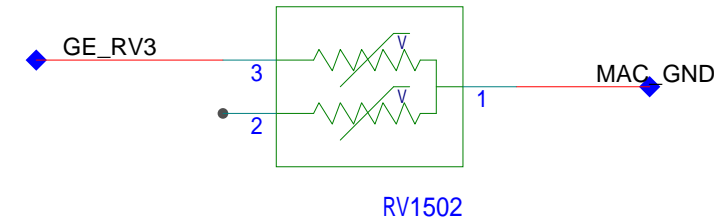
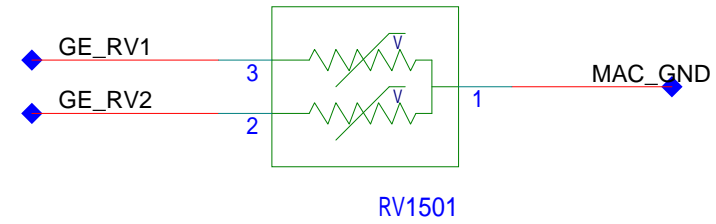
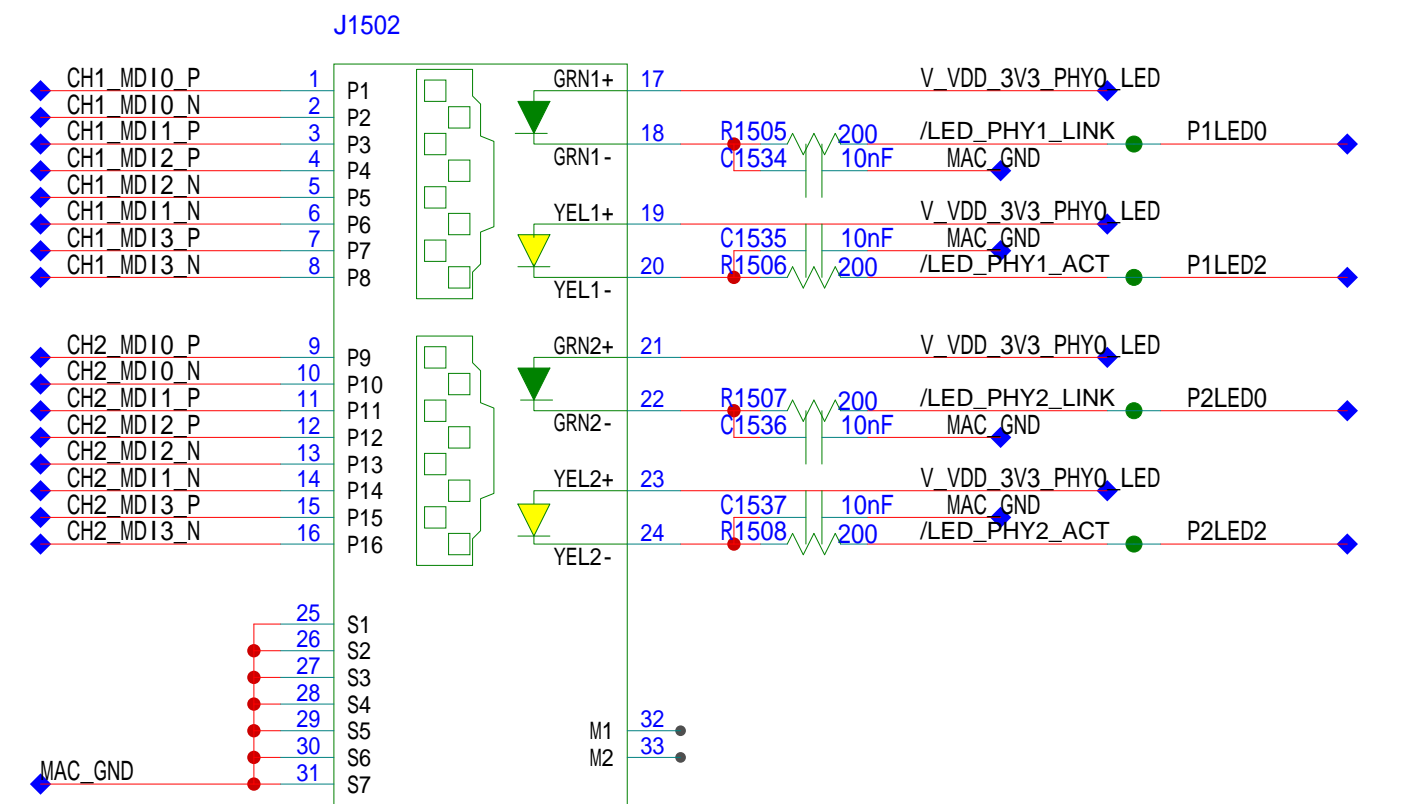
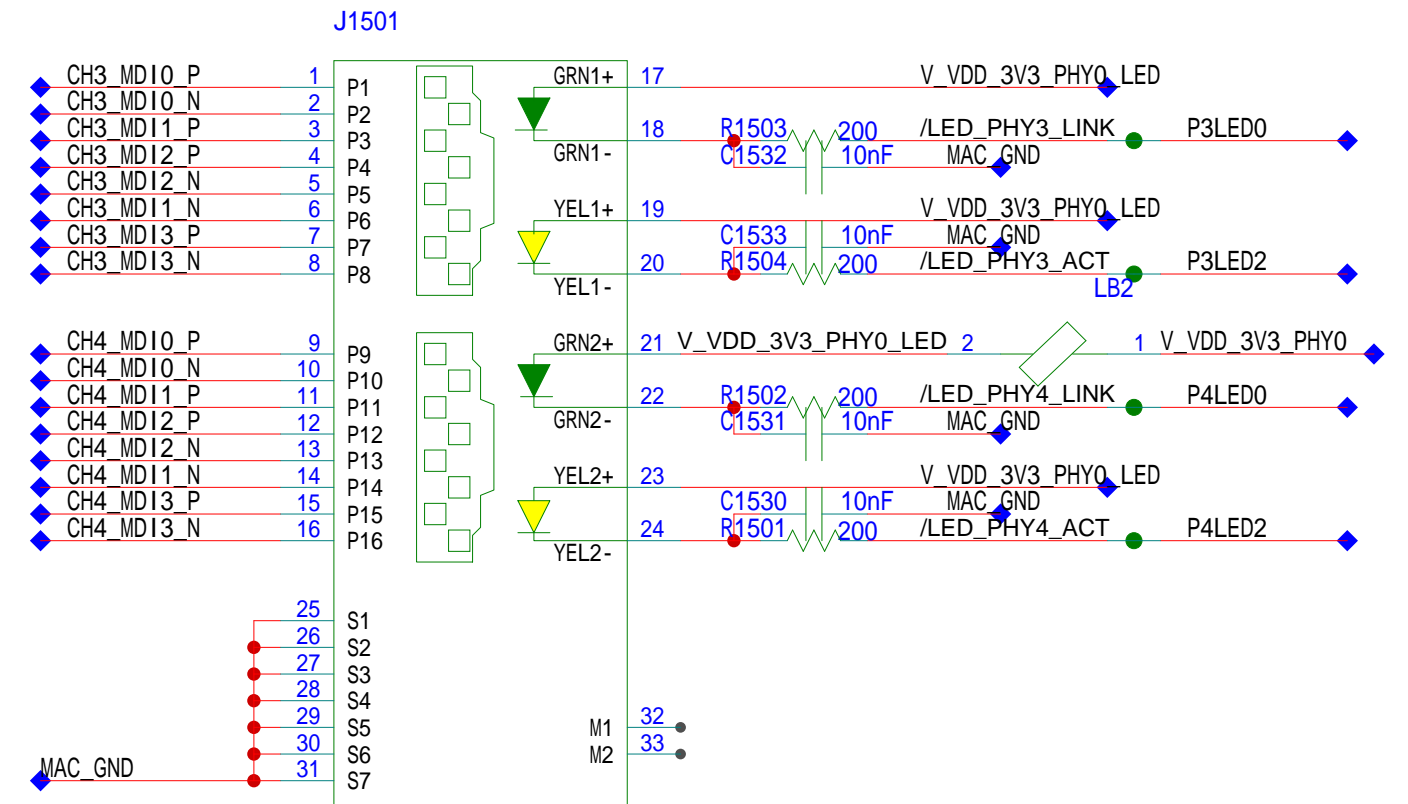
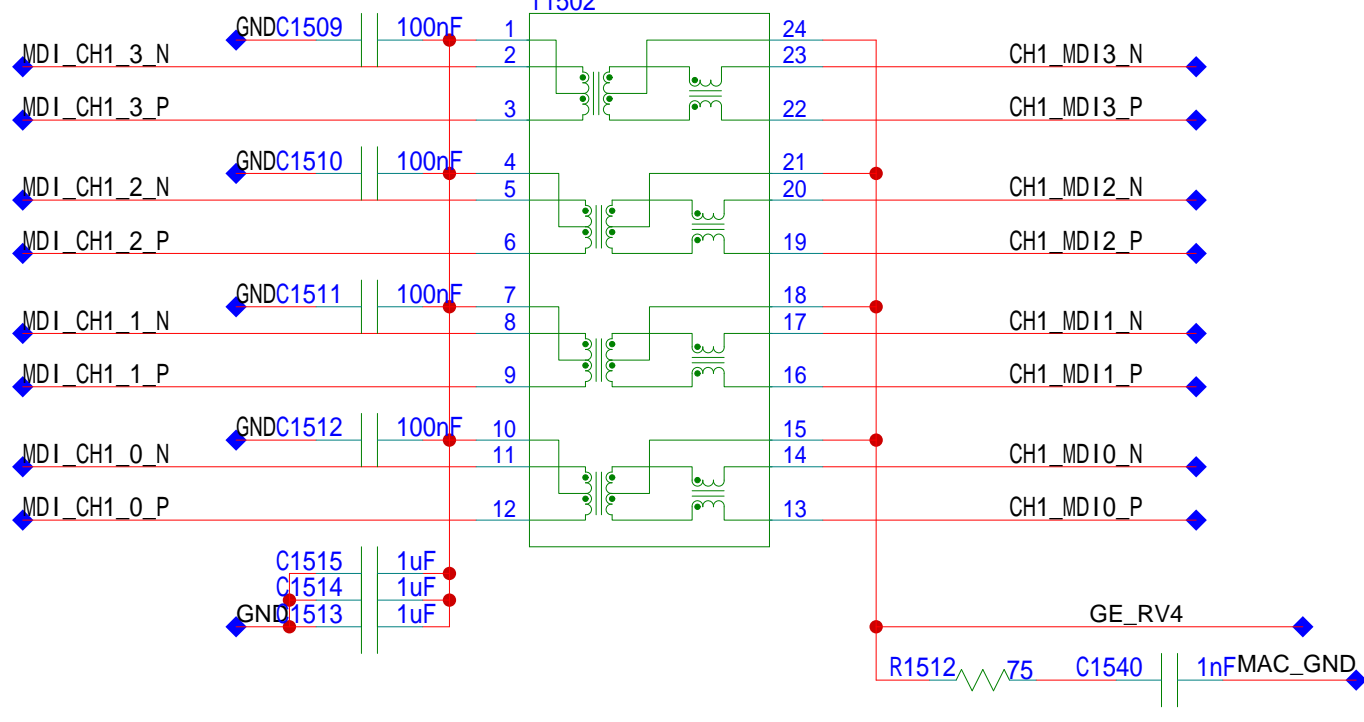
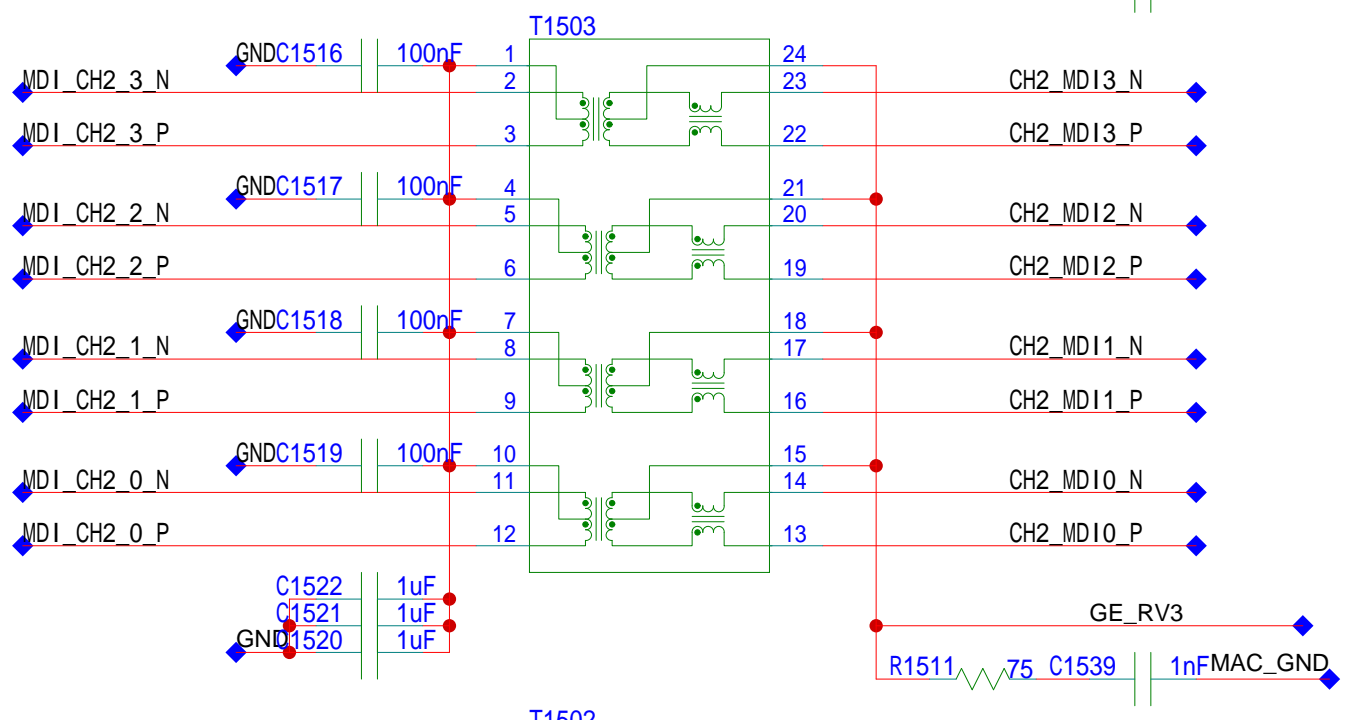
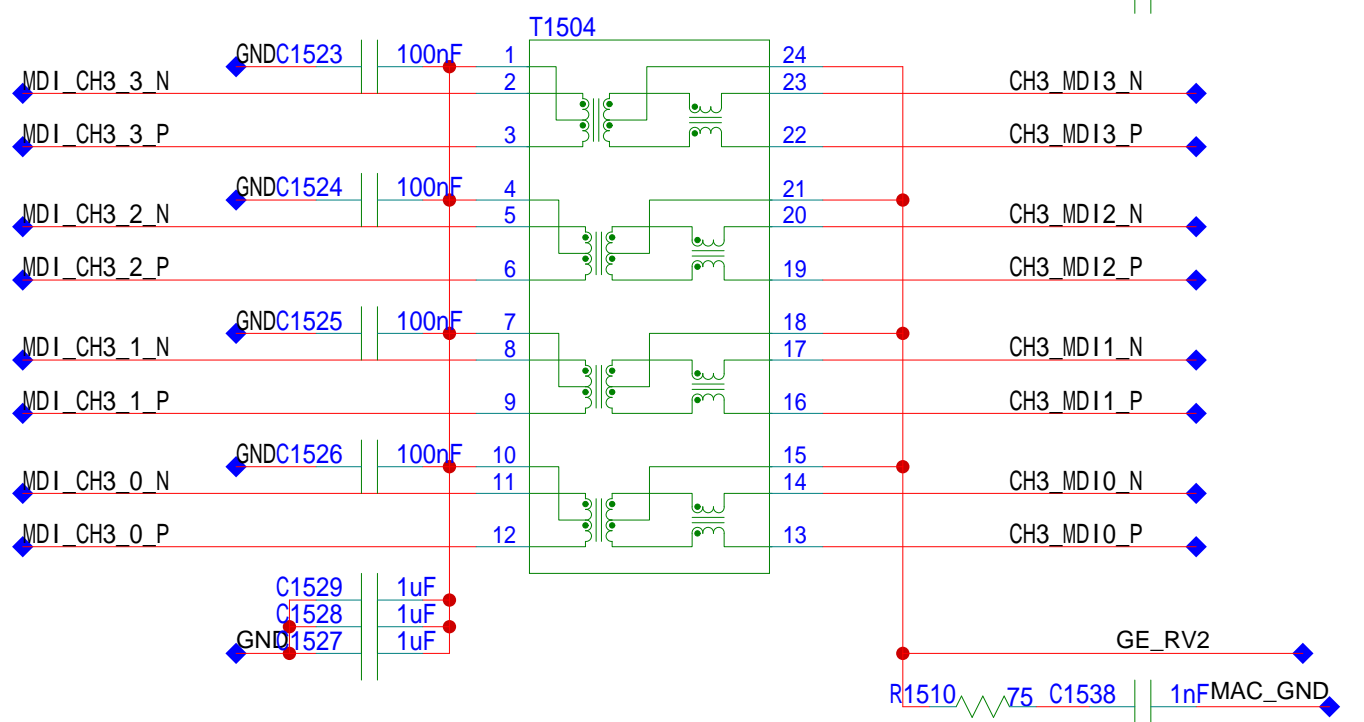
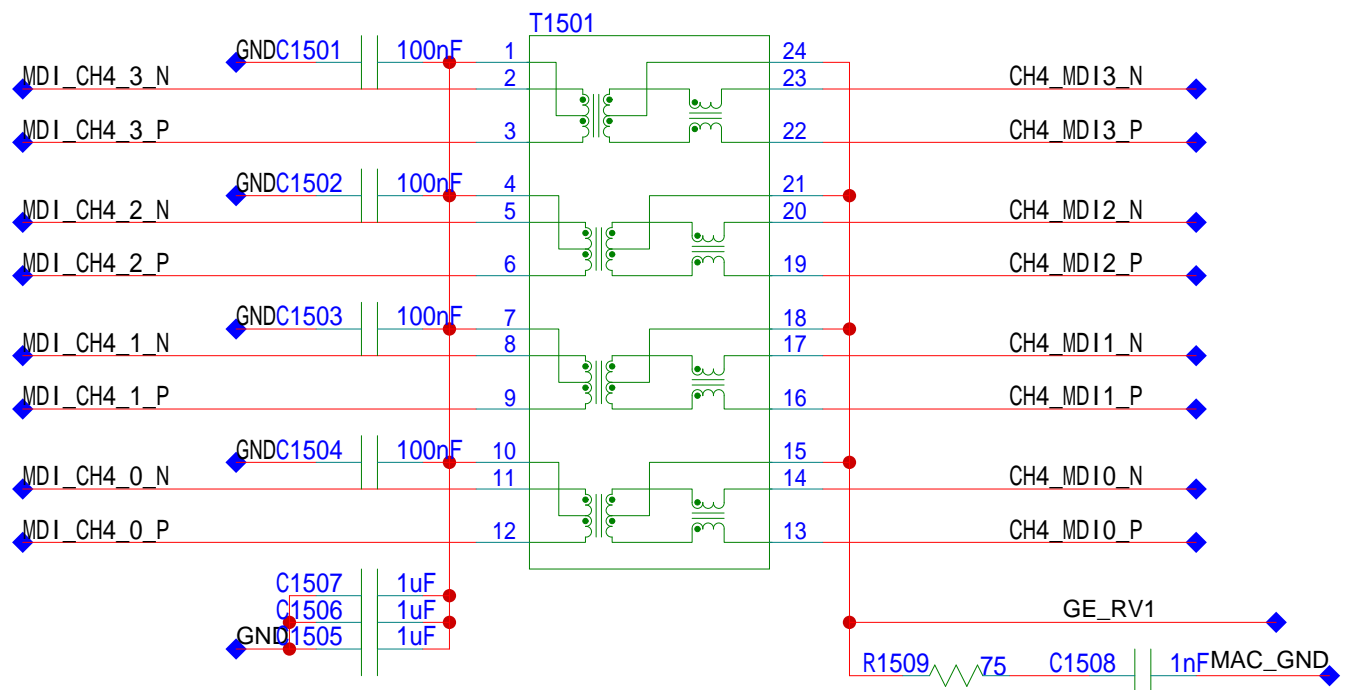
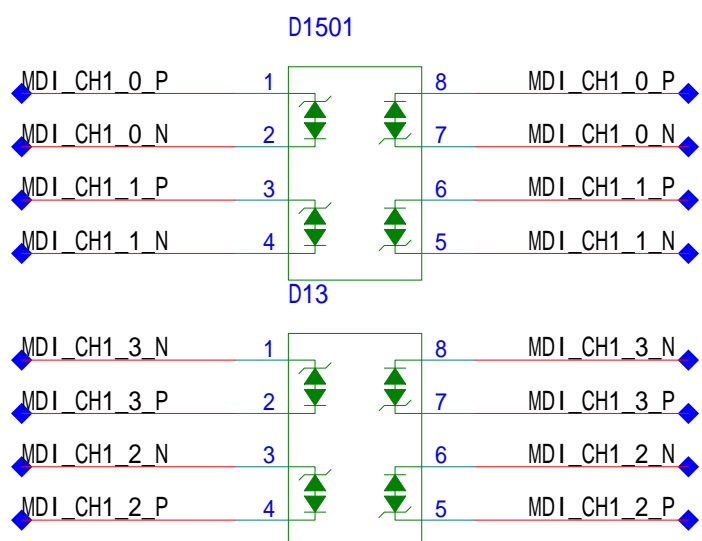
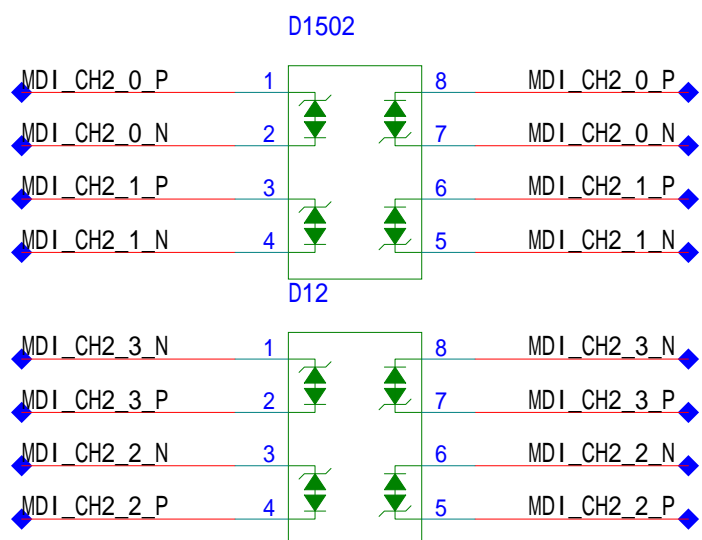
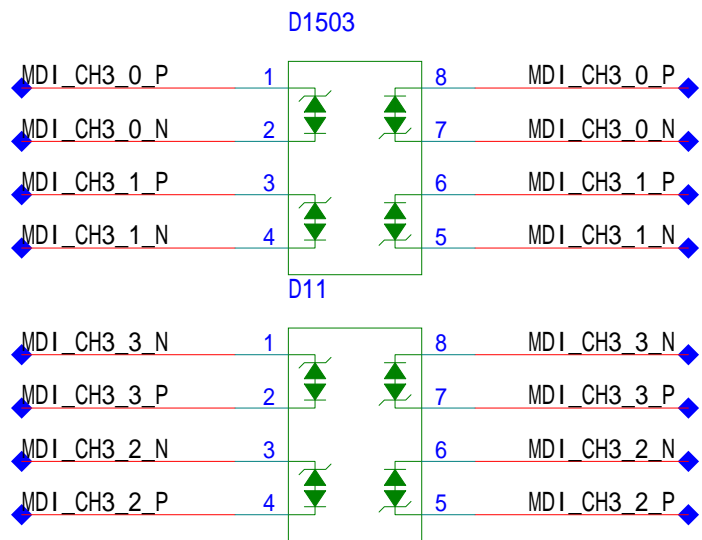
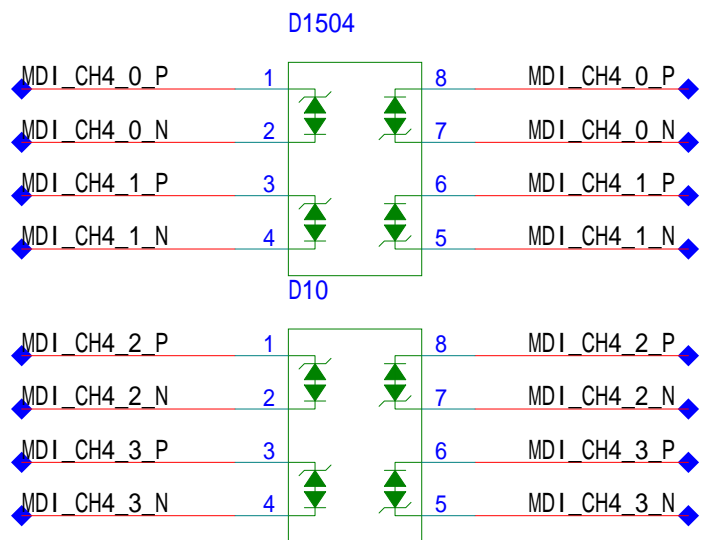
D

A

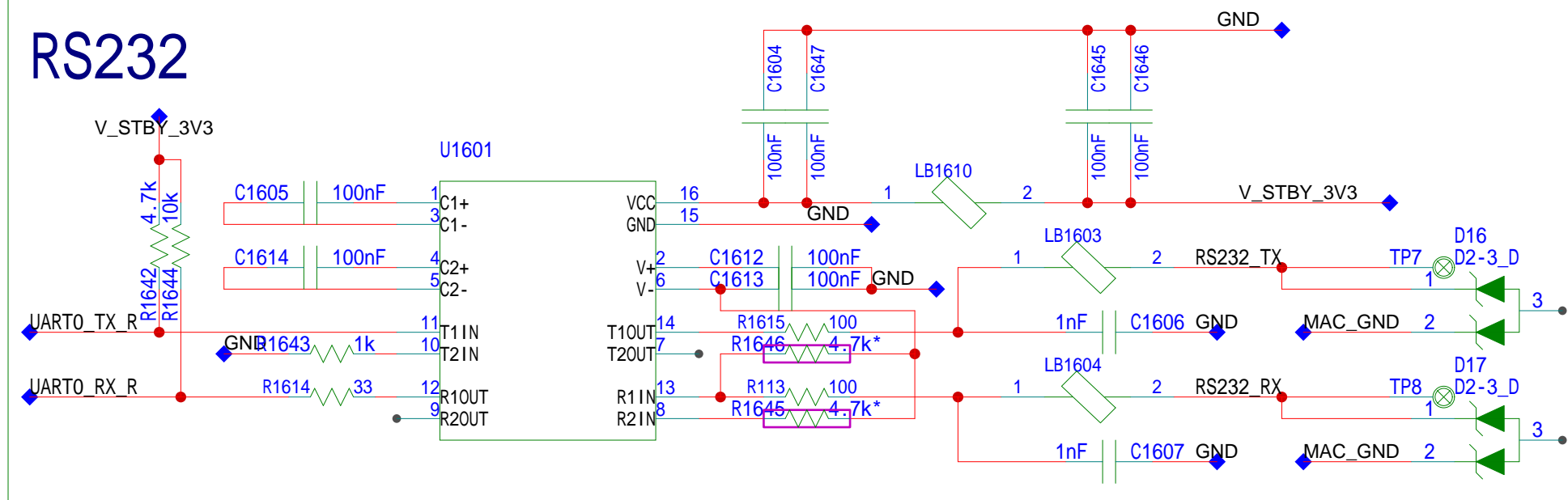
B

C

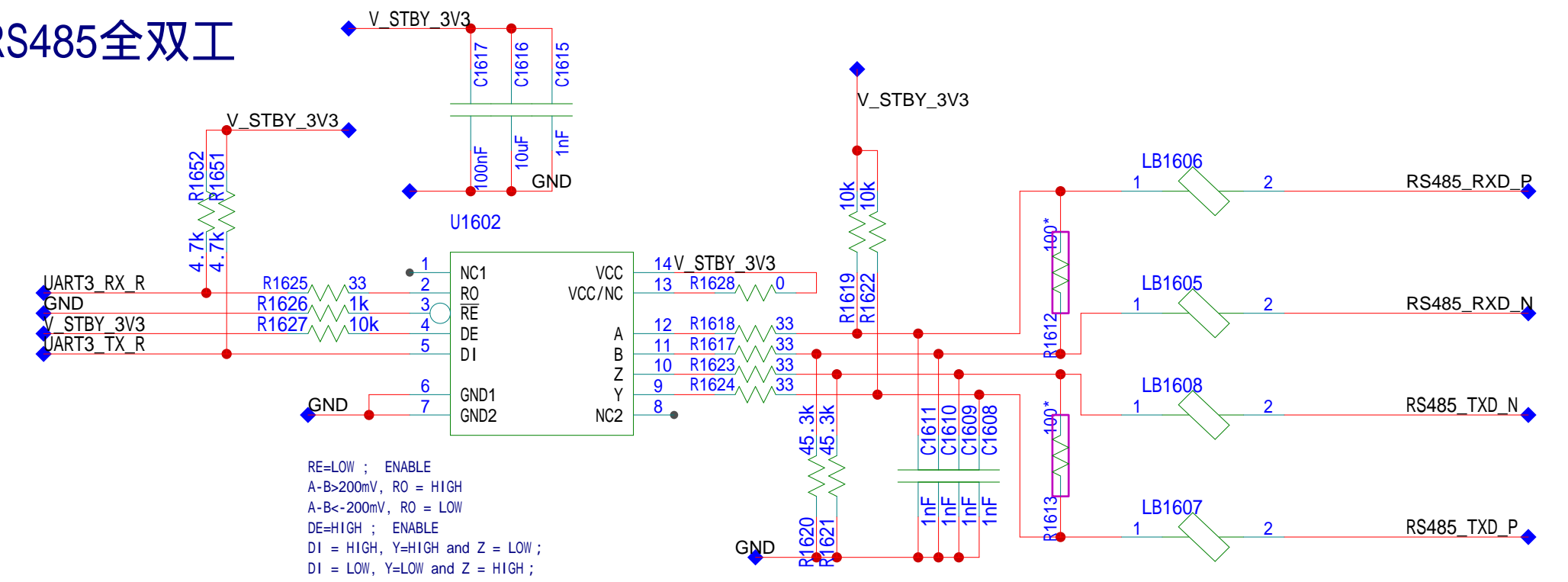
D



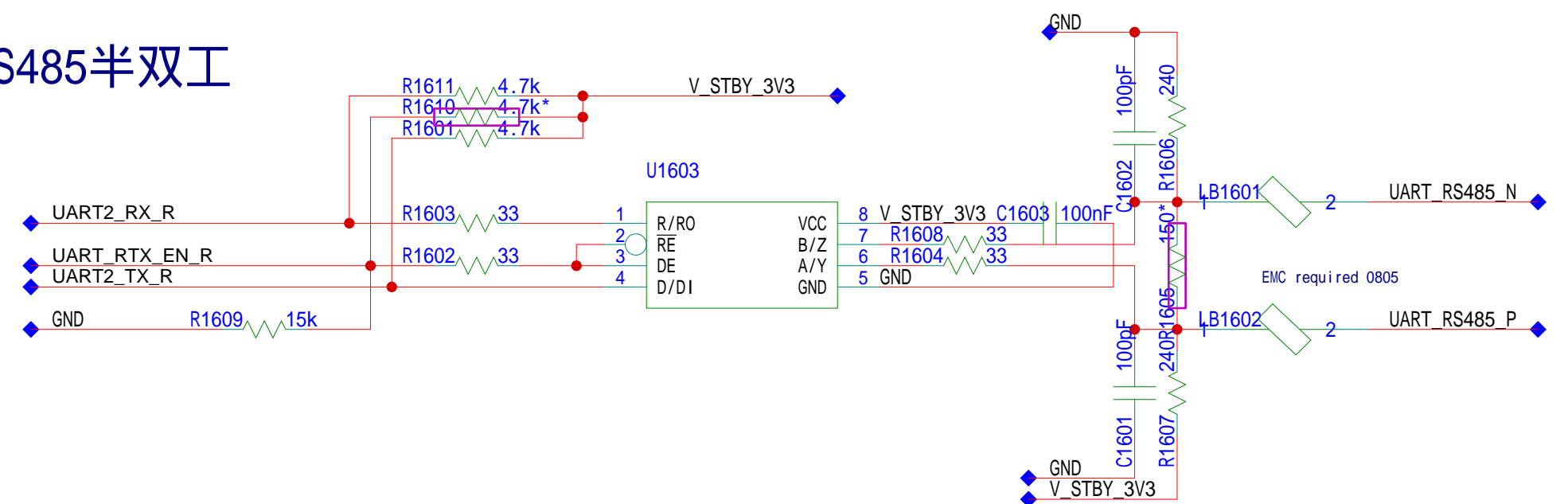
RS232



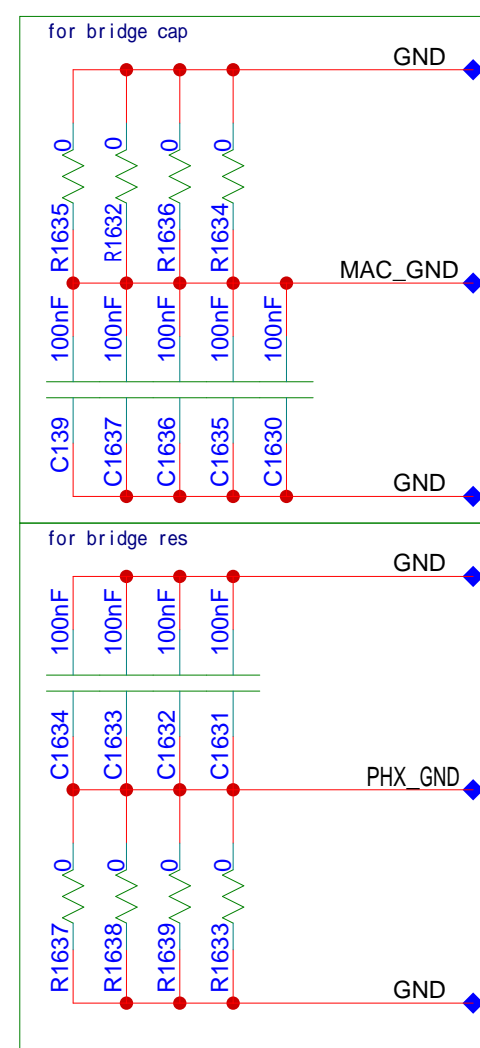
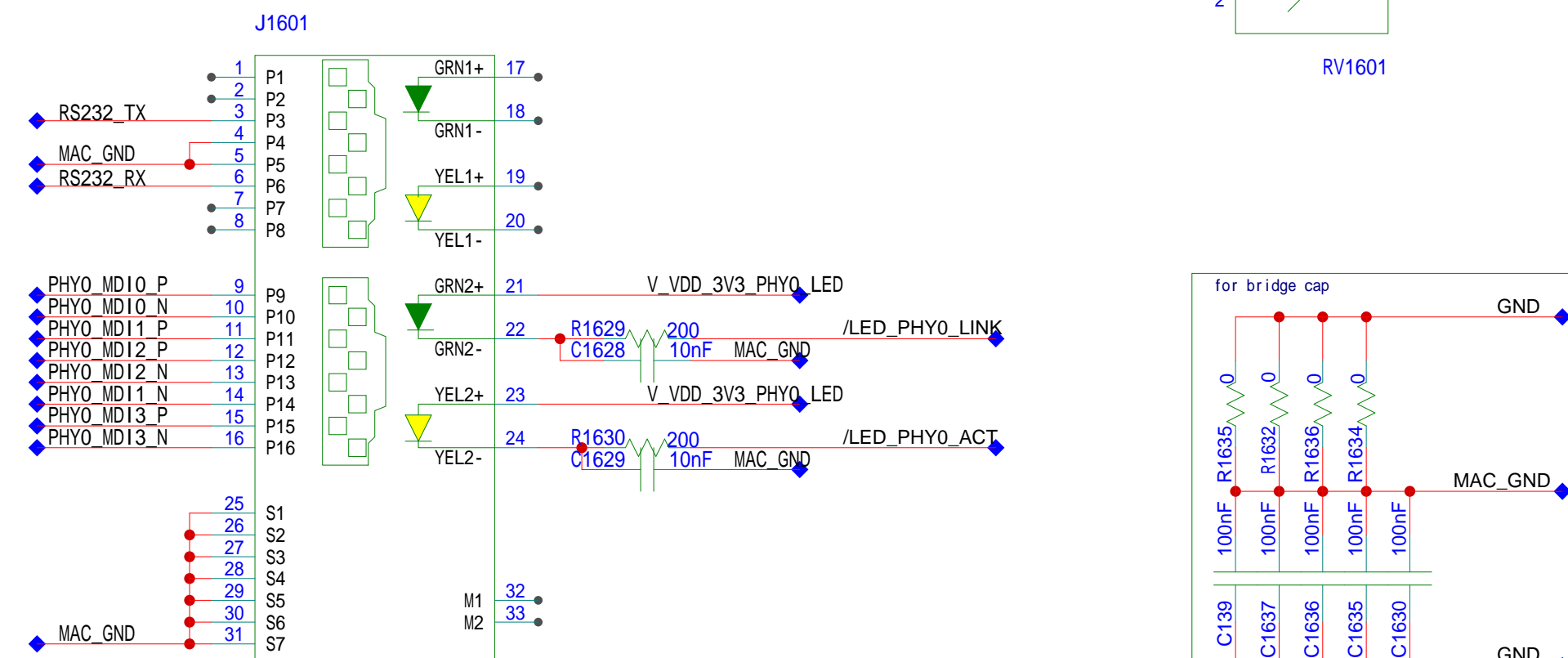
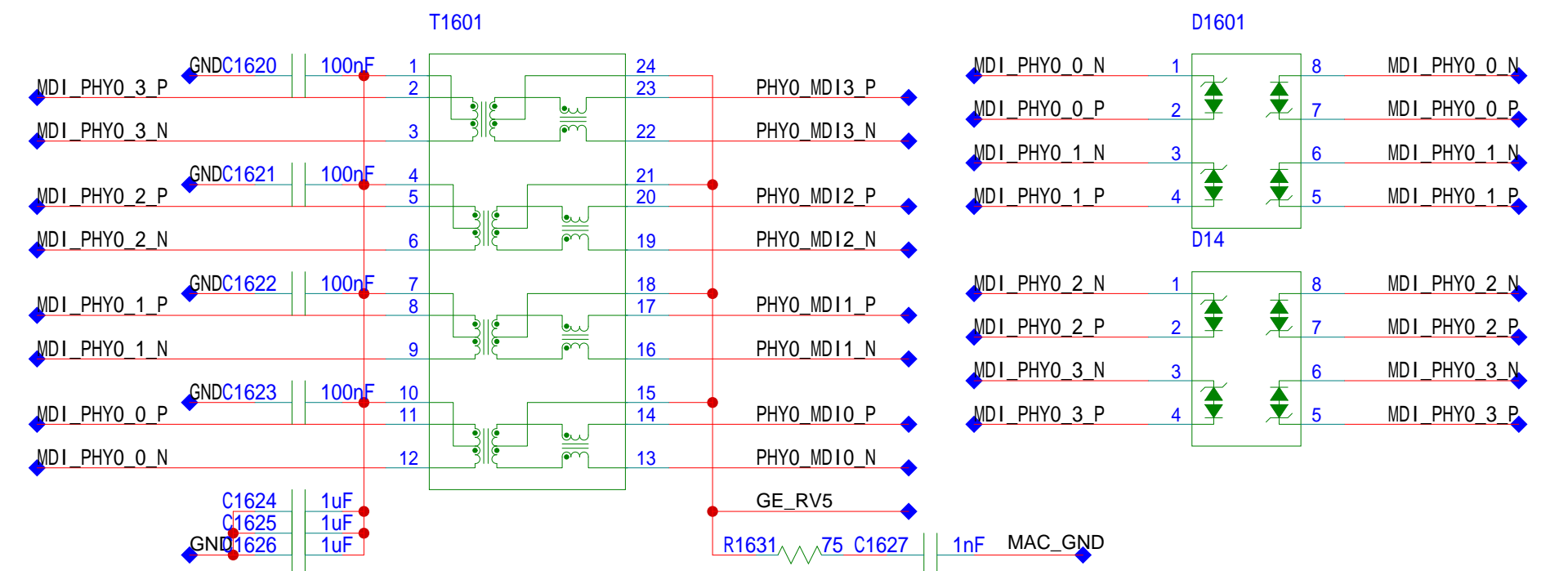
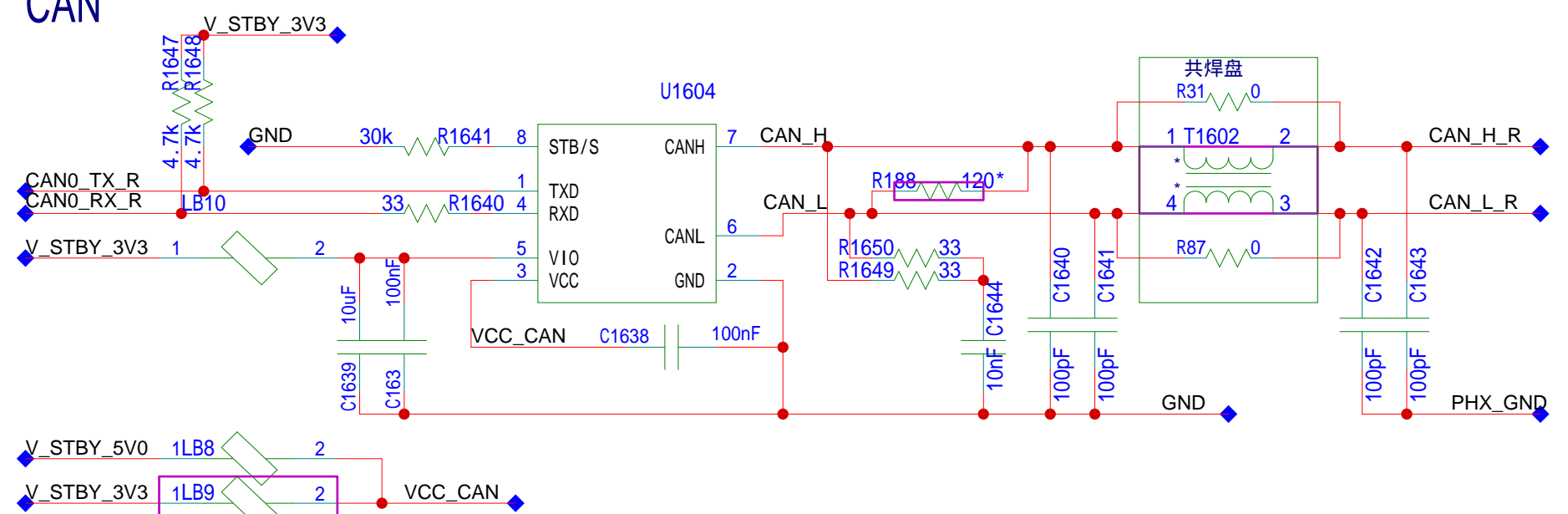
RS485全双工



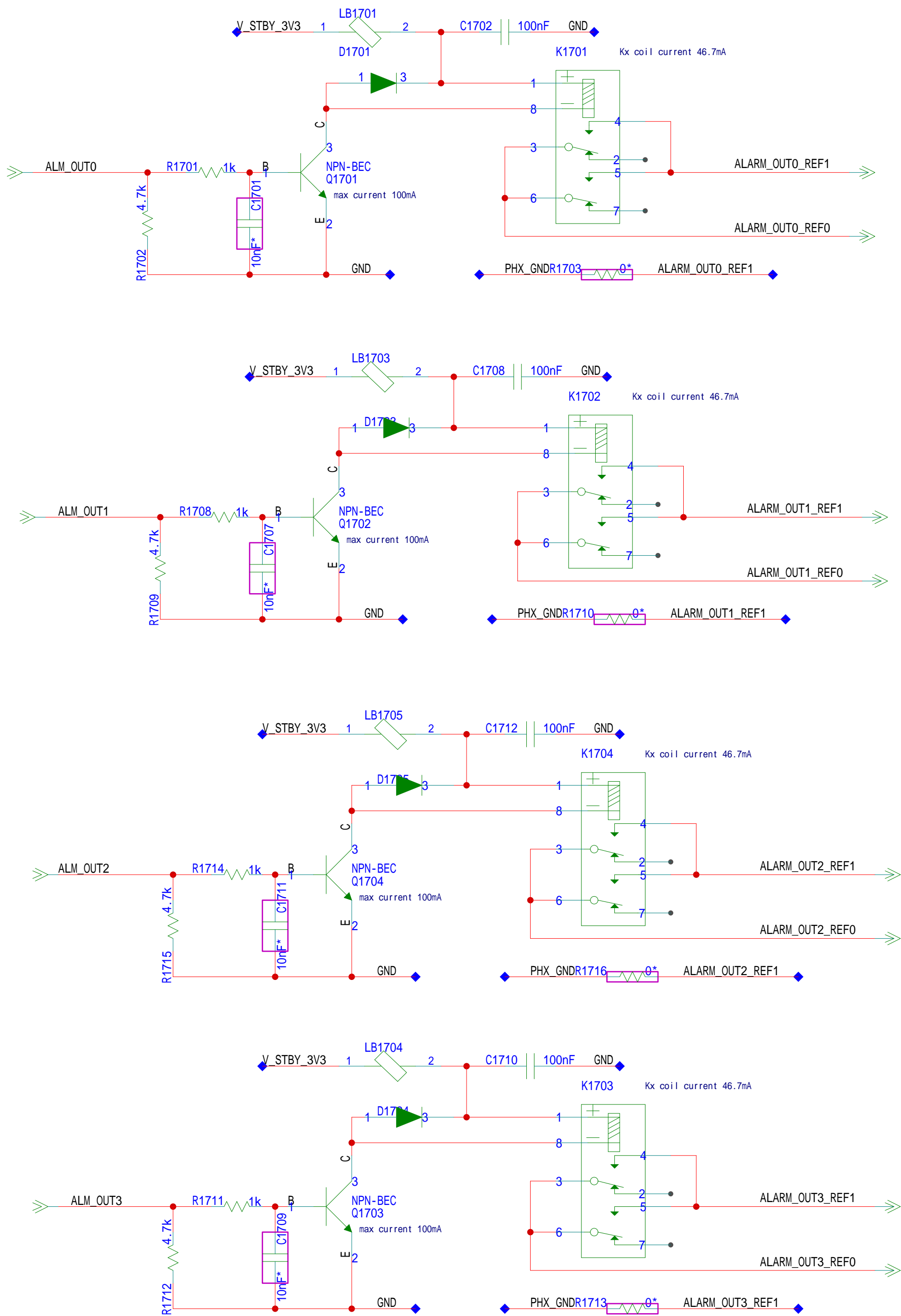
RS485半双工



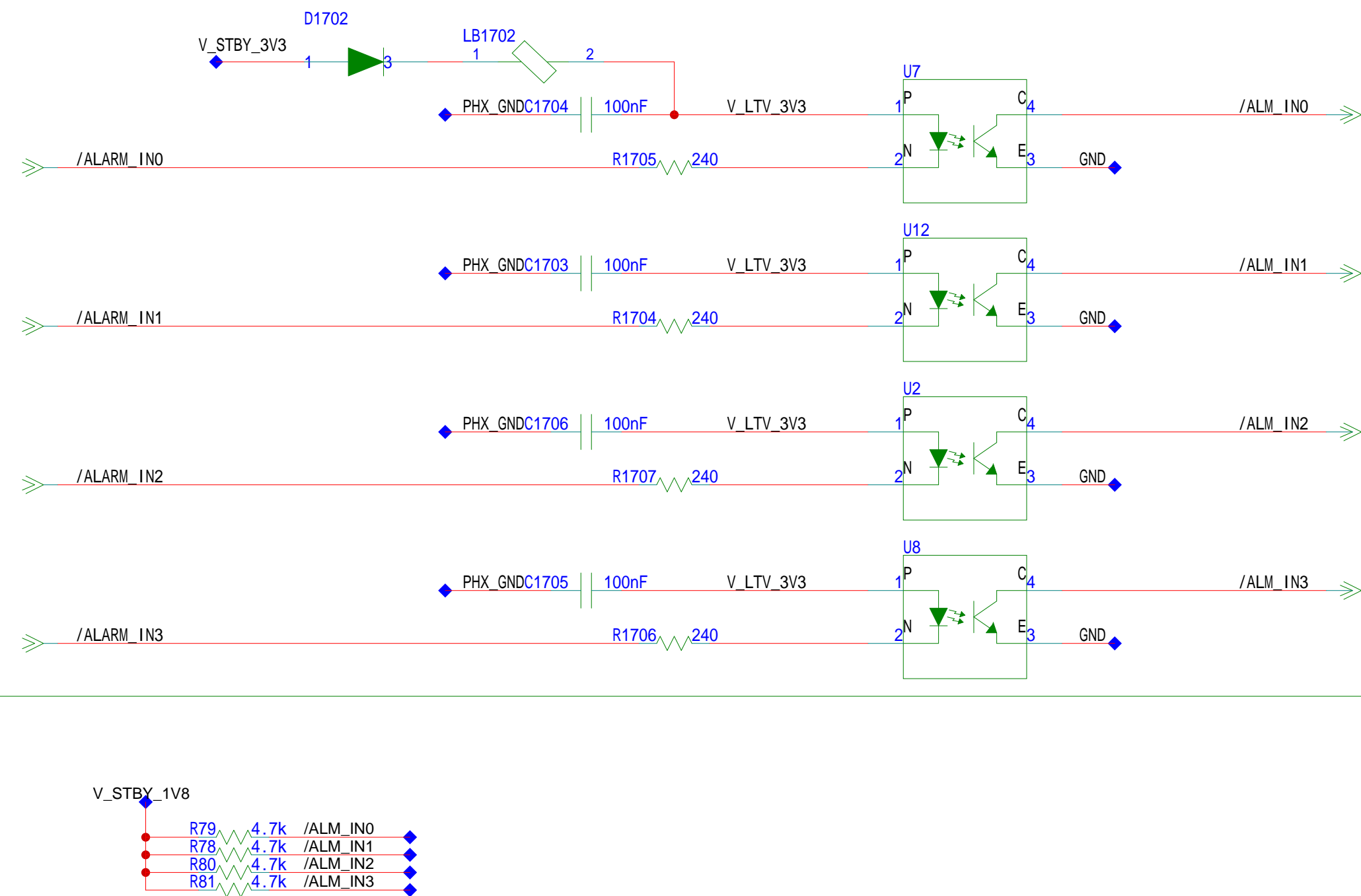
CAN



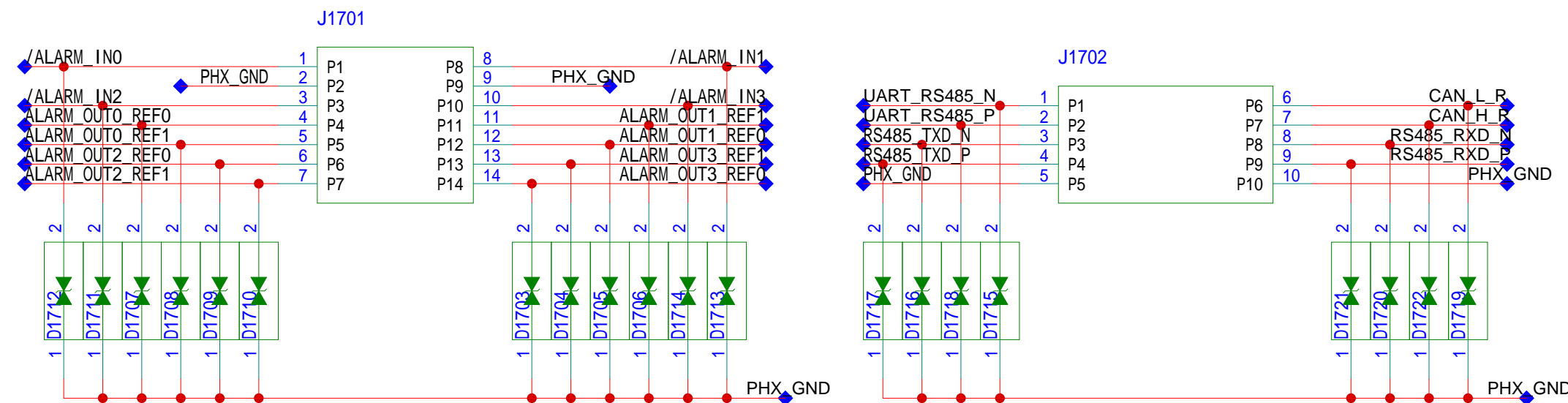
ALARM 4 OUT



ALARM 4 IN

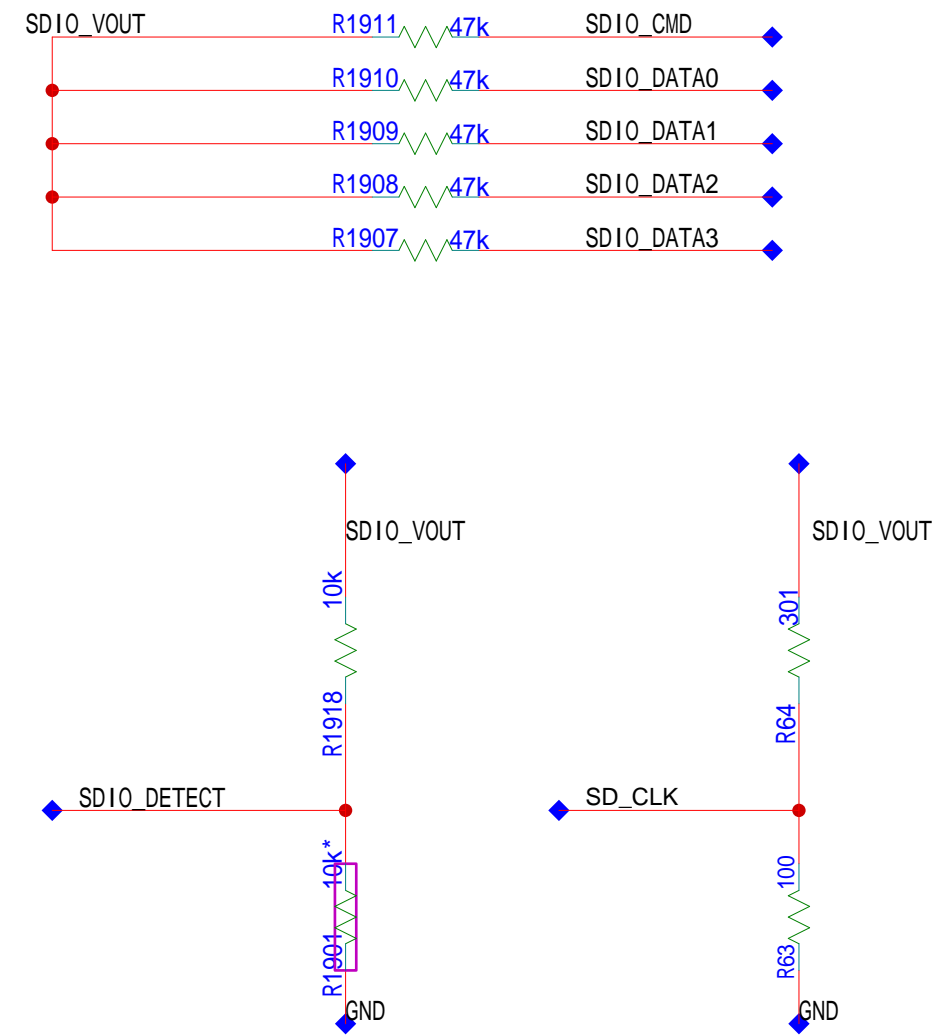
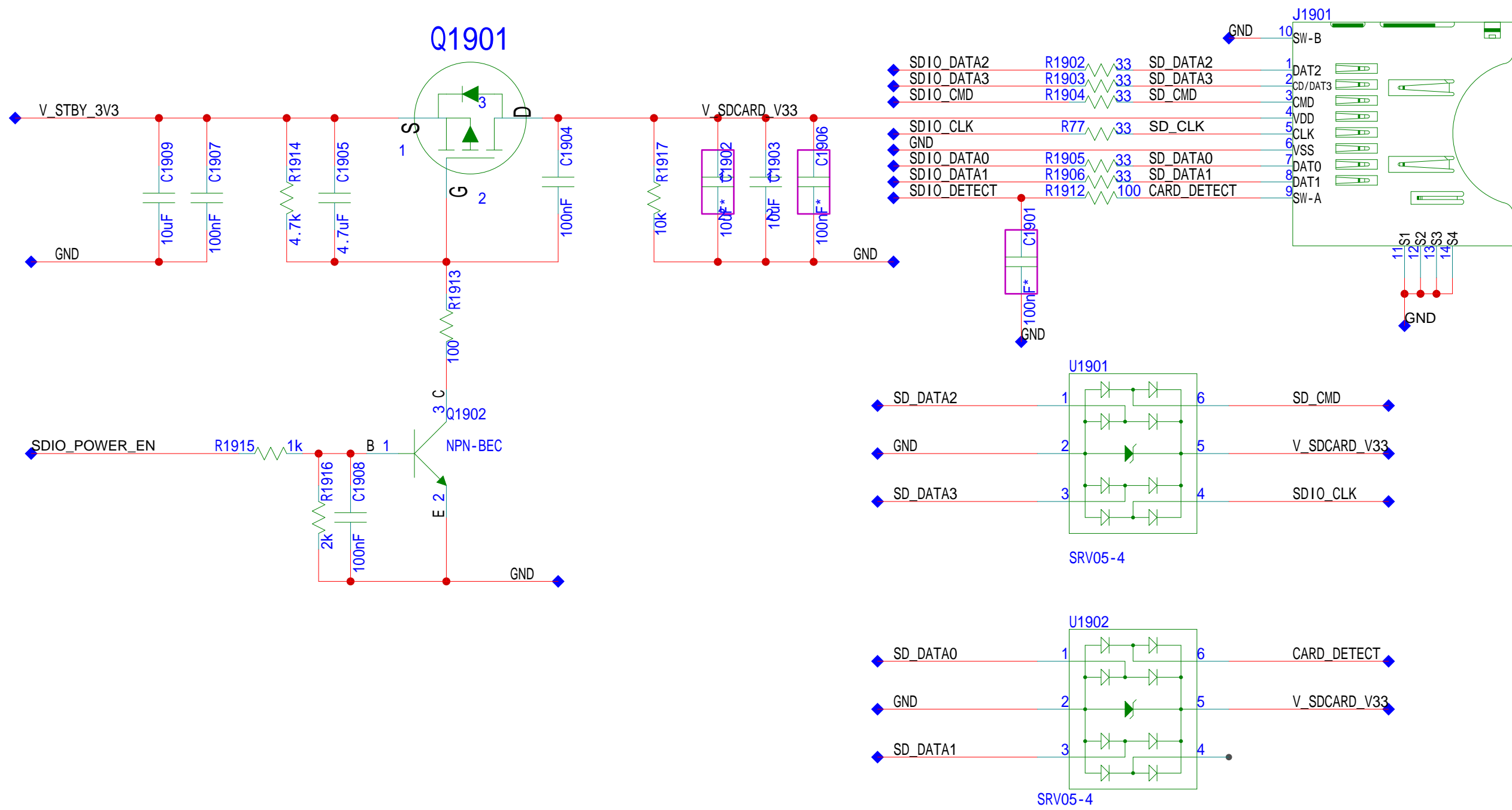


PHOENIX



D





SDIO_DETECT和SD_CLK一定要按这个方案设计

USB3.0 & USB2.0 HUB (兼容设计 , 此方案不上件)

A

B

C

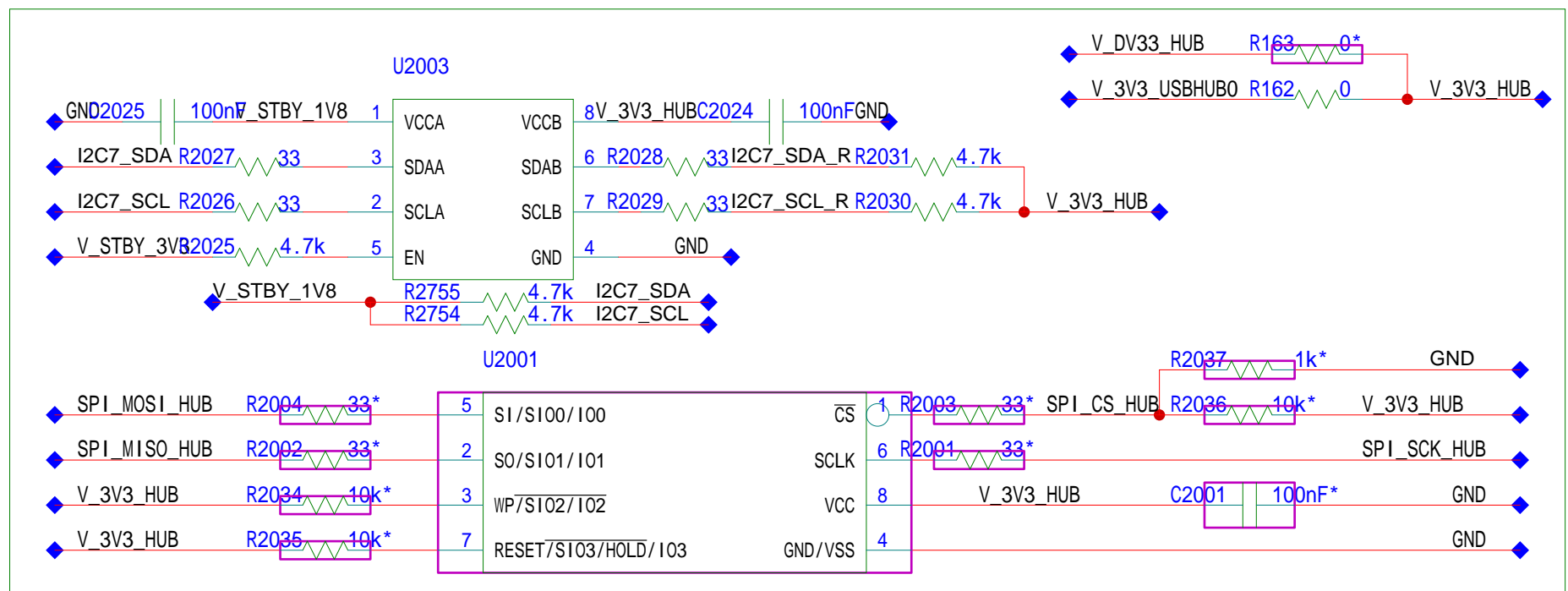
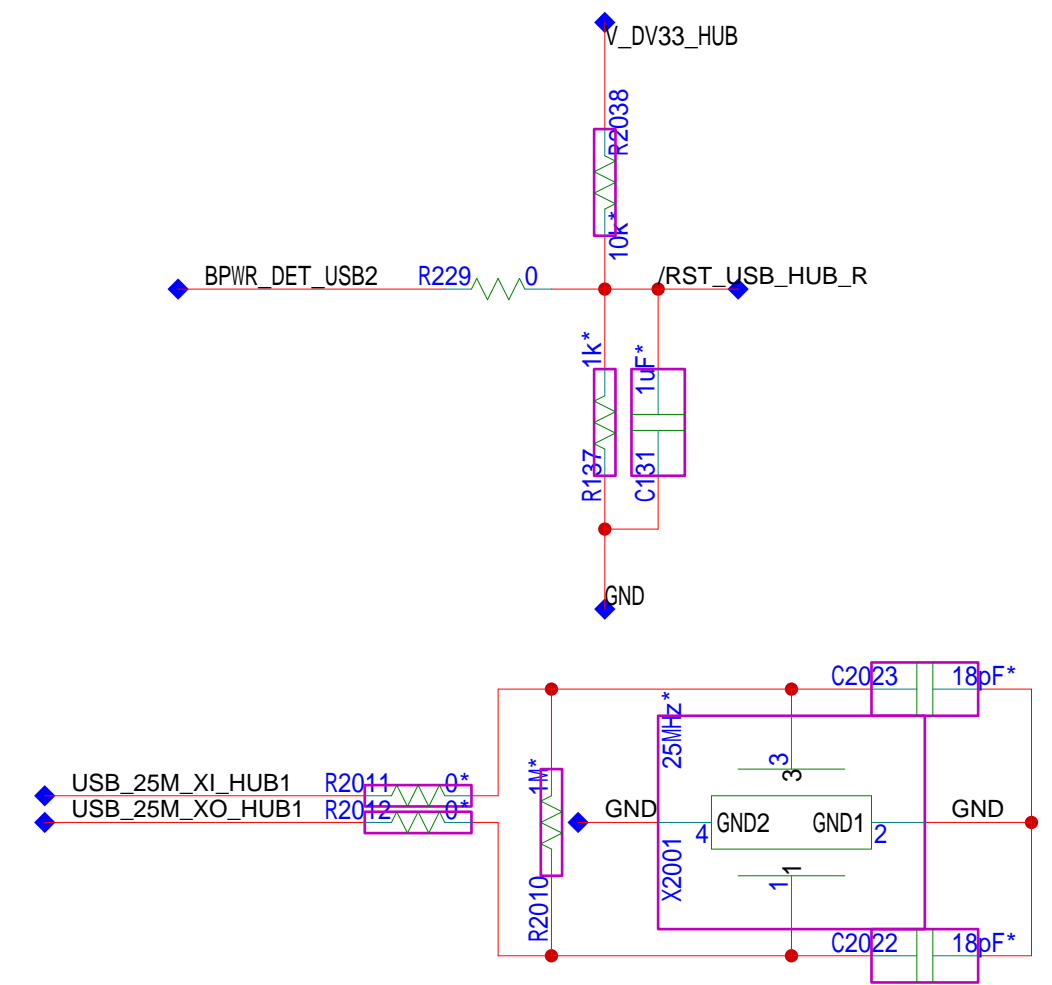
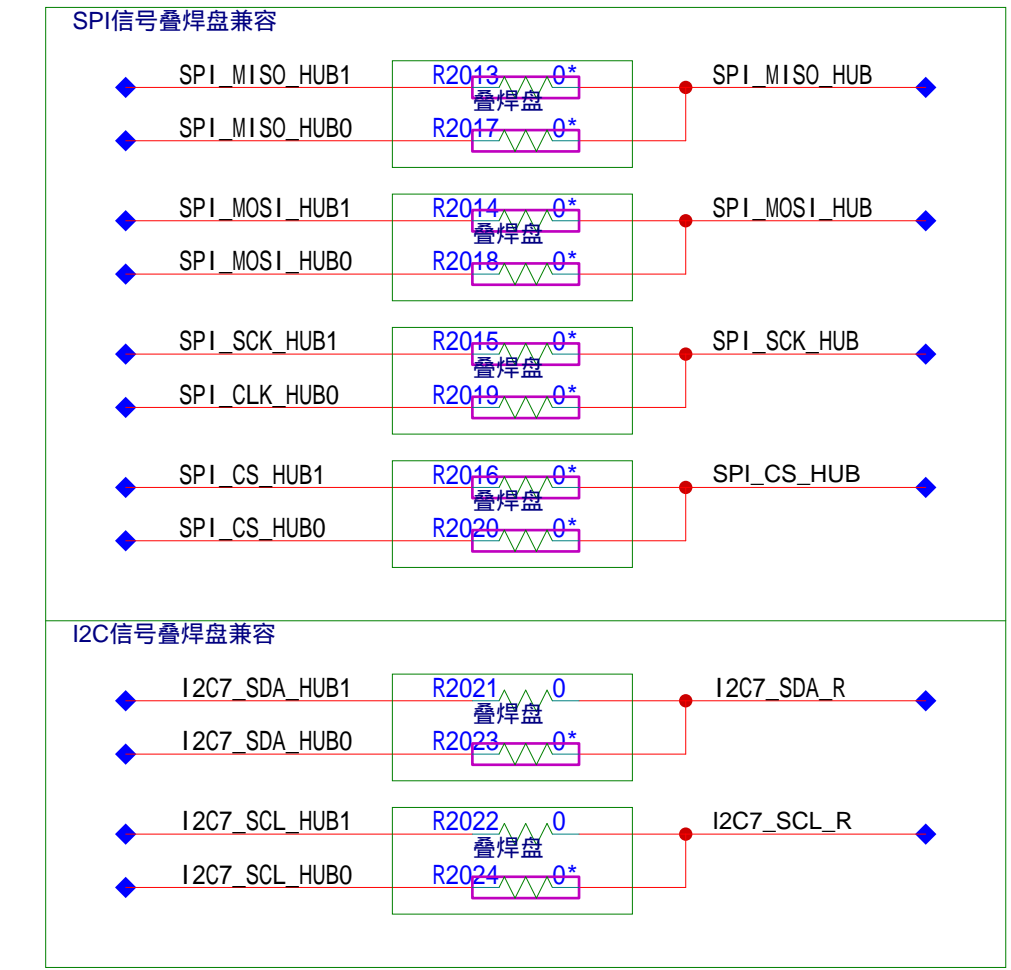
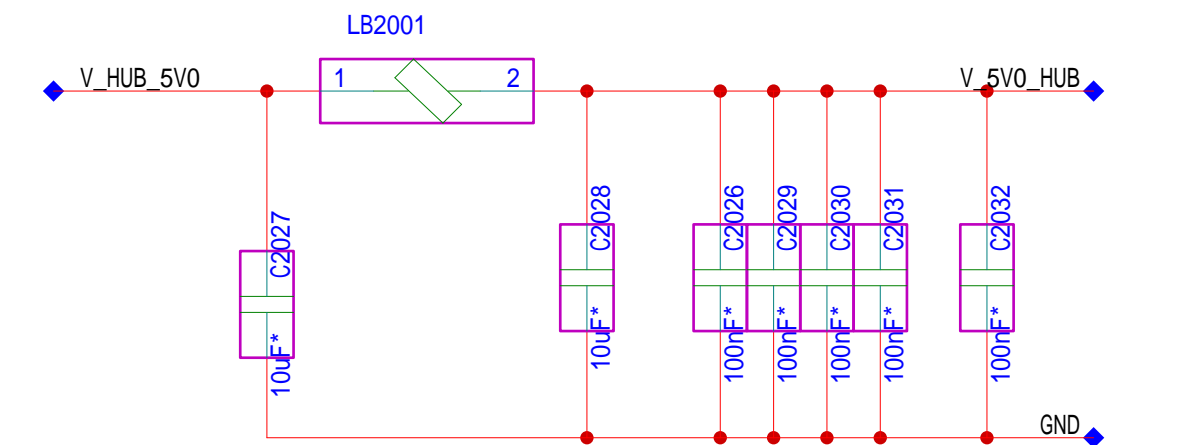
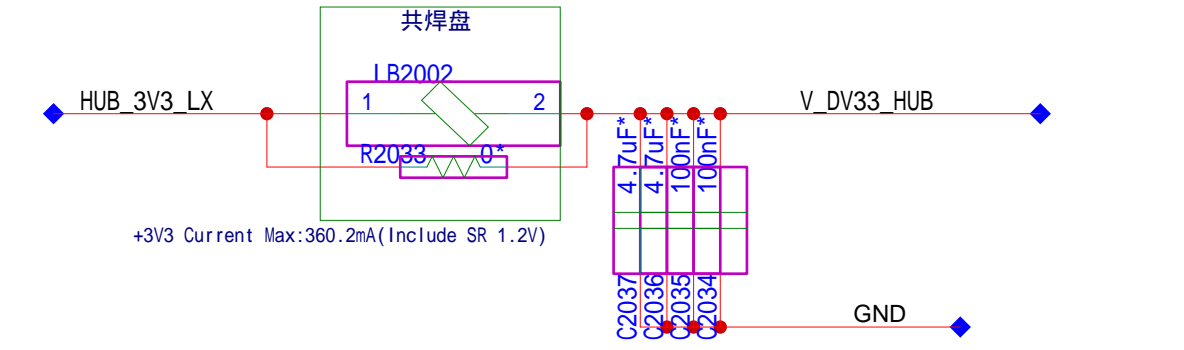
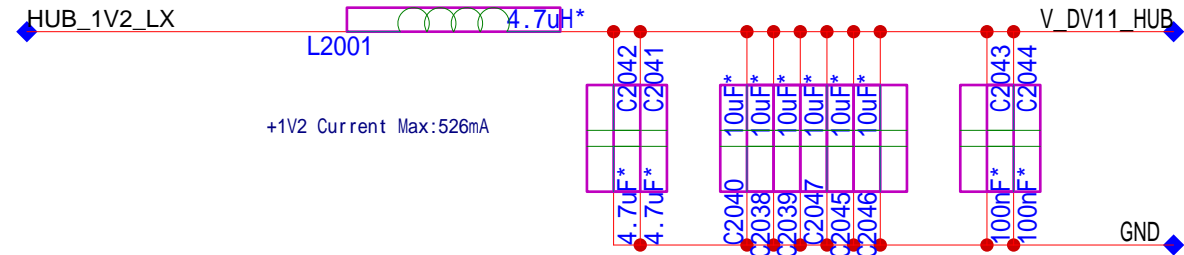
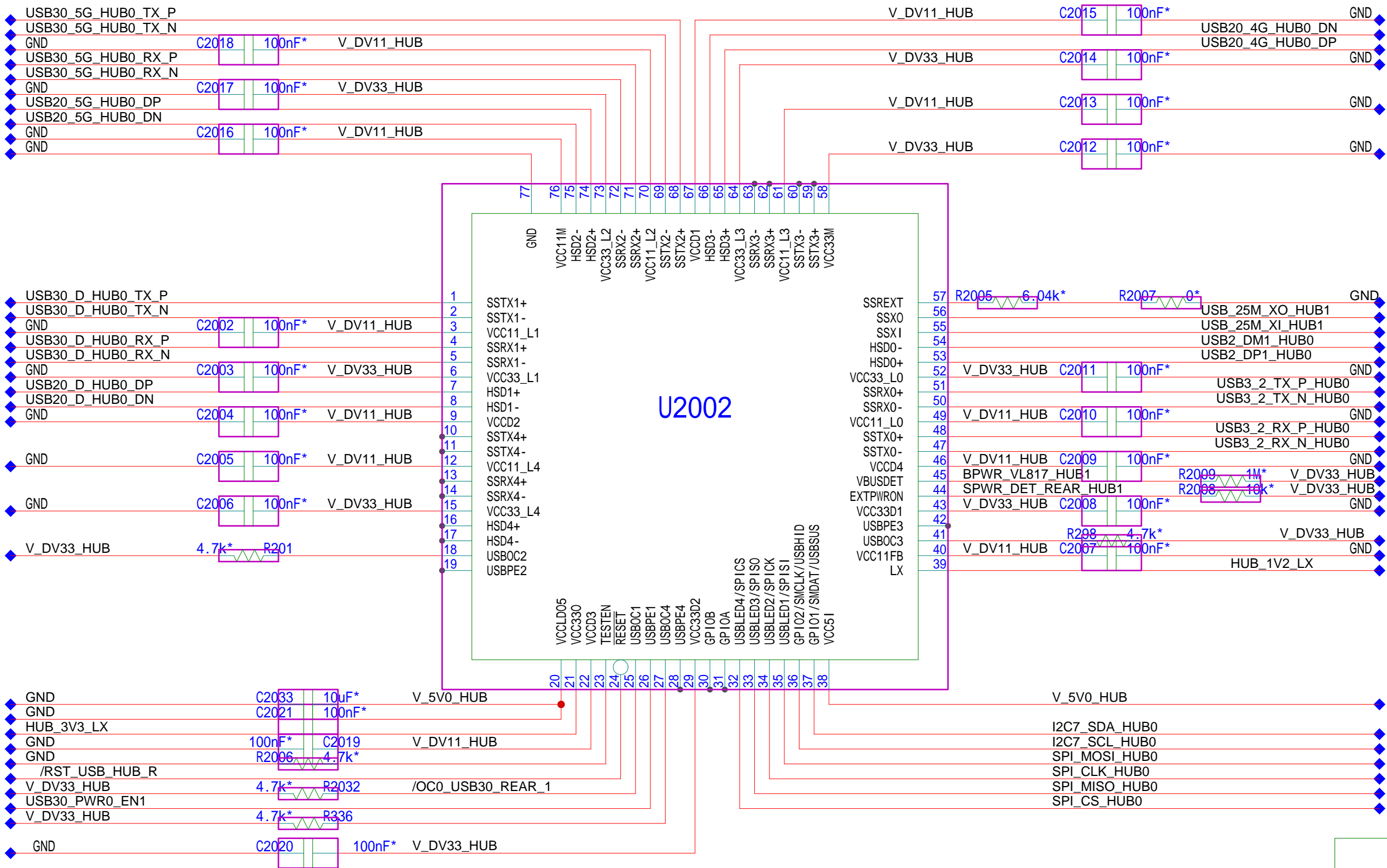
D

A

B

C

D



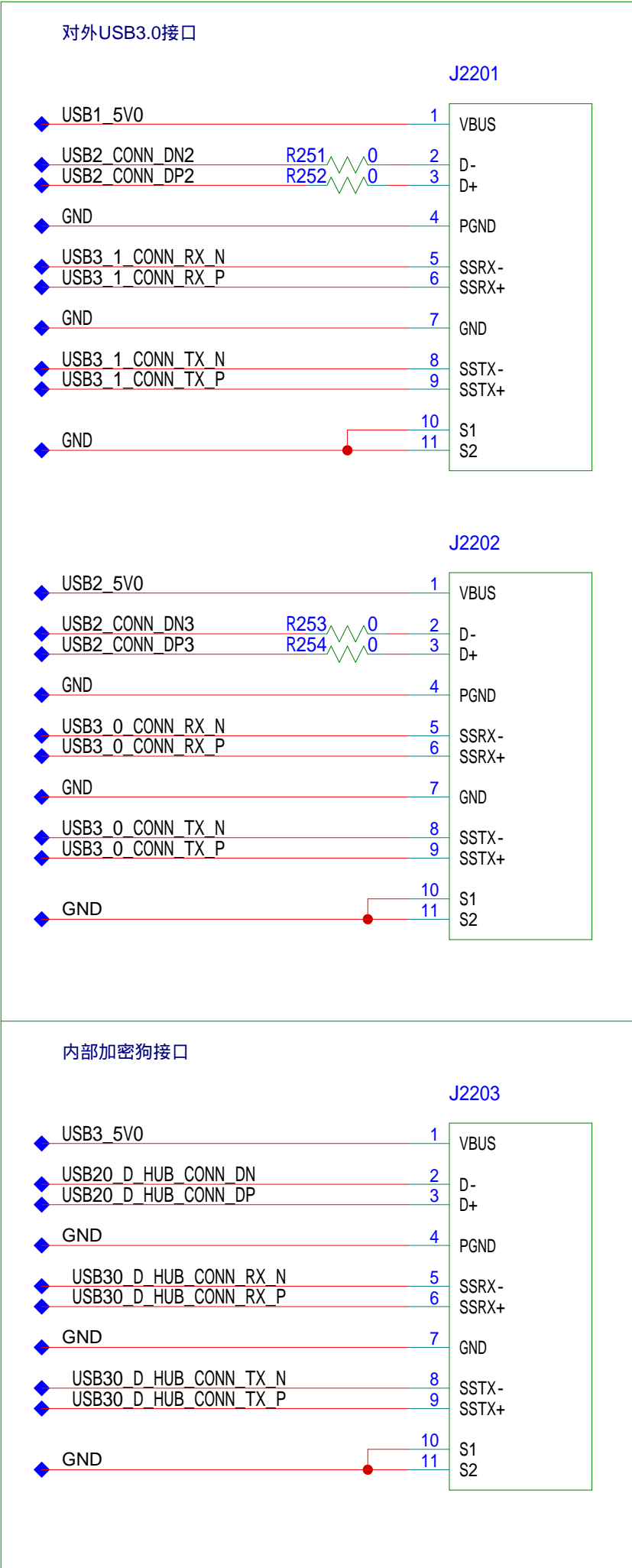
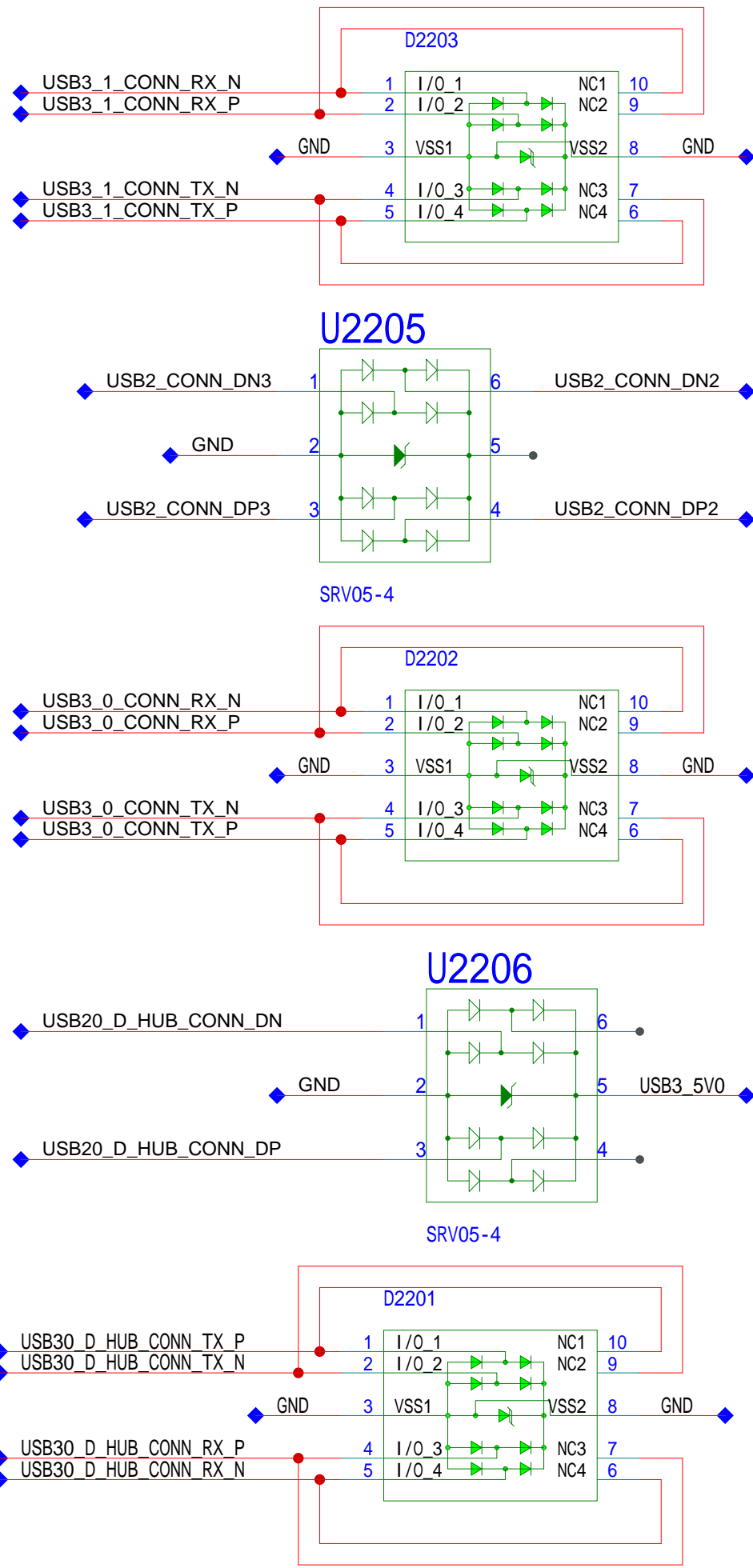
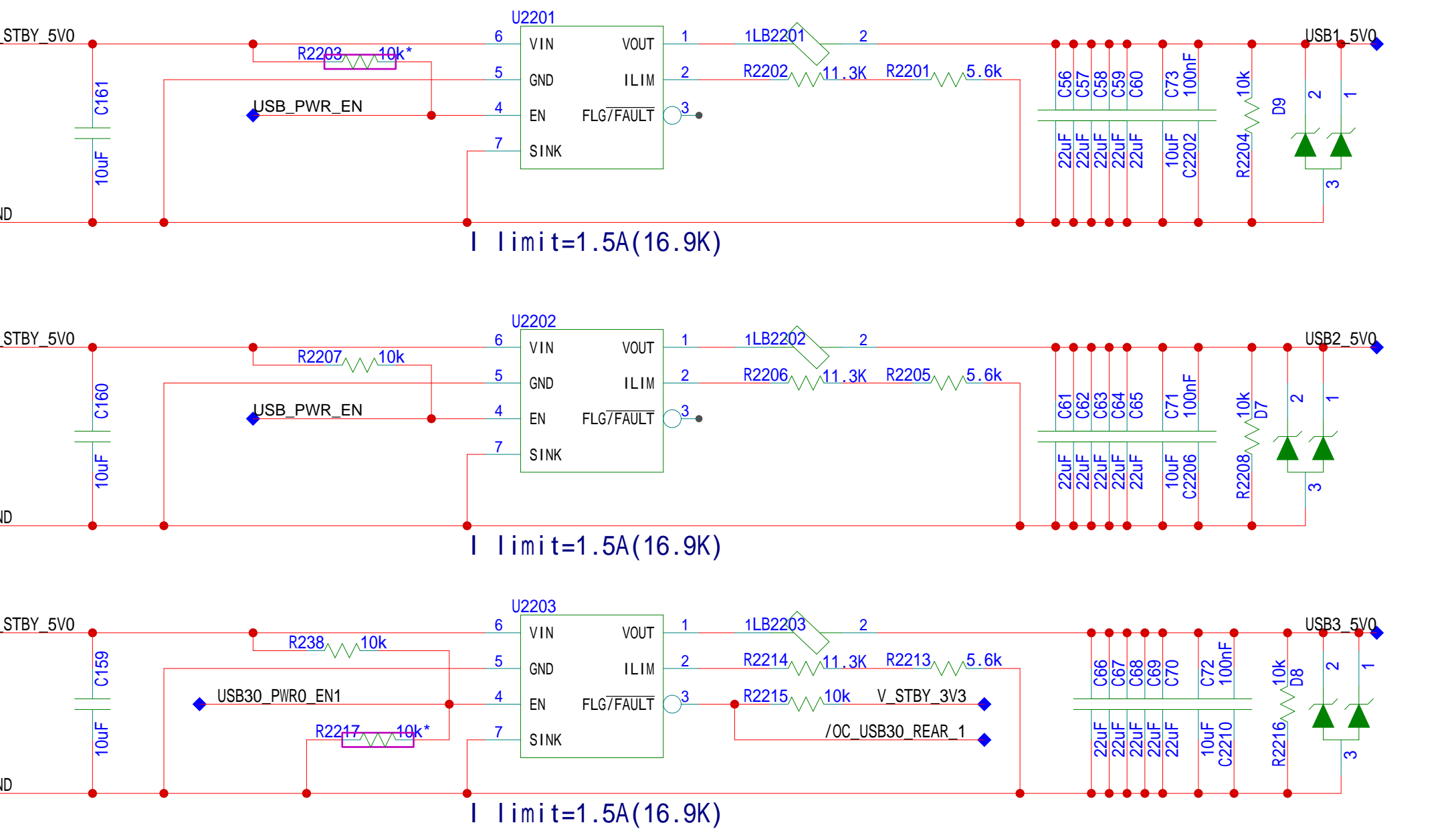
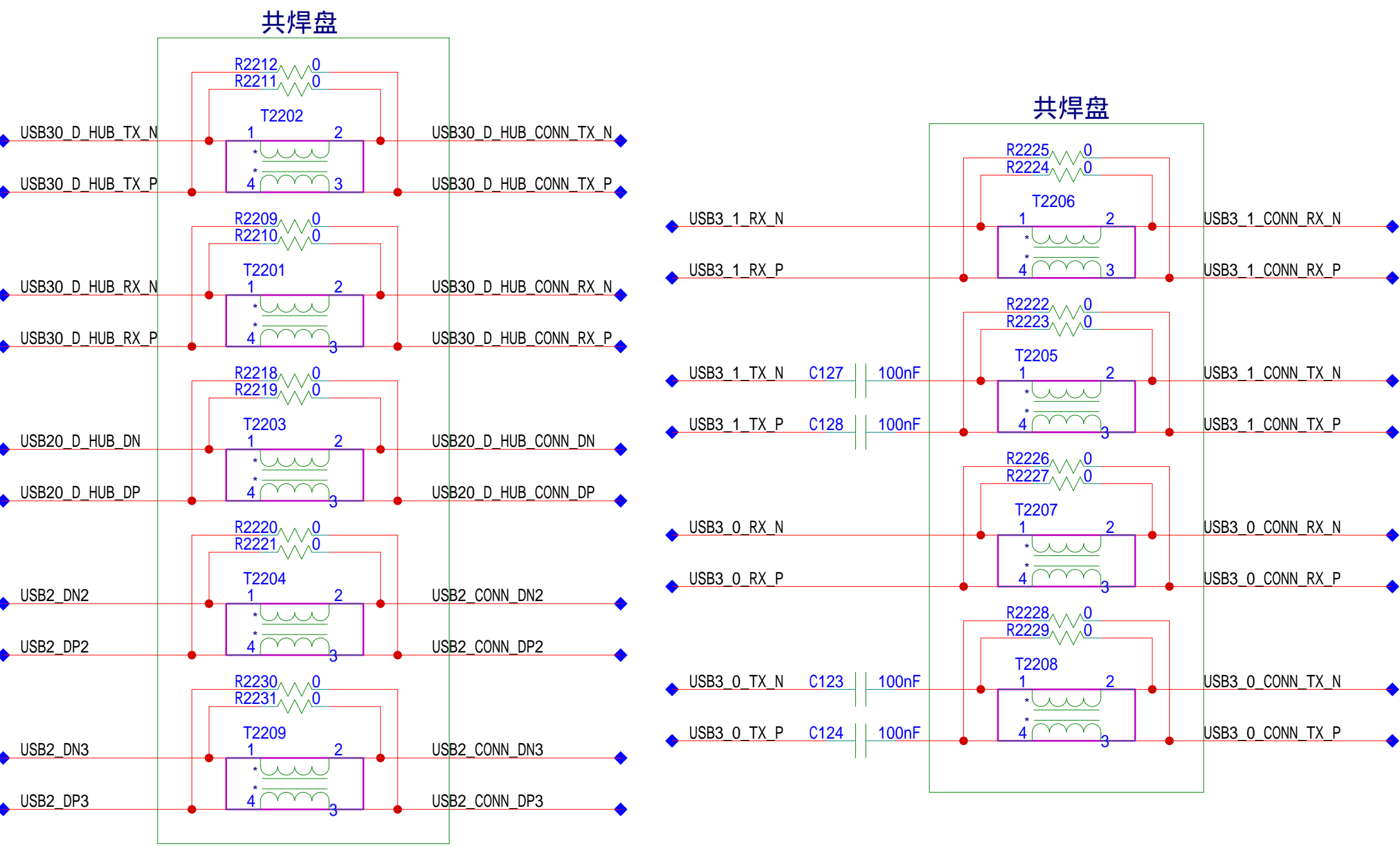
A



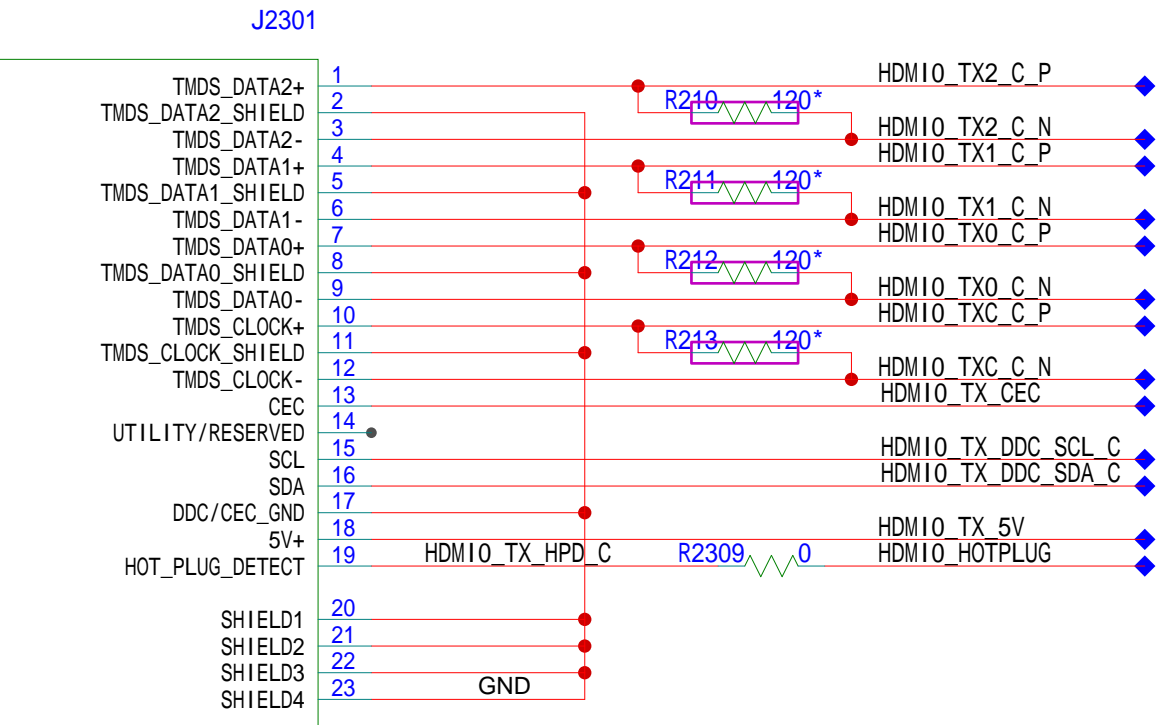
A



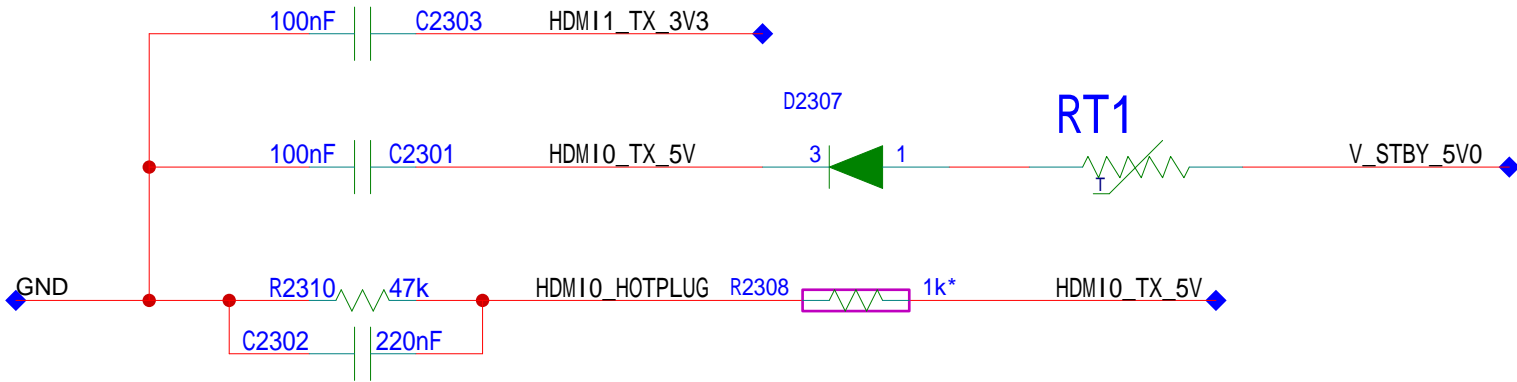
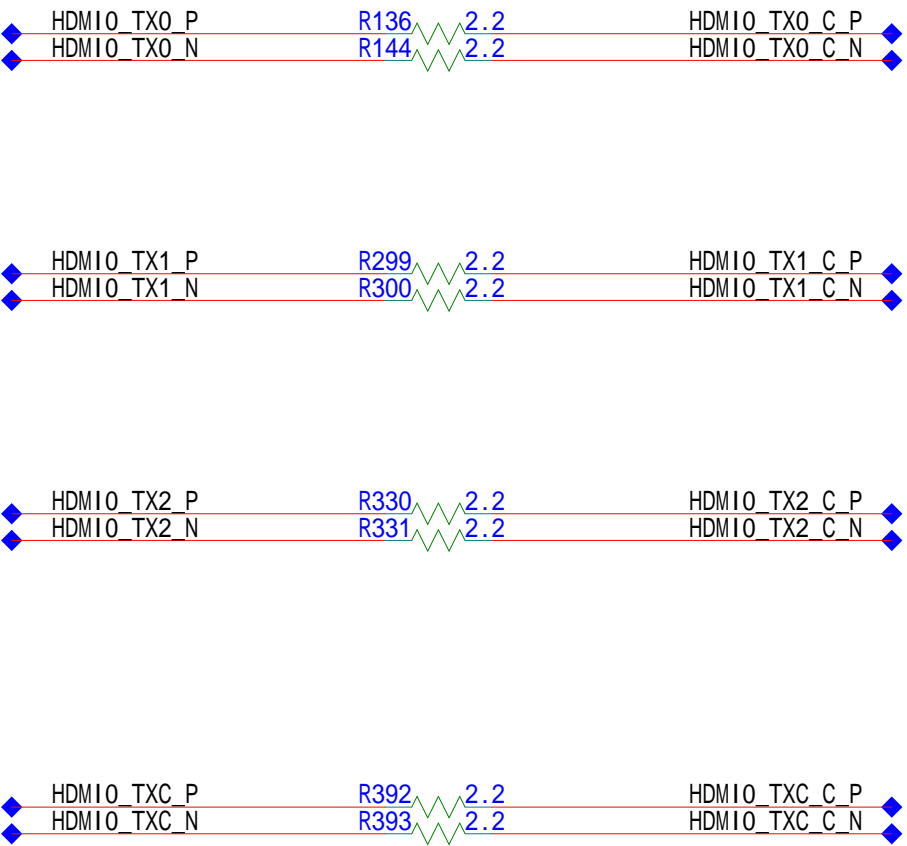
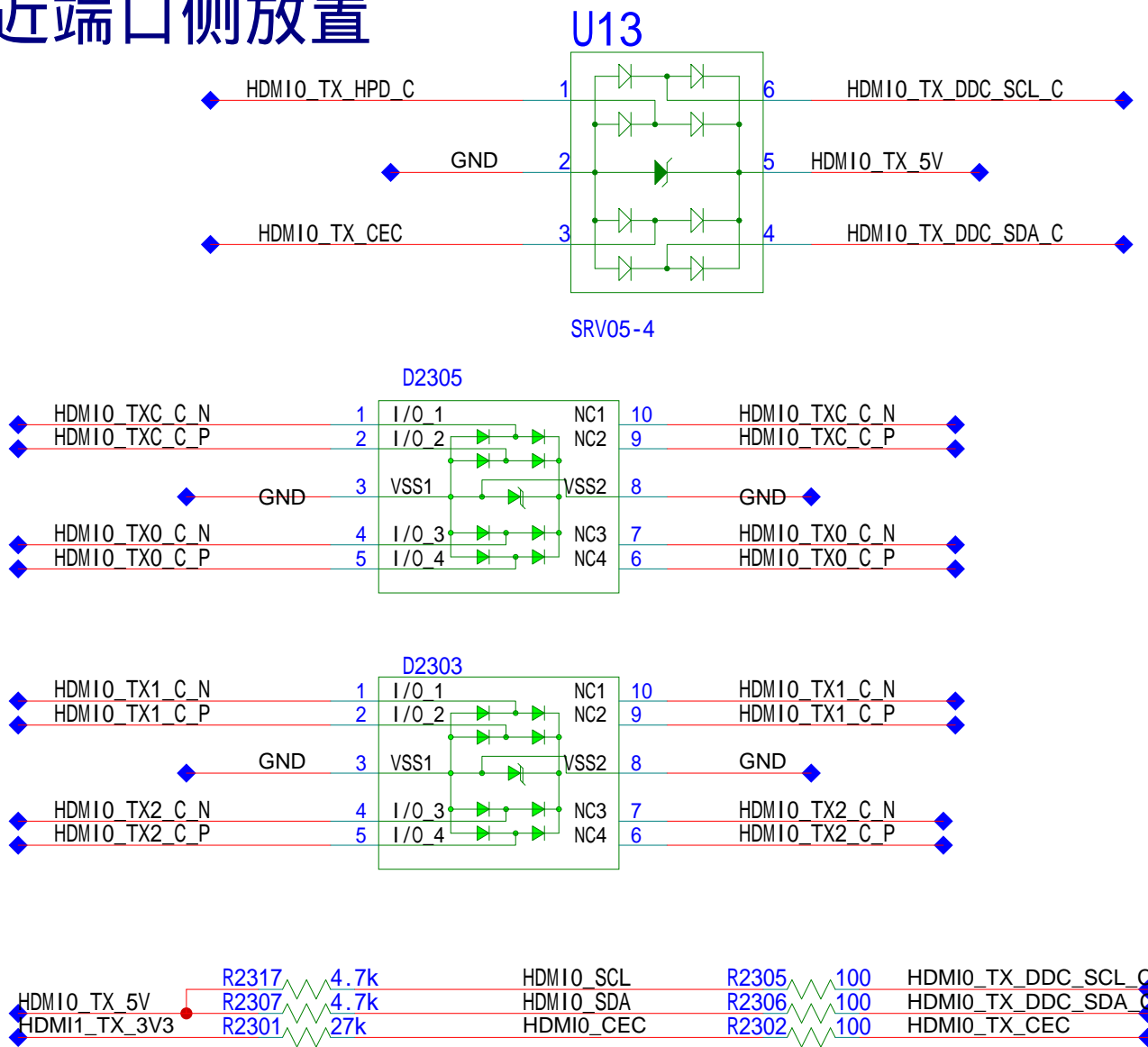
USB3.0 + USB2.0 Connector + Dongle(Type-A)



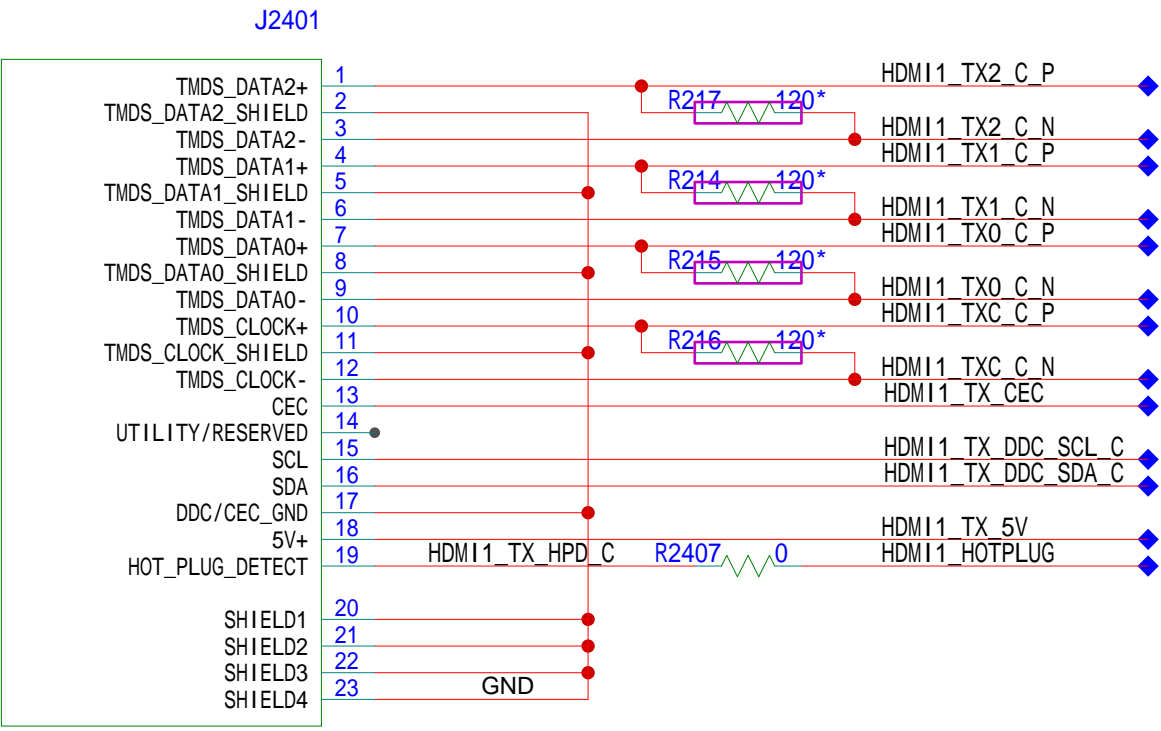
HDMI0 2.0 OUT



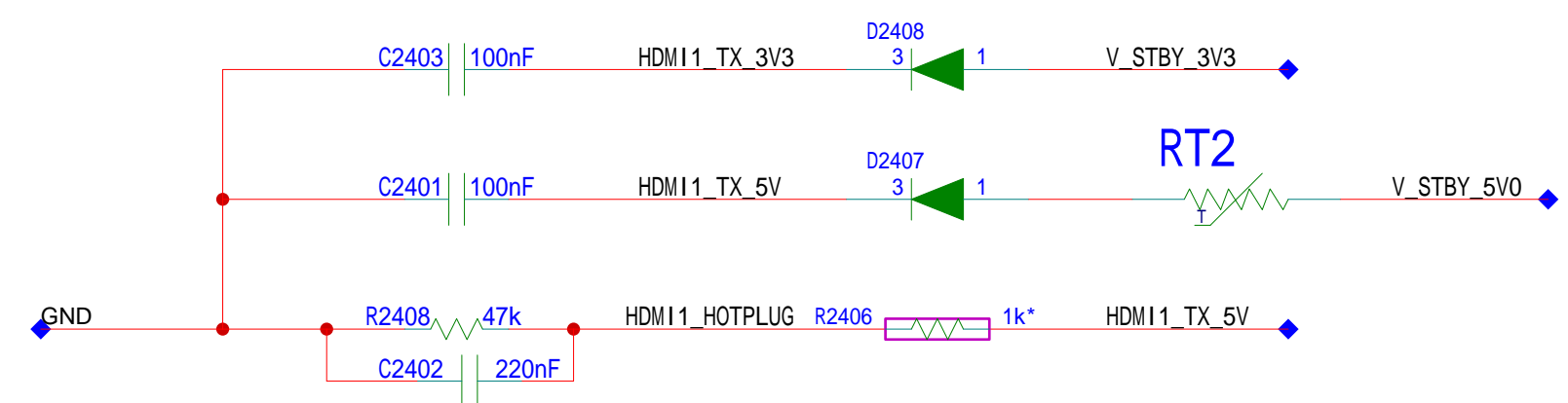
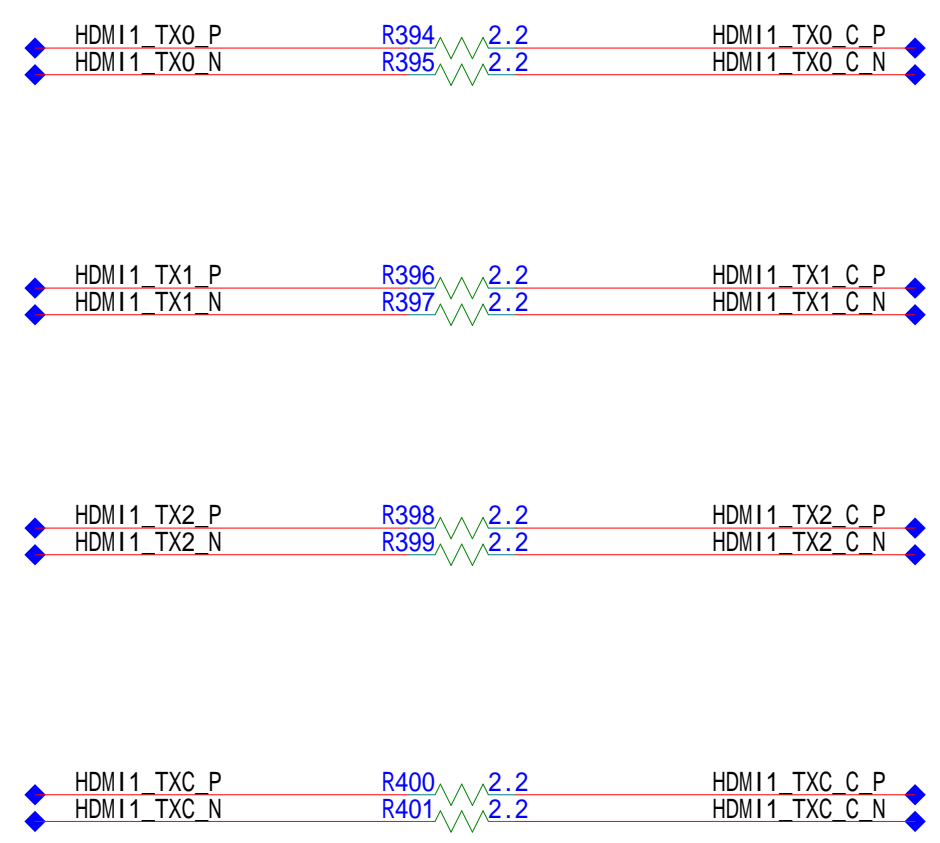
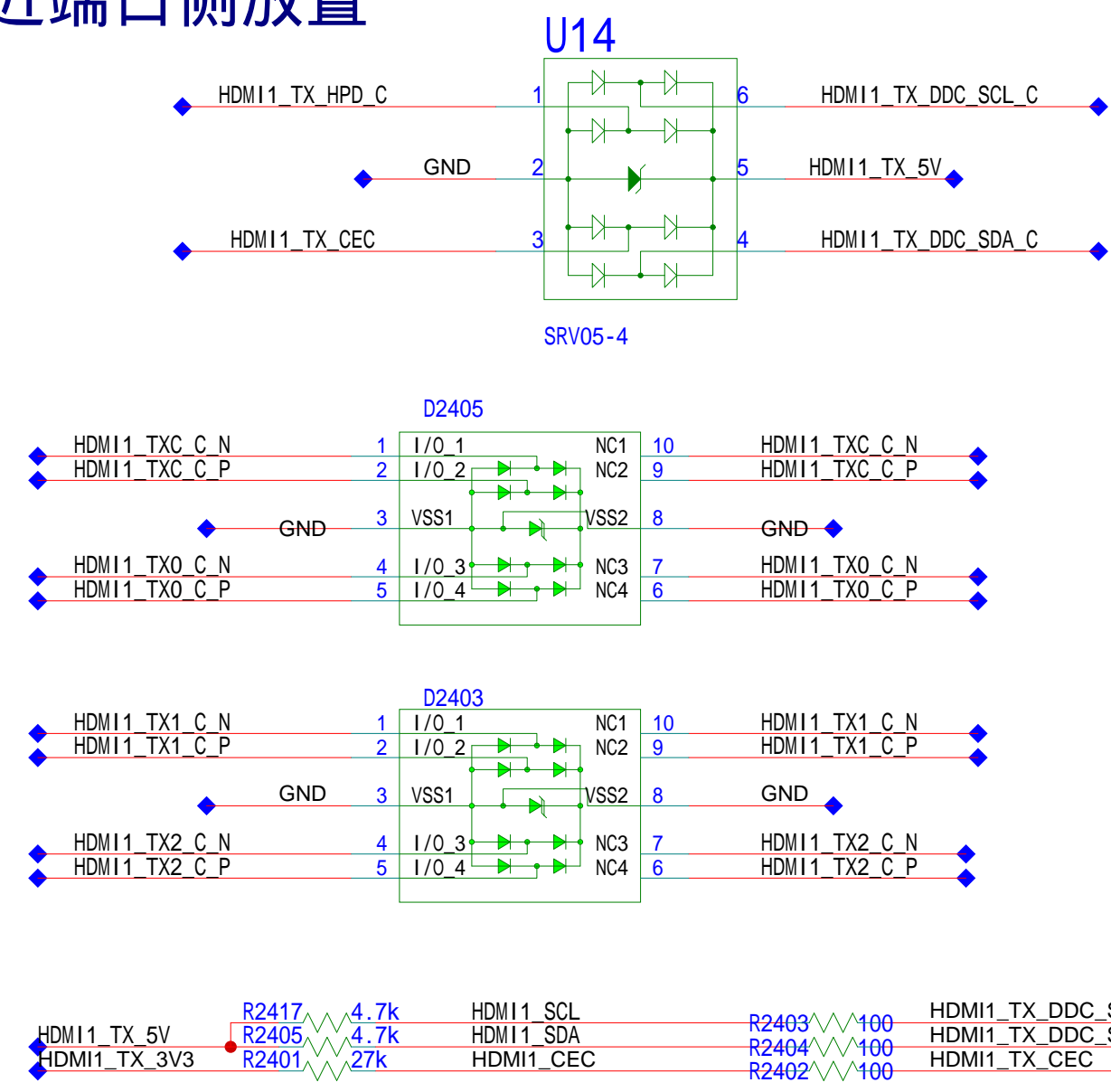
靠近端口侧放置



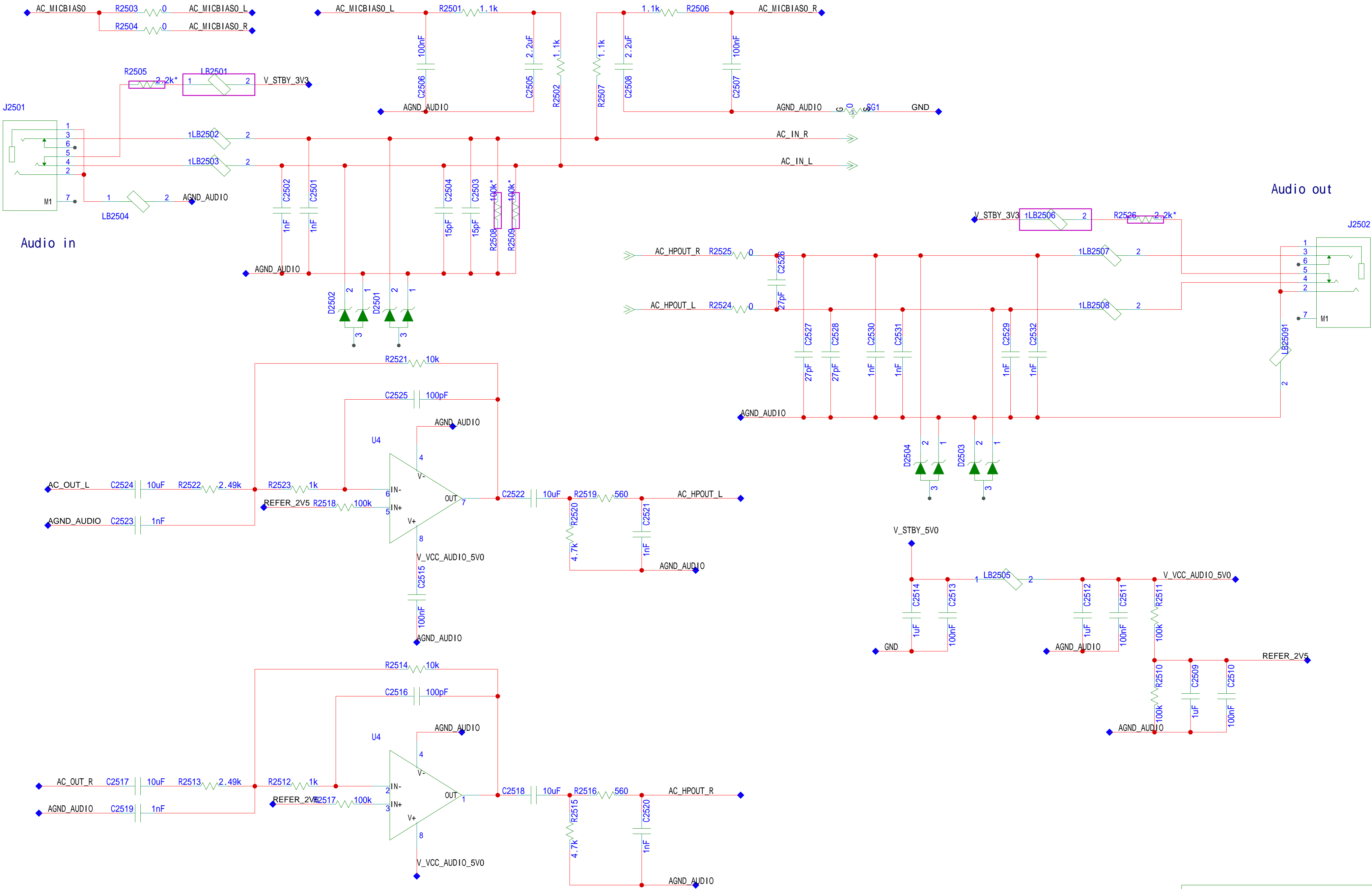
HDMI1 2.0 OUT



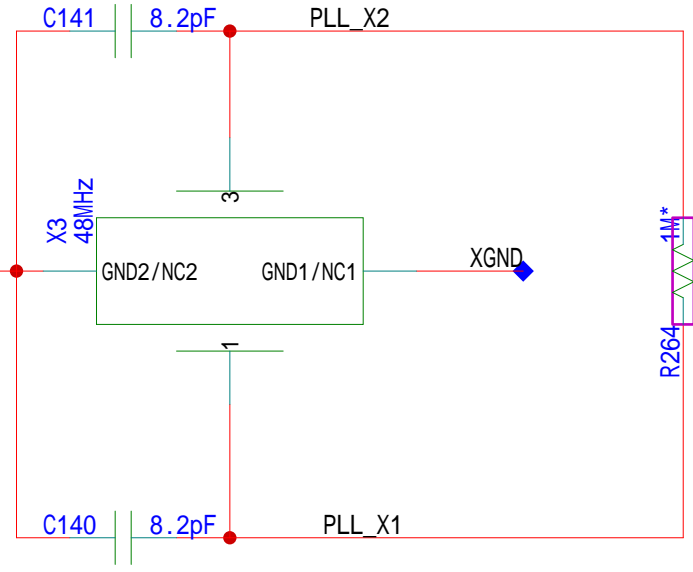
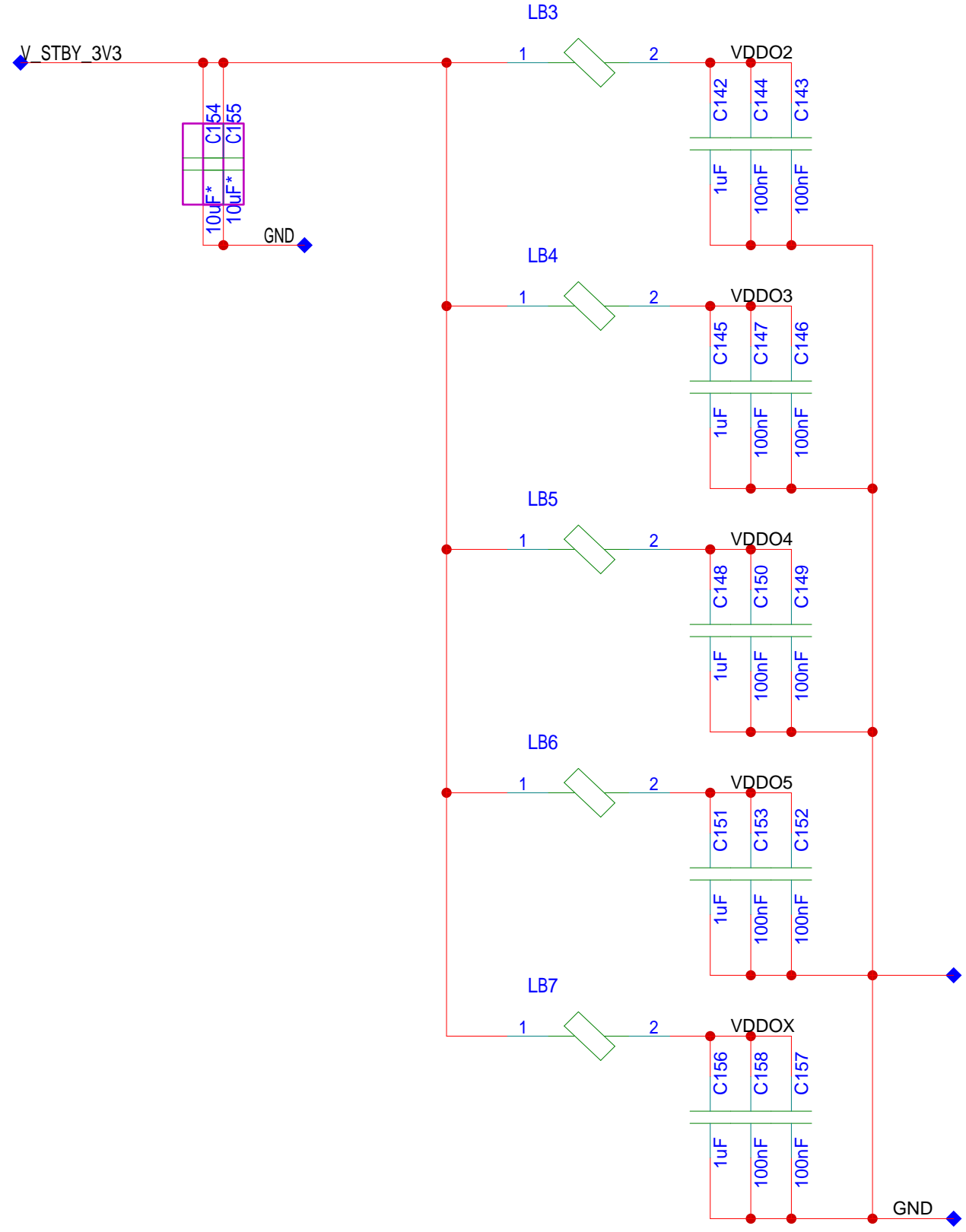
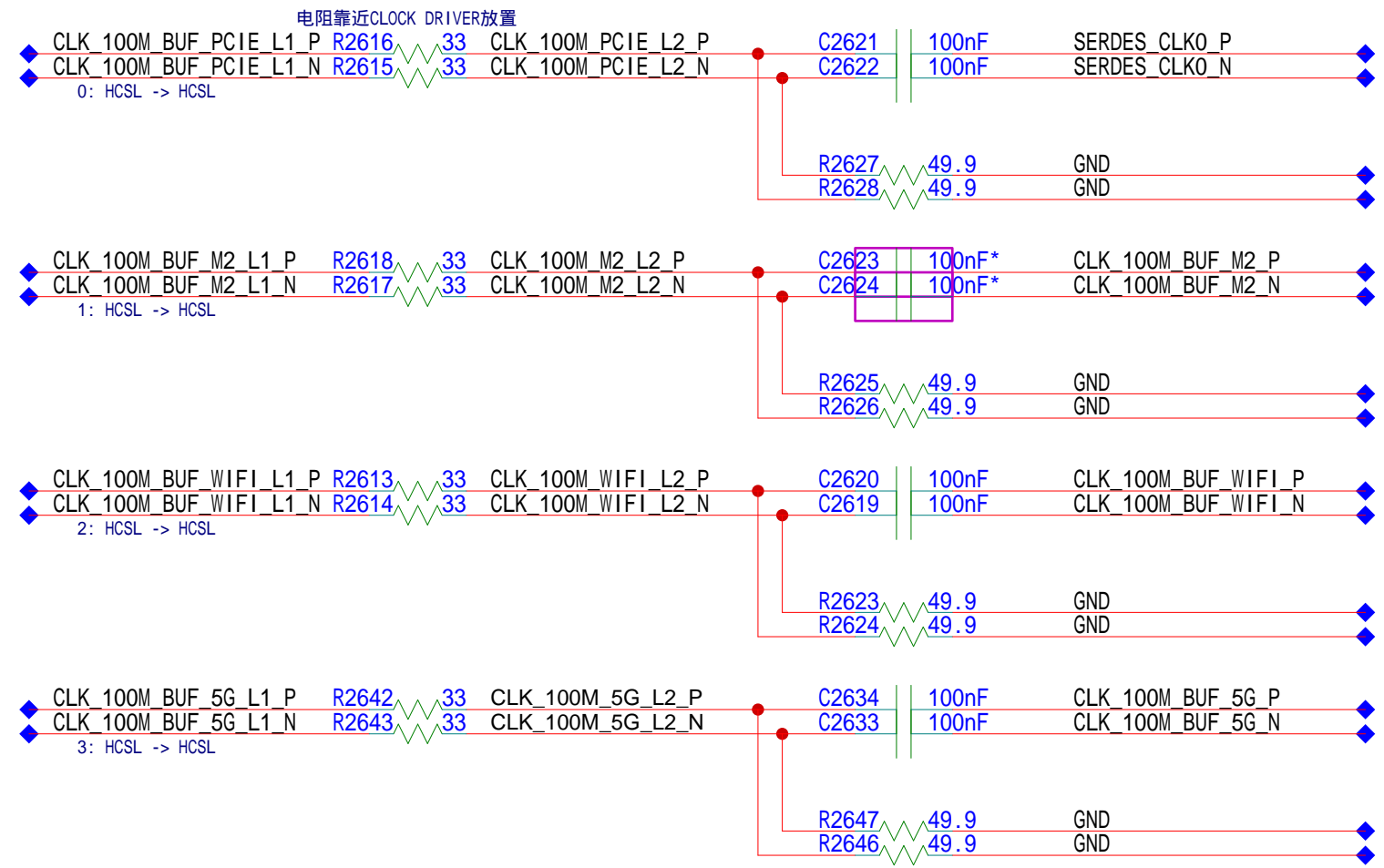
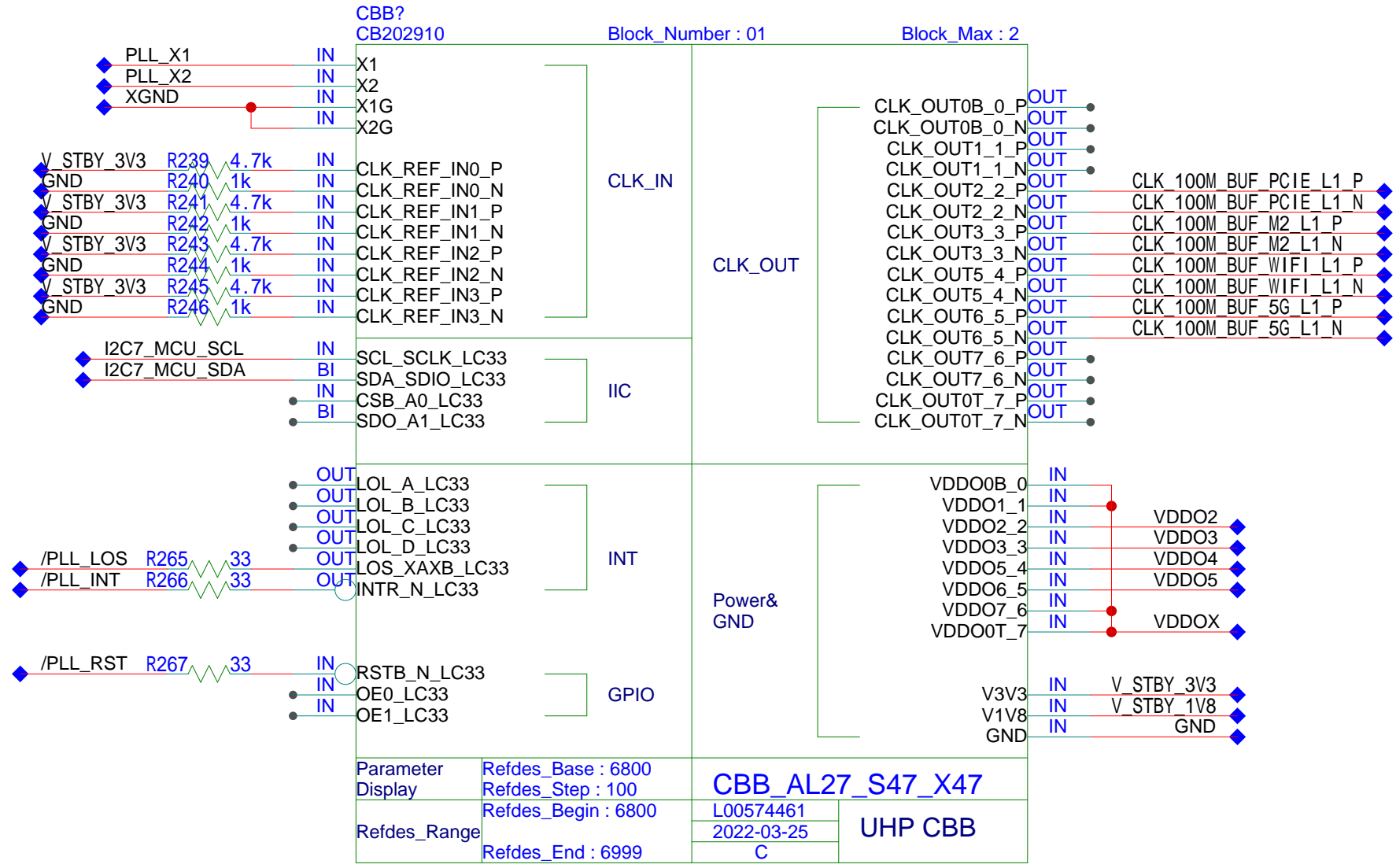
靠近端口侧放置



音频接口

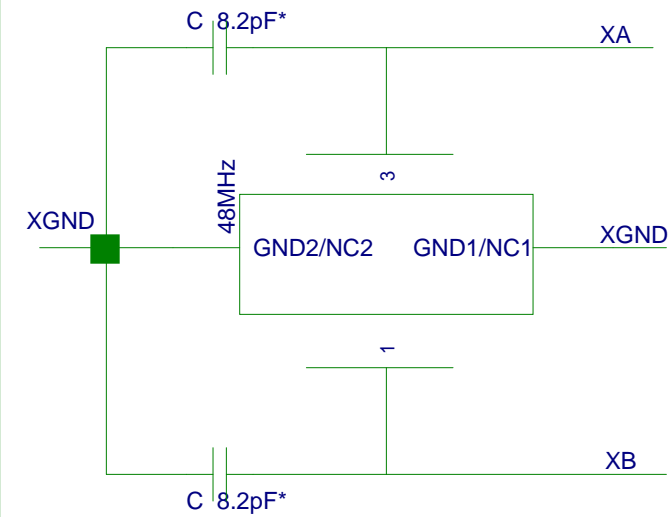


CLOCK



For details about the peripheral circuits of the CBB,see the white block diagram.

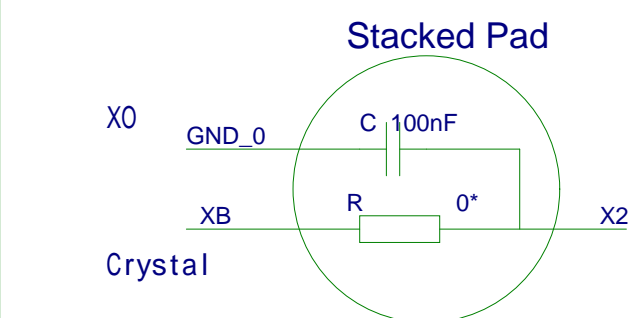
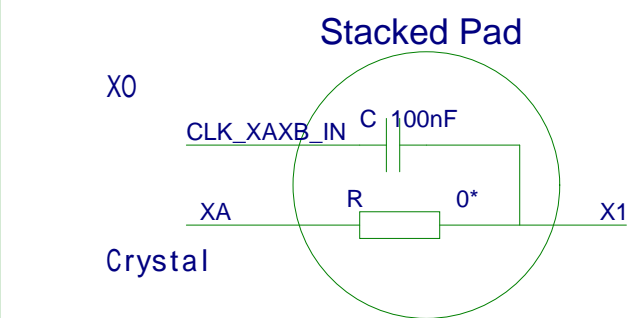
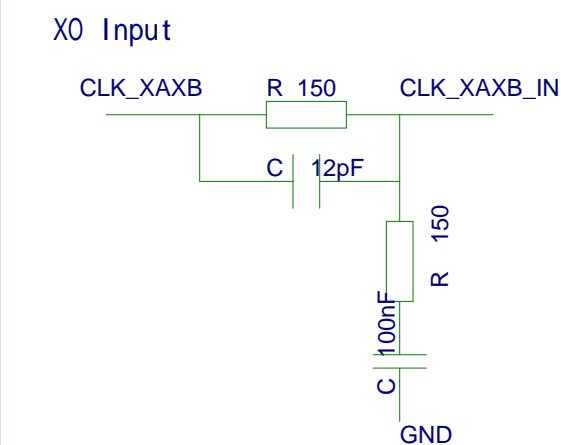
48 MHz crystal is recommended.



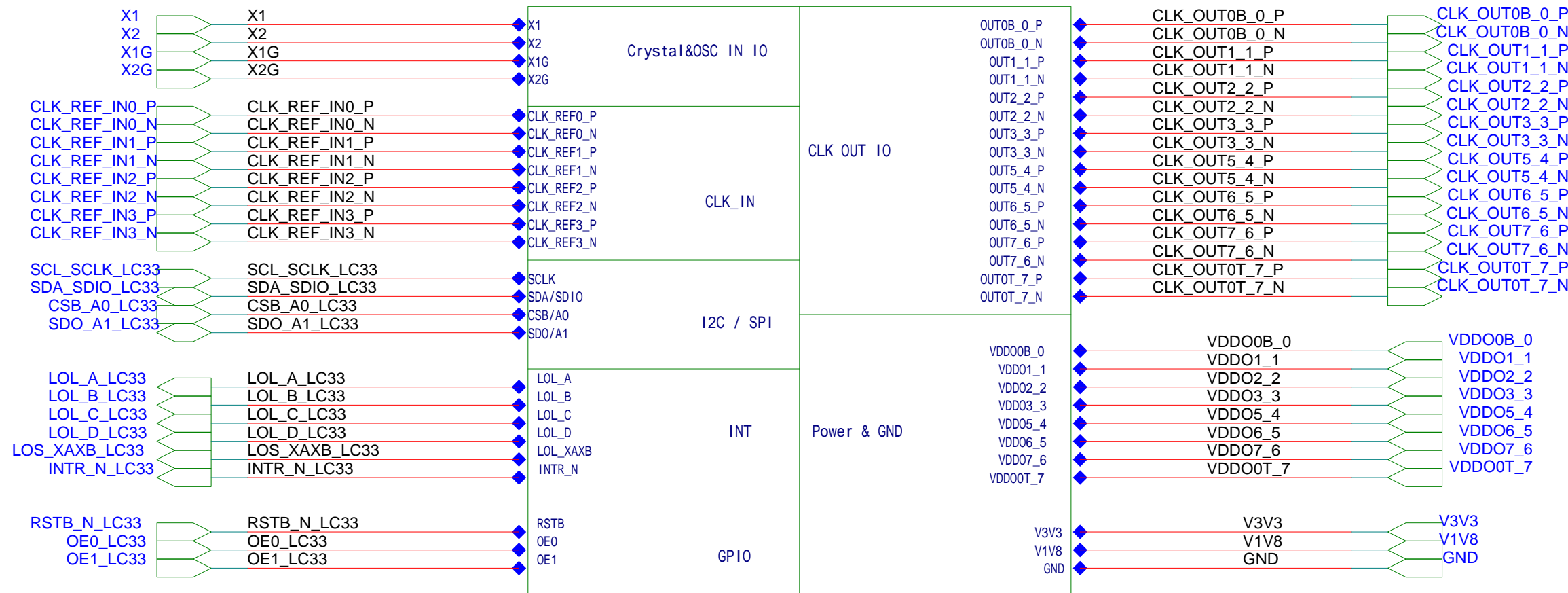
Crystal-compatible crystal oscillator circuit:

Whether the crystal oscillator circuit is reserved depends on product requirements.

Crystal-compatible crystal oscillator circuit:



NOTE: Huawei internal CBB. Do not discuss with external suppliers or take screenshots. ! ! !



Output Note :

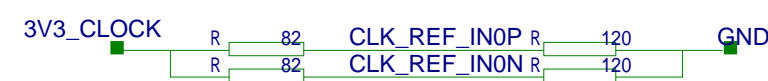
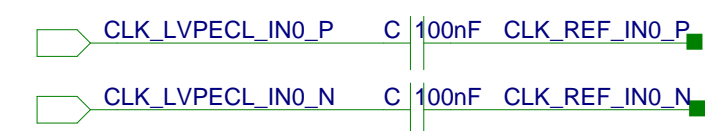
X47 : When the OUT1 pin is used for output, if the output clock frequency ranges from 50 MHz to 90 MHz, the output clock cannot be used as a high-performance clock (HI30/HI60, RMS jitter less than 300 fs) but can be used as a common performance clock (jitter less than 1 ps). There is no restriction on other frequencies.

L27/S47/X47:

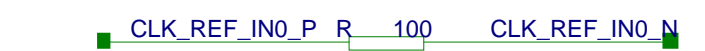
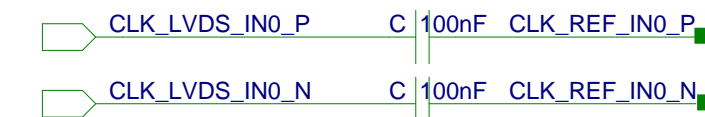
- Generally, it is not recommended to output single-ended clock signals.If different reference sources are used or the output frequency is not multiplied, the single-ended clock output pin must be separated from the differential clock output pin by at least two channels. Otherwise, the output clock performance of the differential pin will be affected (not meeting the H30/H60 requirements). The two differential outputs corresponding to different reference source inputs must be separated by one channel.
- Intra-frequency clocks output by the same loop or clocks with frequency multiplication relationships can be discharged without interval output pins.
- If the same clock source is traced for the same clock output by different loops or the clock with frequency multiplication relationship, the output pins do not need to be spaced.

REF_IN:Reference Circuit

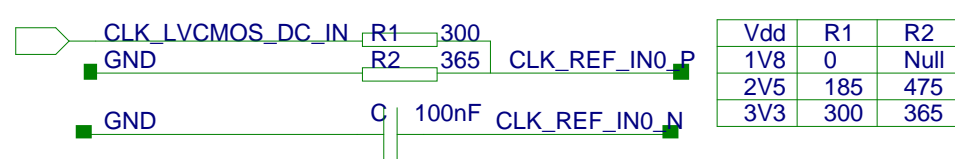
Option1 : AC Coupled Differential LVPECL



Option2 : AC Couple Differential LVDS/LVPECL

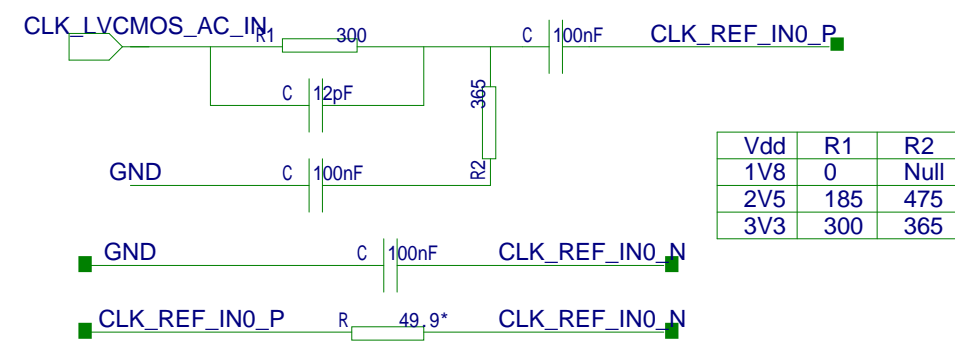


Option3 : Pulsed CMOS DC Coupled Signle Ended



When LVCMOS DC Coupling,please select the appropriate resistance to be compatible with the requirements of the co-coding chip for the single-ended DC input
AL27 LVCOMS DC Vih higher than 0.8V S47 LVCOMS DC Vih higher than 0.8V
X47 LVCOMS DC Vih higher than 0.9V

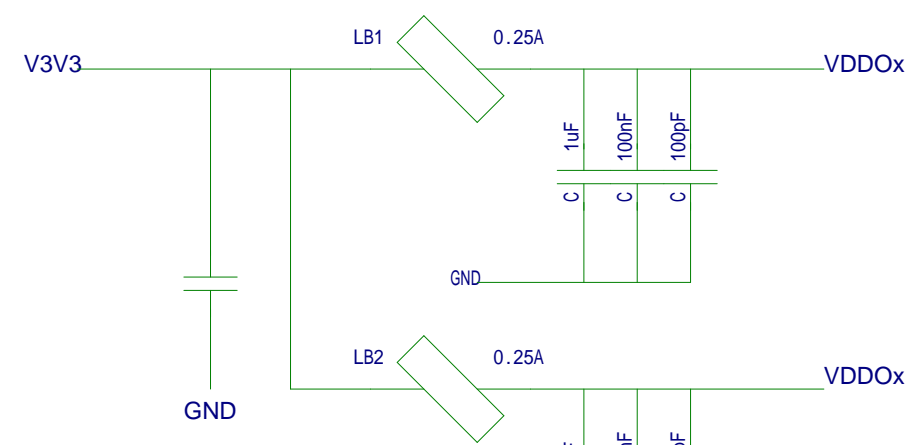
Option4 : Pulsed CMOS AC Coupled Signle Ended



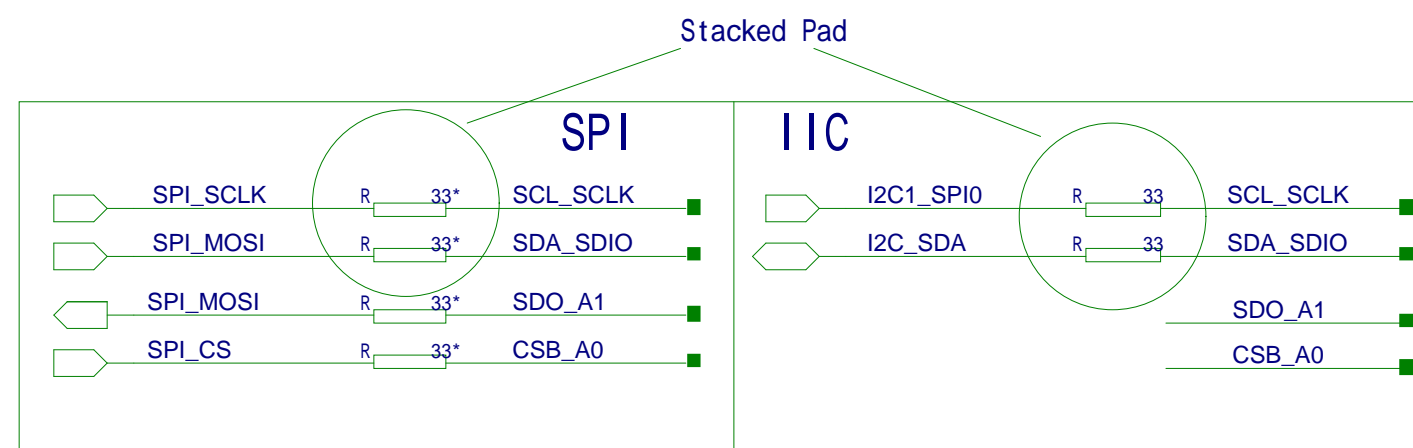
Select one of the voltage divider circuit or soldering 50 ohm resistors.

VDDOx:Reference Filter Circuit

Each product designs its own VDDOx circuiu as needed



AL27 IDDOx type:16mA
S47 IDDOx type:15mA
X47 IDDO0/1 type:36mA
X47 IDDO2-7 type:16mA

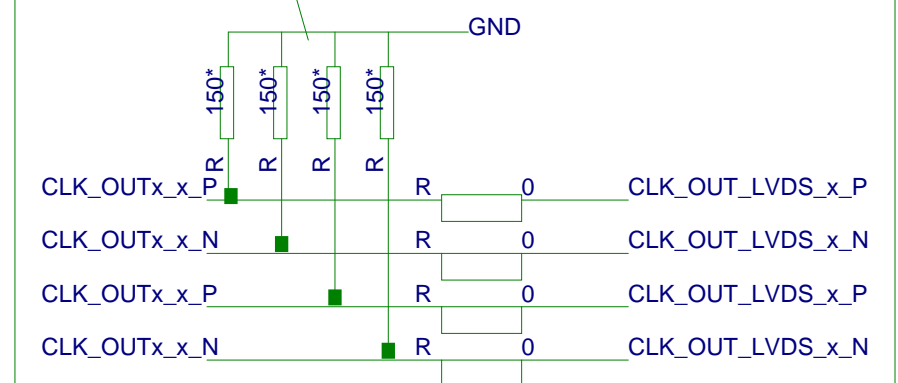


CLOCK CBB - 1

CLK_OUT:Reference Circuit

Option for Diff Output

The 150 ohm resistor is only used in LVPECL2 mode of AL53x7



NOTE:It is recommended to use LVDS output string 0 ohm resistor

CLOCK CBB -2

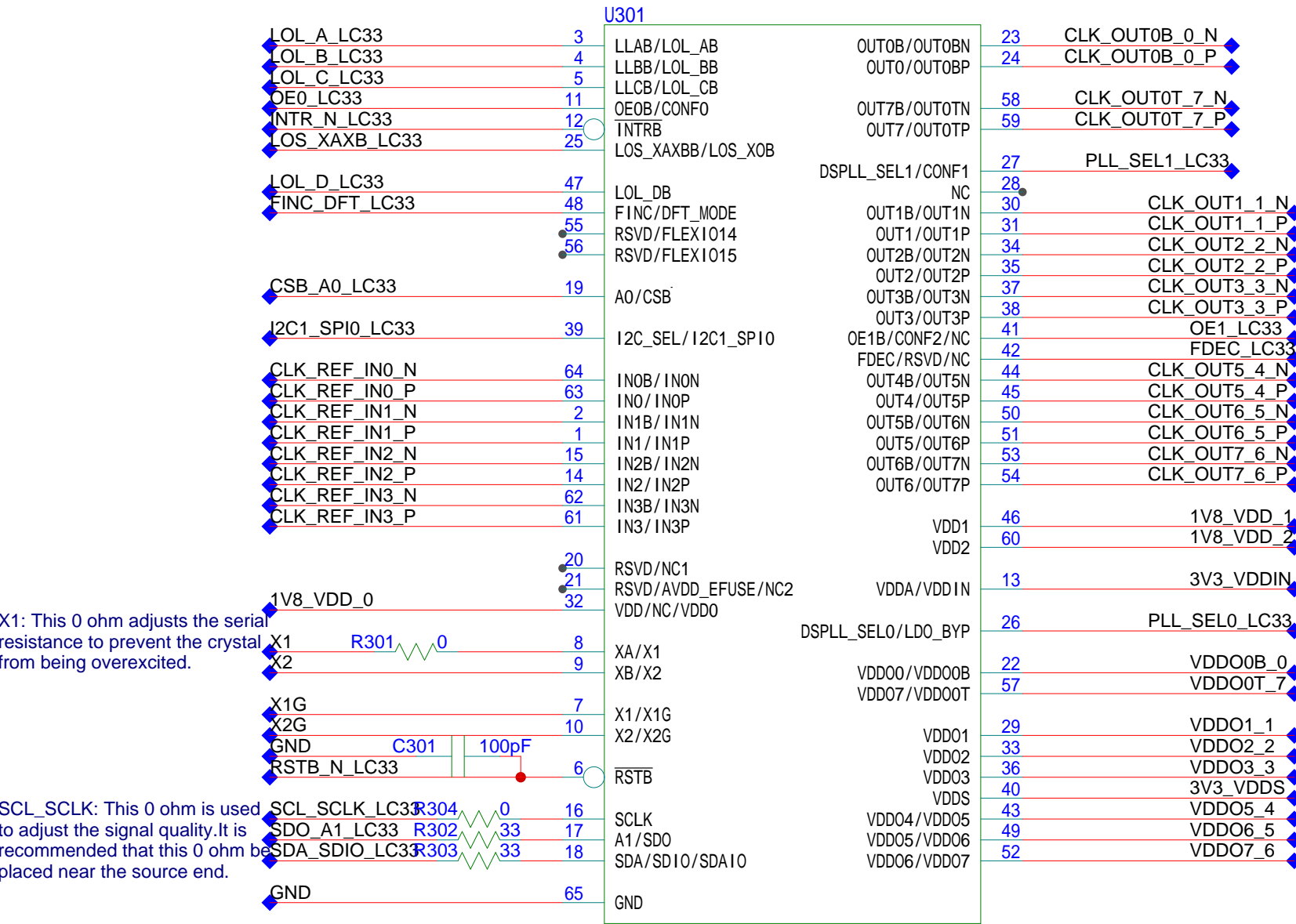
NOTE: Huawei internal CBB. Do not discuss with external suppliers or take screenshots. ! ! !

Compatible with S47 and AL27 and X47

A

PIN	S47	AL27	X47	PIN	Pin Differences
3	LOL_A	LOL_A	LOL_A	11	This pin is not used in normal applications of the three chips and requires pull-down. For S47 and L27, this pin controls the output enable of all outputs. For X47, this pin can control all output enable status only after this pin is enabled in the register.
4	LOL_B	LOL_B	LOL_B		
5	LOL_C	LOL_C	LOL_C		
11	OE0b	OE0b	OE0b	19	L27 does not support the 3-wire SPI mode.Both X47 and S47 support the 3-wire SPI mode. L27 does not support continuous reading and writing of multiple registers in SPI mode. Both X47 and S47 support this function. L27 does not support continuous writing of multiple registers in IIC mode. Both X47 and S47 support writing registers in IIC mode. This pin is the same for the normal application of the three chips.
12	INTR	INTR	INTR		
25	LOS_XAXB	LOS_XOB	LOS_XAXB		
47	LOL_D	LOL_D	LOL_D	40	The X47 pin has no actual function and can be connected or not. When the chip of other vendors is compatible, the 3V3 power supply must be connected. S47 This pin determines the VIH/VIL level of the FDEC and OE1b. It must be connected to the 3V3 power supply. L27: This pin determines the VIH/VIL level of the FDEC. It must be connected to the 3V3 power supply.
48	FINC	FINC	FINC		
55	RSVD	FLEXIO14	RSVD		
56	RSVD	FLEXIO15	RSVD	41	This pin is not used in normal applications of the three chips and requires pull-down. S47: This pin works with OE1a to enable or disable the chip output. L27: This pin is not used.
19	CSb/A0	CSb	CSb/A0		
39	I2C_SEL	I2C1_SPI0	I2C_SEL		
64	IN0b	IN0N	IN0b	55	This pin is not used when the three chips are normally used. The pin is pulled up or floated. For S47 and X47, this pin has no function. For L27, this pin can be used as a FLEX pin.
63	IN0	IN0P	IN0		
2	IN1b	IN1N	IN1b		
1	IN1	IN1P	IN1	56	This pin is not used when the three chips are normally used. The pin is pulled up or floated. For S47 and X47, this pin has no function. For L27, this pin can be used as a FLEX pin.
15	IN2b	IN2N	IN2b		
14	IN2	IN2P	IN2		
62	IN3b	IN3N	IN3b	65	SCL_SCLK: This 0 ohm is used to adjust the signal quality.It is recommended that this 0 ohm be placed near the source end.
61	IN3	IN3P	IN3		
20	RSVD	NC	RSVD		
21	RSVD	NC	RSVD	66	SCL_SCLK: This 0 ohm is used to adjust the signal quality.It is recommended that this 0 ohm be placed near the source end.
32	VDD	NC	VDD		
8	XA	X1	XA		
9	XB	X2	XB	67	SCL_SCLK: This 0 ohm is used to adjust the signal quality.It is recommended that this 0 ohm be placed near the source end.
7	X1	X1G	X1		
10	X2	X2G	X2		
6	RSTb	RSTB	RSTb	68	SCL_SCLK: This 0 ohm is used to adjust the signal quality.It is recommended that this 0 ohm be placed near the source end.
16	SCLK	SCLK	SCLK		
17	SDO/A1	SDO	SDO/A1		
18	SDA/SDIO	SDAIO	SDA/SDIO	69	SCL_SCLK: This 0 ohm is used to adjust the signal quality.It is recommended that this 0 ohm be placed near the source end.
65	GND	GND	GND		

B



The VDD power pins are connected to filter circuits to obtain better phase noise.

PIN	S47	AL27	X47
23	OUT0b	OUT0BN	OUT0b
24	OUT0	OUT0BP	OUT0
58	OUT7b	OUT0TN	OUT7b
59	OUT7	OUT0TP	OUT7
27	DSPLL_SEL1	PLL_SEL1	DSPLL_SEL1
28	NC	NC	NC/RSVD
30	OUT1b	OUT1N	OUT1b
31	OUT1	OUT1P	OUT1
34	OUT2b	OUT2N	OUT2b
35	OUT2	OUT2P	OUT2
37	OUT3b	OUT3N	OUT3b
38	OUT3	OUT3P	OUT3
41	OE1b	NC	OE1b
42	FDEC	FDEC	FDEC
44	OUT4b	OUT5N	OUT4b
45	OUT4	OUT5P	OUT4
50	OUT5b	OUT6N	OUT5b
51	OUT5	OUT6P	OUT5
53	OUT6b	OUT7N	OUT6b
54	OUT6	OUT7P	OUT6
46	VDD	VDD	VDD1
60	VDD	VDD	VDD2
13	VDDA	VDDIN	VDDA
26	DSPLL_SEL_0	PLL_SEL_0	DSPLL_SEL_0
22	VDD00	VDD0B	VDD00
57	VDD07	VDD0T	VDD07
29	VDD01	VDD01	VDD01
33	VDD02	VDD02	VDD02
36	VDD03	VDD03	VDD03
40	VDD5	VDD5	VDD5
43	VDD04	VDD05	VDD04
49	VDD05	VDD06	VDD05
52	VDD06	VDD07	VDD06

A

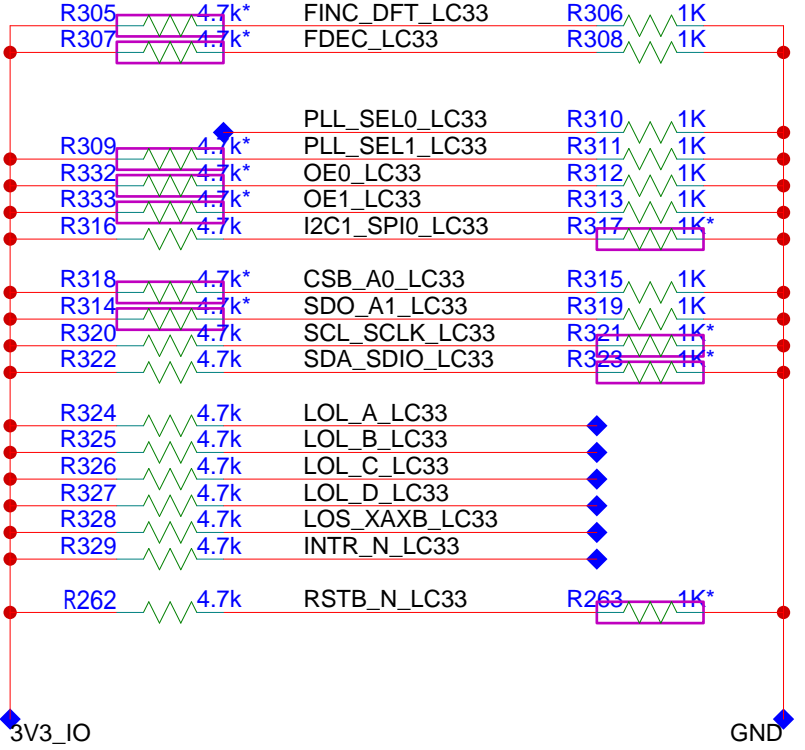
B

C

Functions of GPIO pins:

FINC/FDEC	X47/S47/AL27:FINC , Used as frequency up step control in DCO mode X47/S47/AL27:FDEC , Used as frequency down step control in DCO mode
PLL_SELO/1	X47/S47/AL27:PLL_SELO with PLL_SEL1 , Loop selection signal for pin control in DCO mode
OE1/OE2	X47/S47/AL27: OE1 works with OE2 to determine all output configurations of the chip.X47/S47/AL27: Pull-down resistors must be connected to the ground. Pull-up resistors cannot be connected or floated.The pull-up resistors in the circuit must be soldered and reserved. Note that the X47 can be used only after the register is configured.
I2C1_SPI0	I2C_SEL=1 : IIC mode; I2C_SEL=0 SPI mode Pull-up IIC mode and pull-down SPI mode. The IIC mode is recommended.
A0/A1	A0: used as the A0 address in IIC mode and as the chip select pin in SPI mode. Internal pull-up, floating when not in use.
LOL_A/B/C/D	SDAIO: SDA in IIC mode and SCLK in SPI mode; SCLK: SCL in IIC mode and SCLK in SPI mode; SDAIO: SDA in IIC mode; bi-direction data in 3-wire SPI mode; data input in 4-wire SPI mode
SCLK/SDAIO	LOLA: PLLA loop lock status interrupt indication signal. It is recommended that this signal be connected to the logic. LOLB: PLLB loop lock status interrupt indication signal. It is recommended that this signal be connected to the logic. LOLC: PLLC loop lock status interrupt indication signal. It is recommended that this signal be connected to the logic. LOLD: PLLD loop lock status interrupt indication signal. It is recommended that this signal be connected to the logic. LOL_XAXB: LOS interrupt indication signal of the XAXB working clock. It is recommended that this signal be connected to the logic.
INTRb	INTRb: interrupt indication signal. It is recommended that this signal be connected to the logic.
RSTB	Reset signal, active low; The logic must be connected. Before the chip is initialized, reset and deassert the reset.

D



Note: The SPI bus cannot be connected to multiple chips.

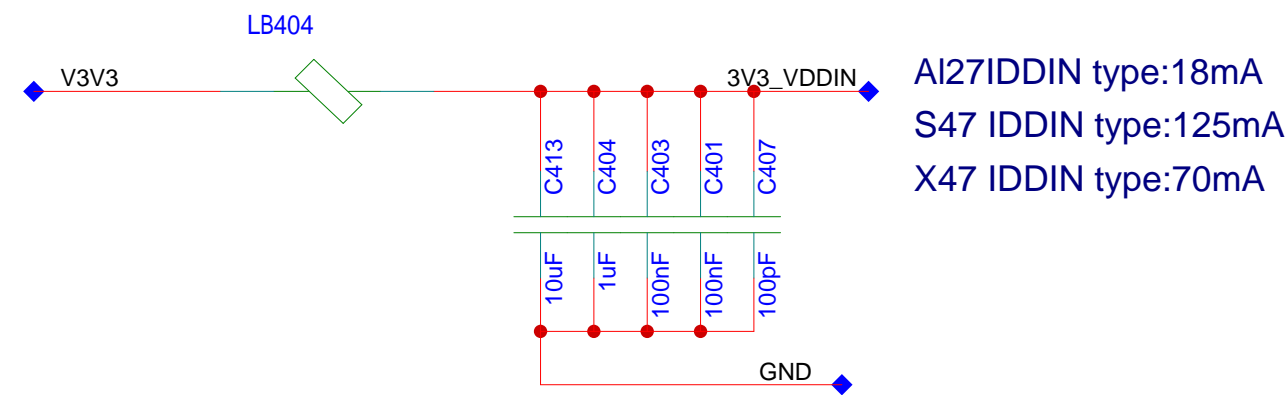
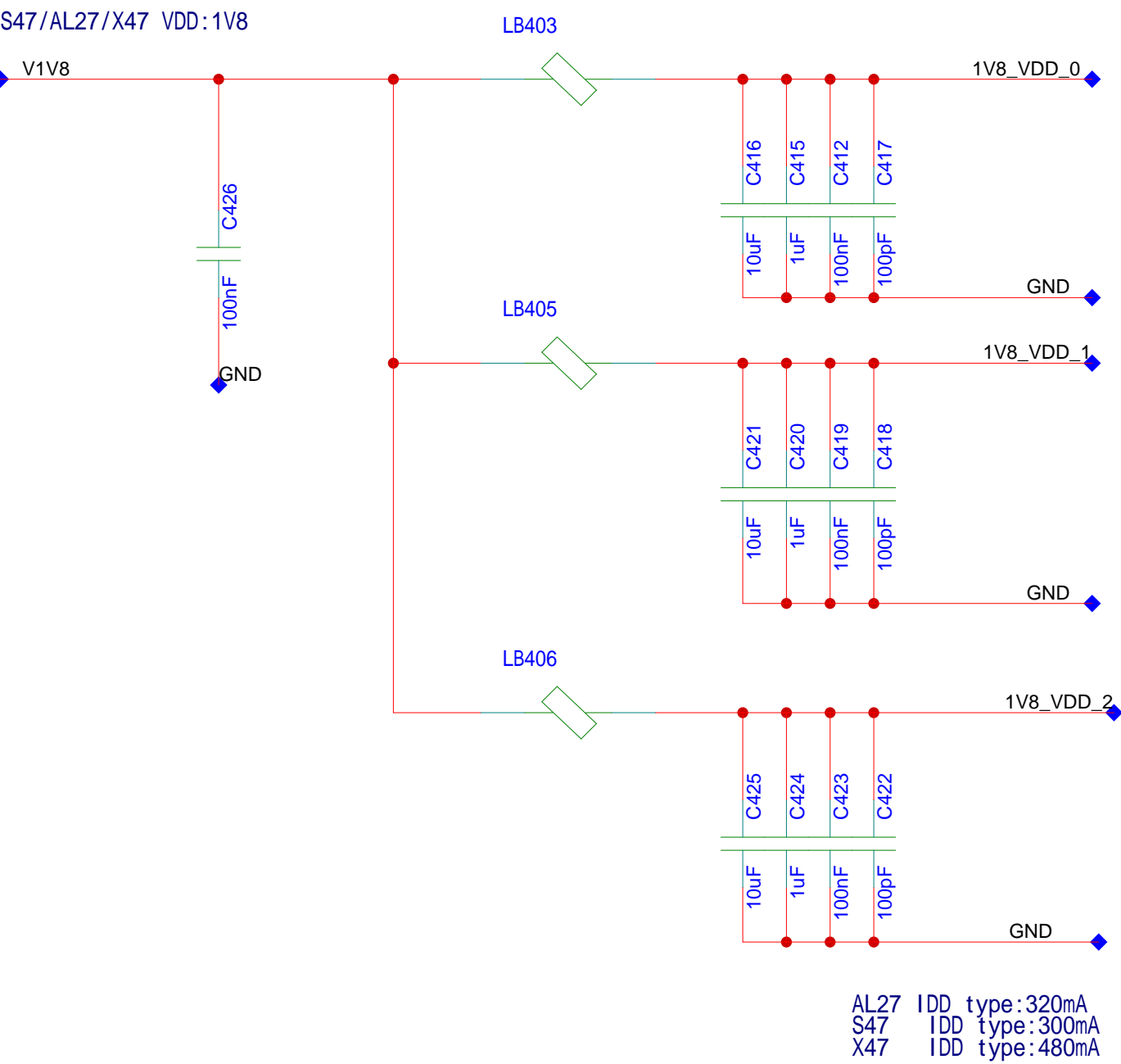
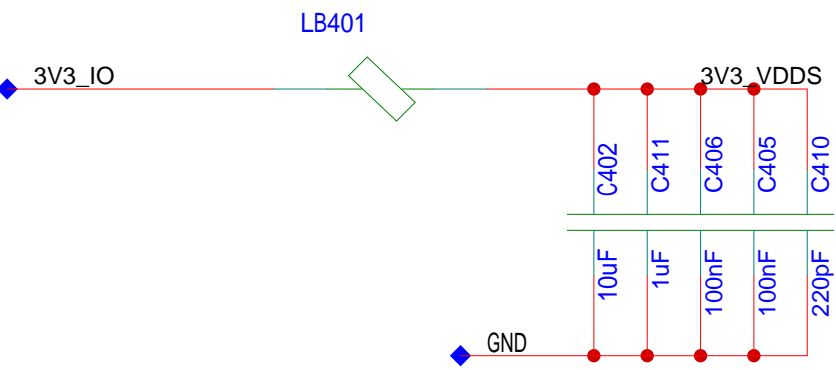
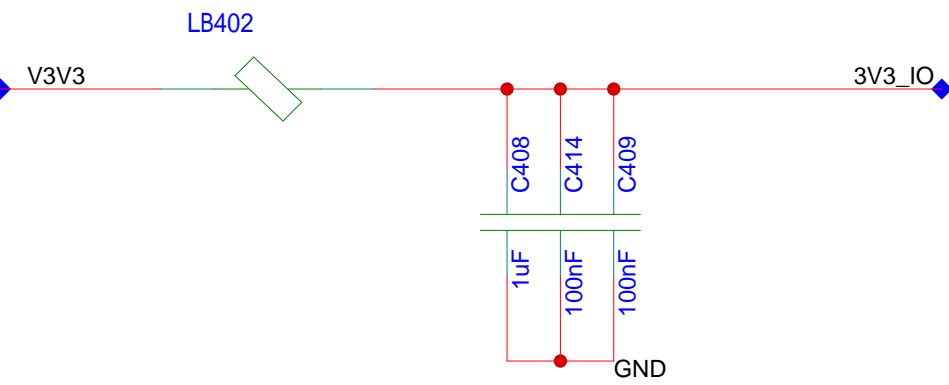
C

D

CLOCK CBB -3

Recommended circuit for VDD:

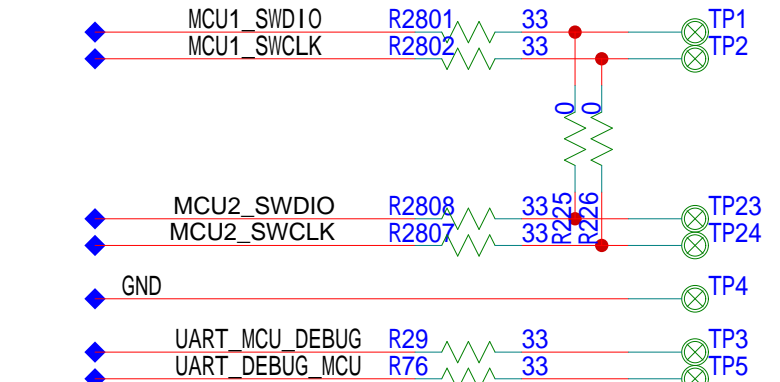
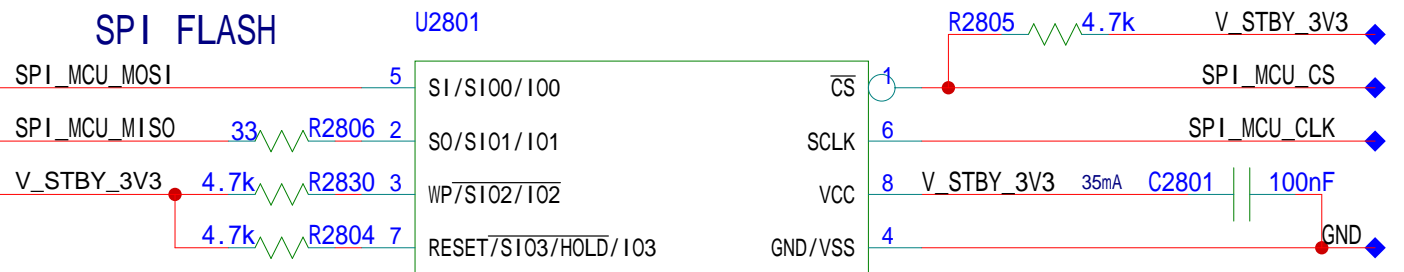
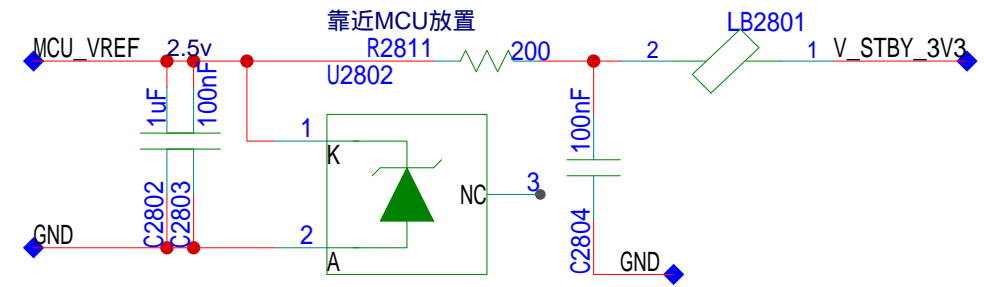
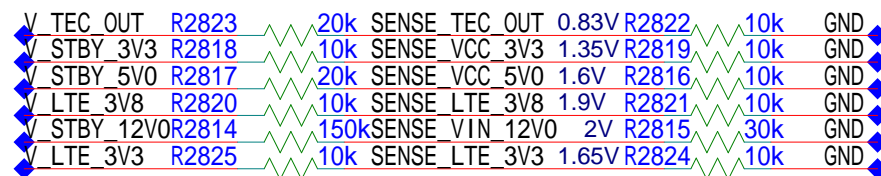
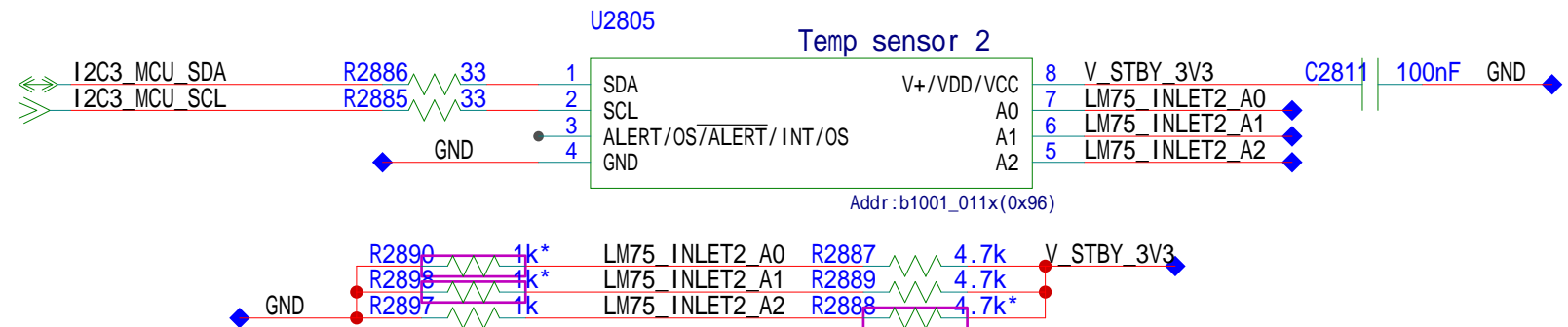
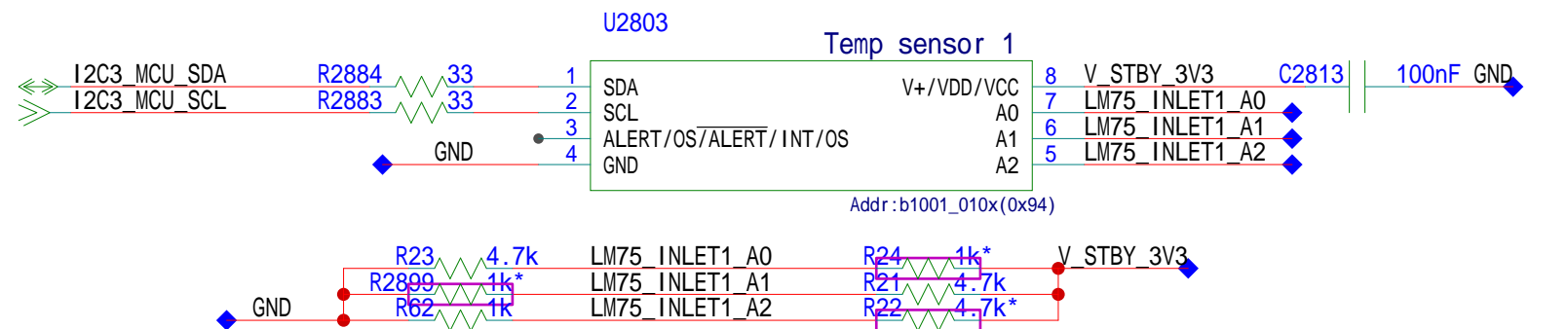
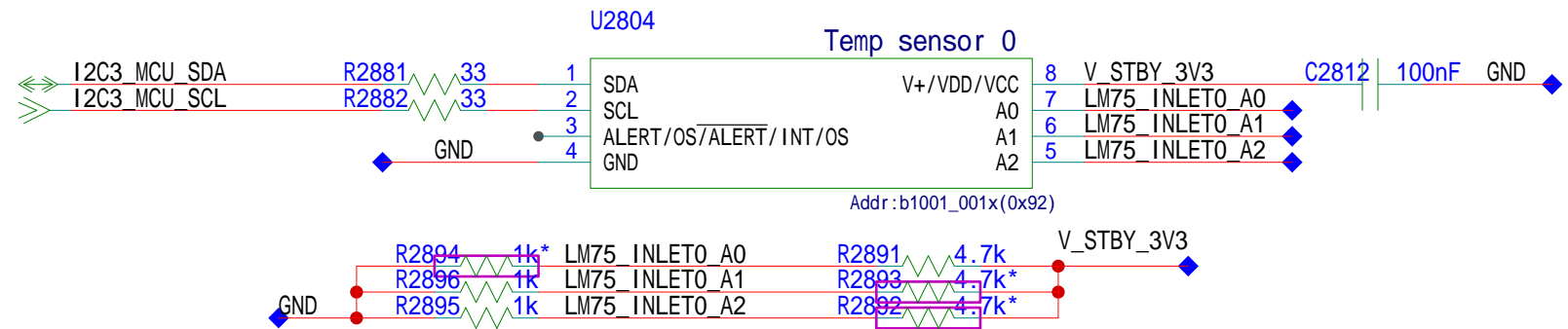
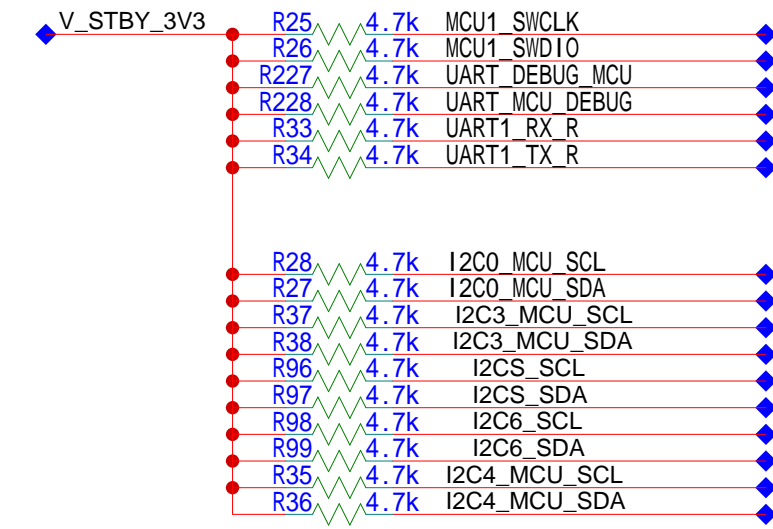
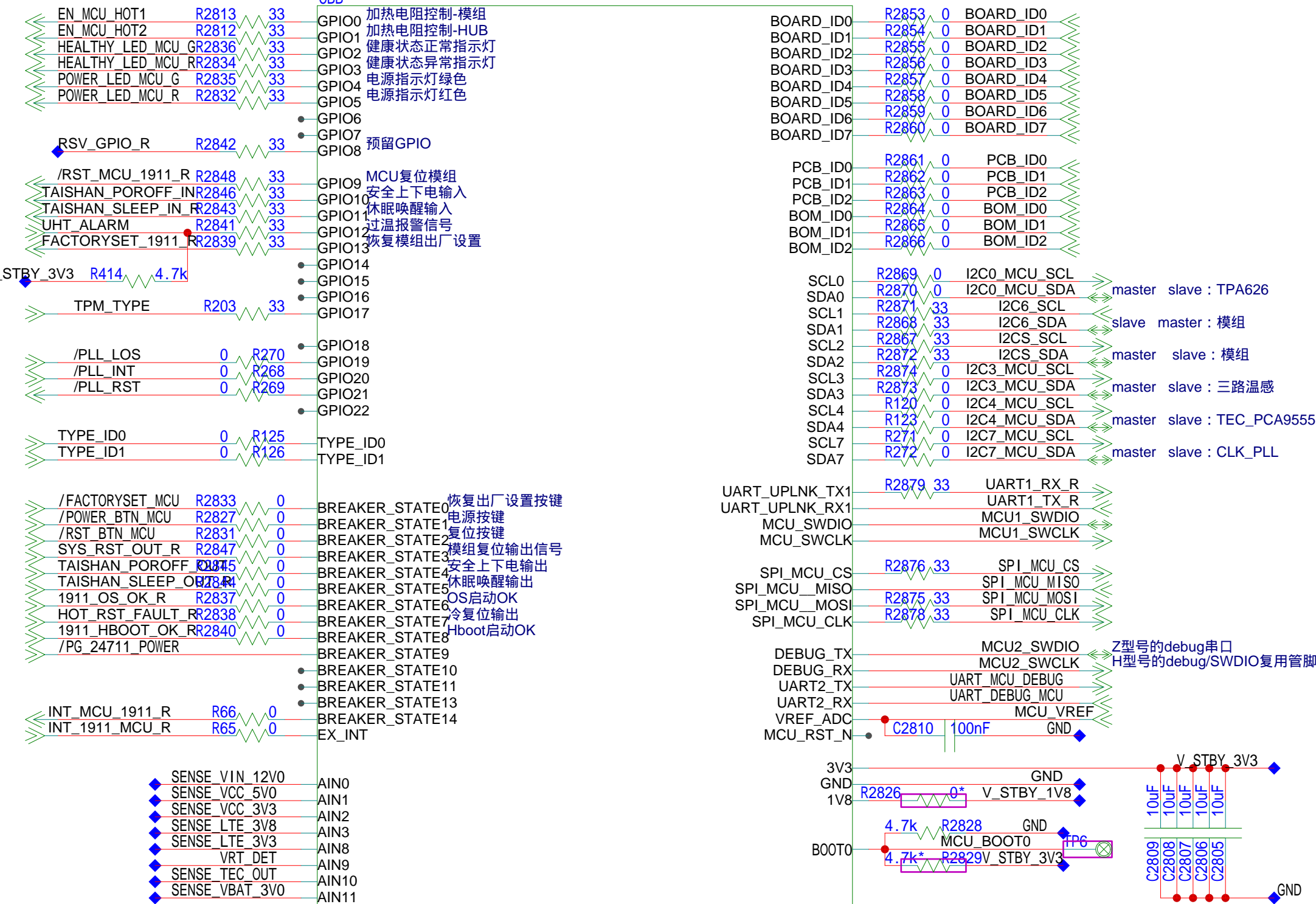
S47/AL27/X47 GPIOs use 3V3 pull-up.



AI27IDDIN type:18mA
S47 IDDIN type:125mA
X47 IDDIN type:70mA

Note: Pins 32, 46, and 60 use independent filter circuits. It is recommended that 100 nF capacitors be placed close to each pin on the PCB.

MCU



1

2

3

4

5

6

MCU CBB -1

A

A

B

B

C

C

D

D

MCU CBB电路

1

2

3

4

5

6

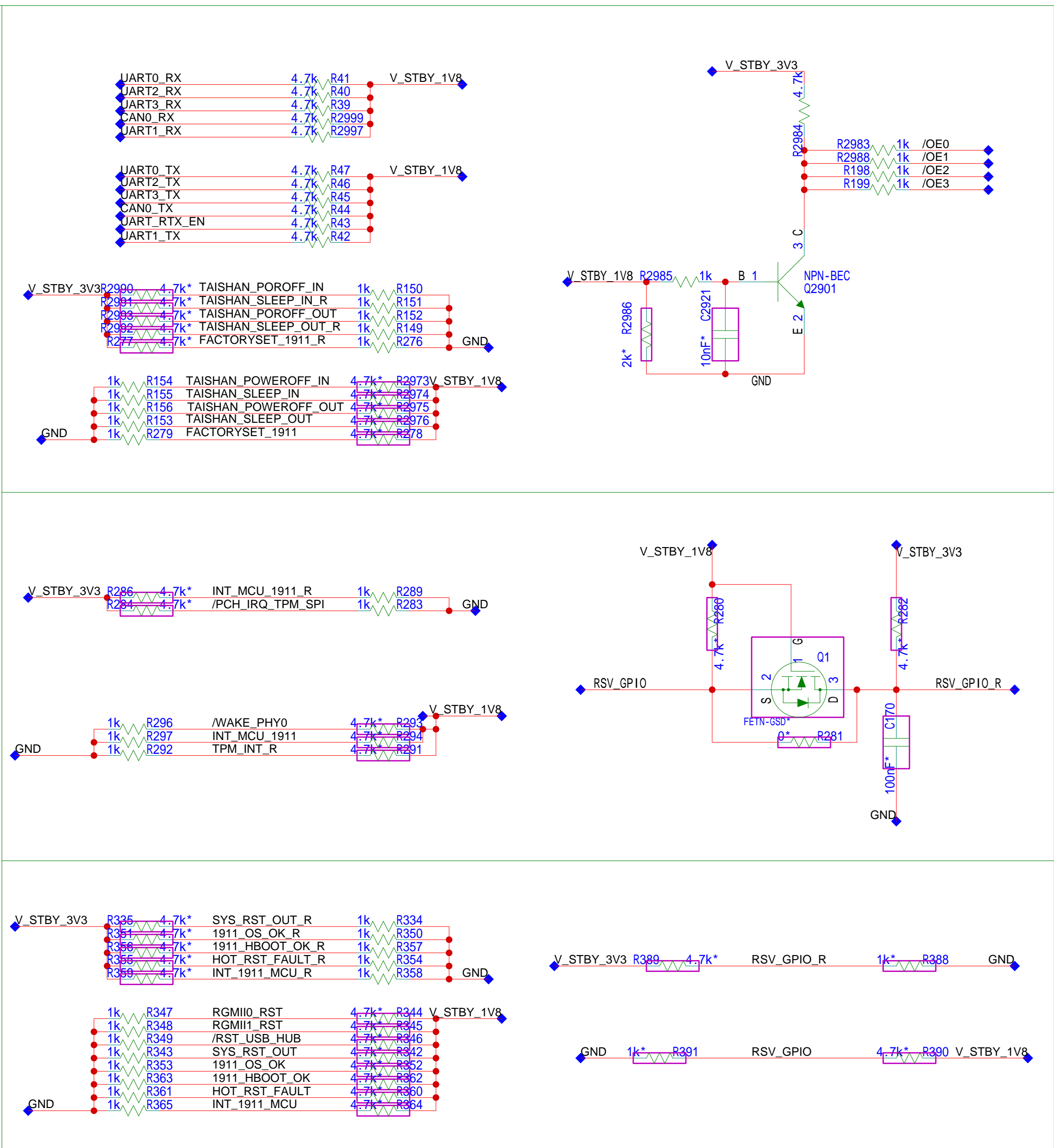
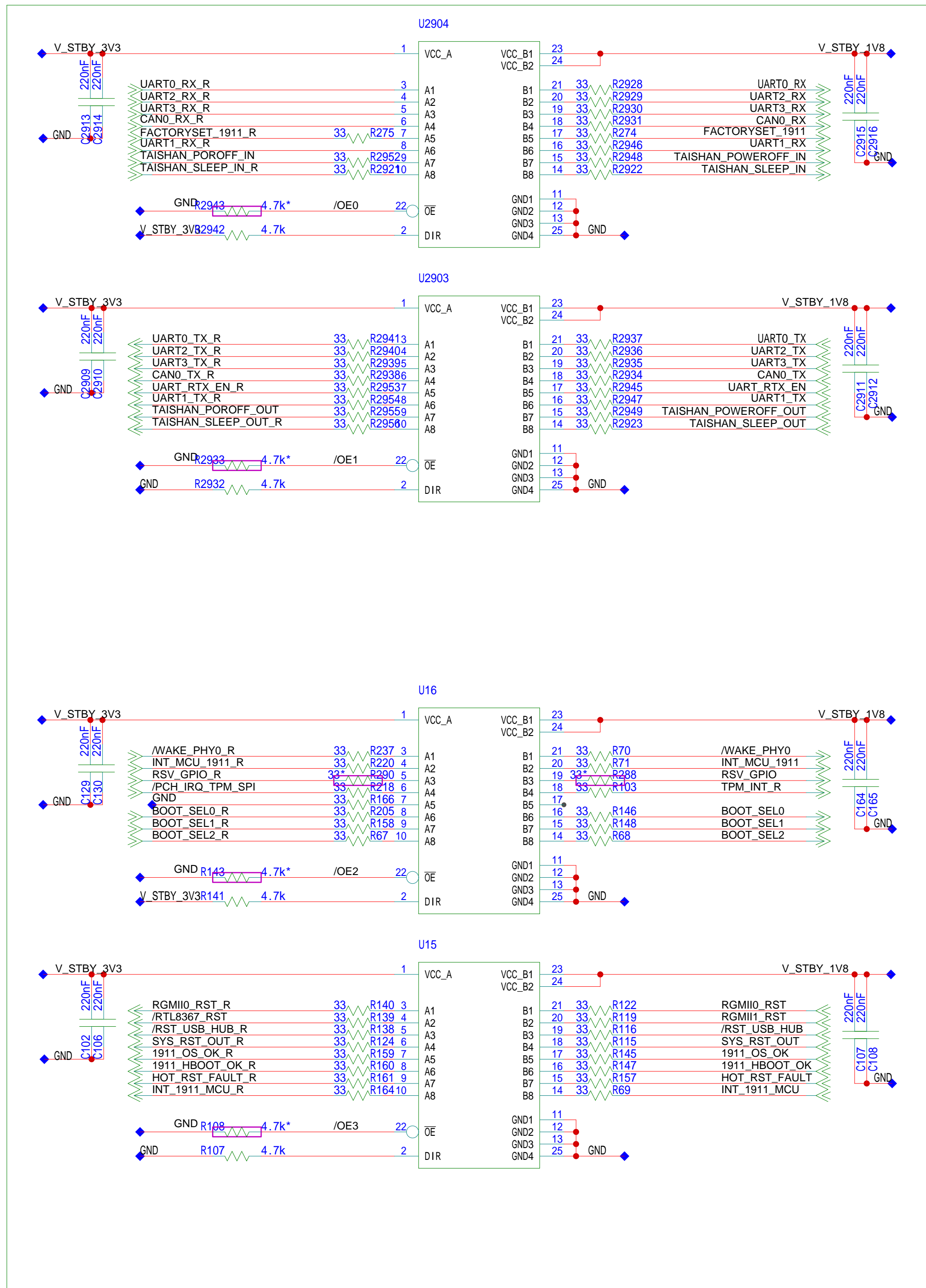
A



A

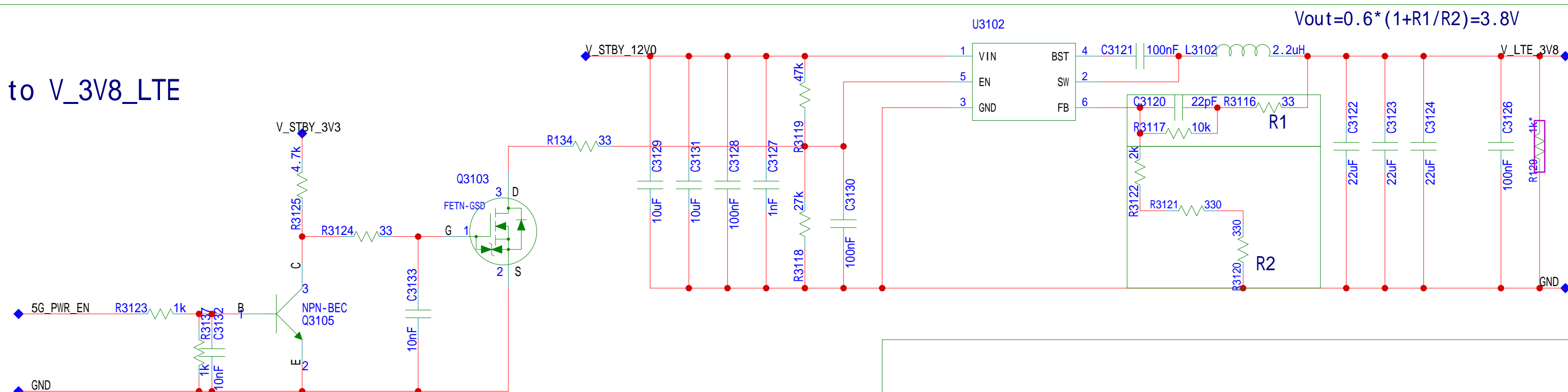
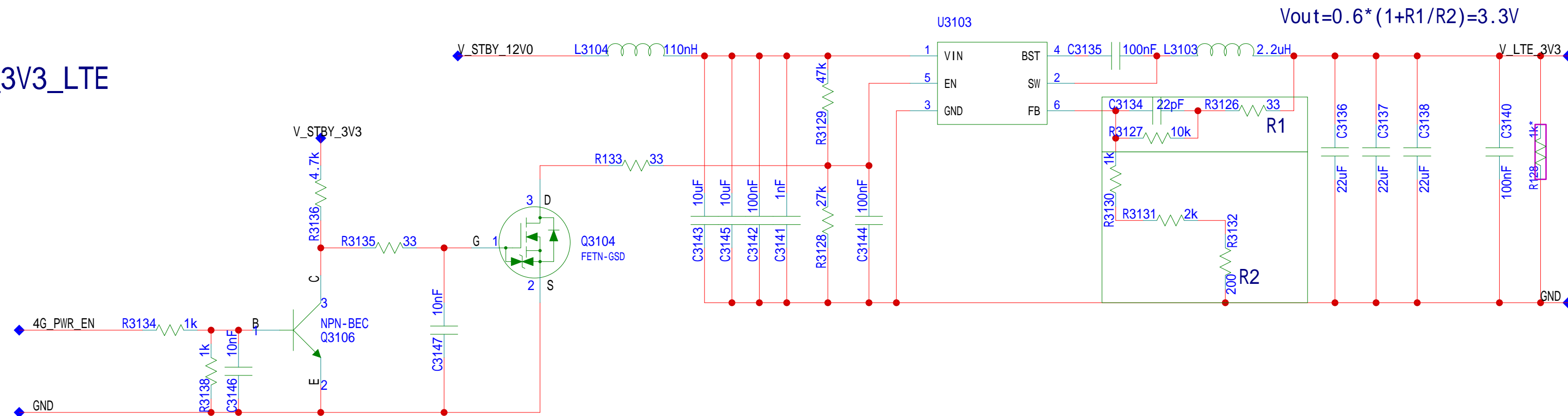
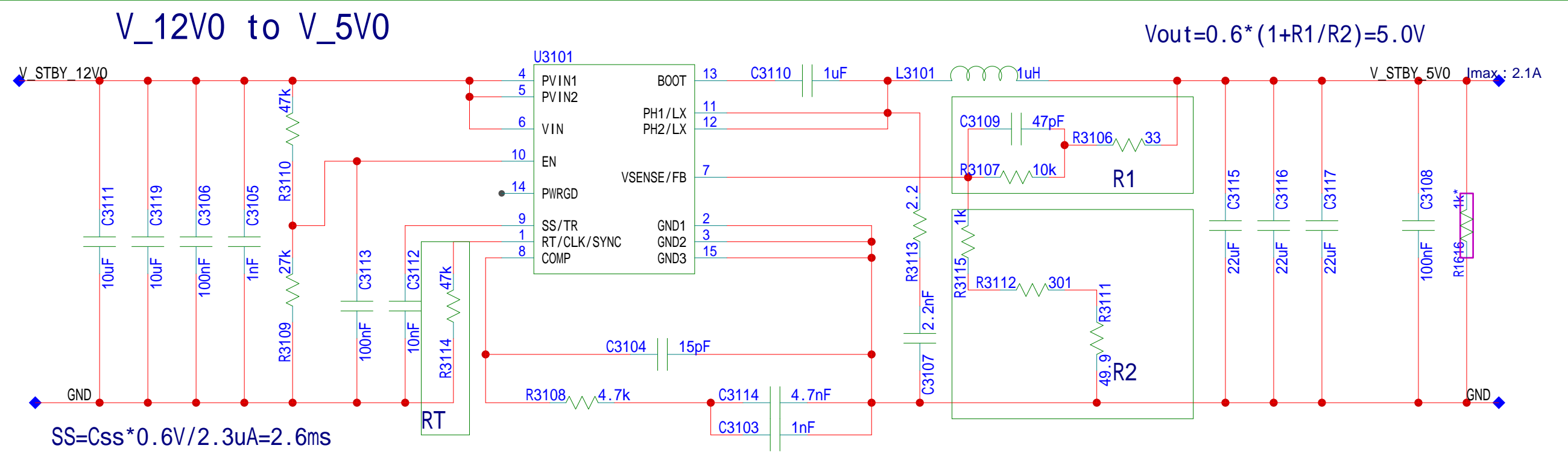
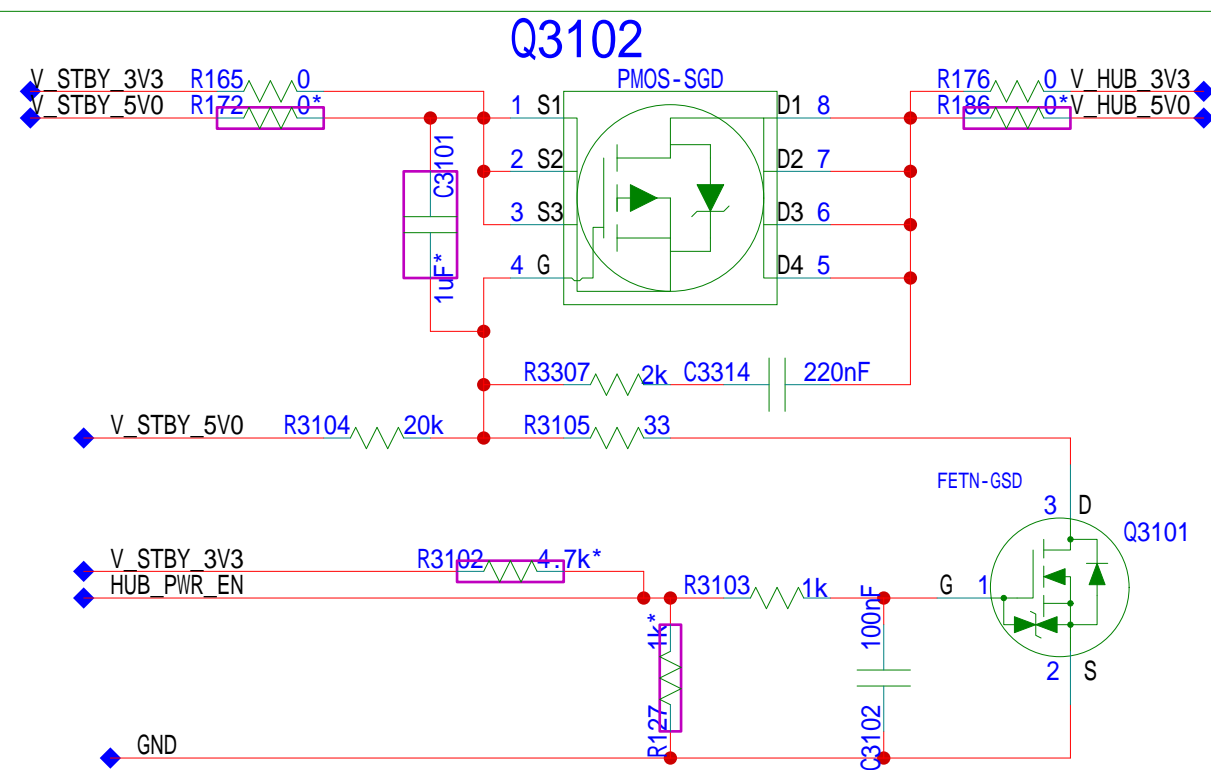


Level Shift

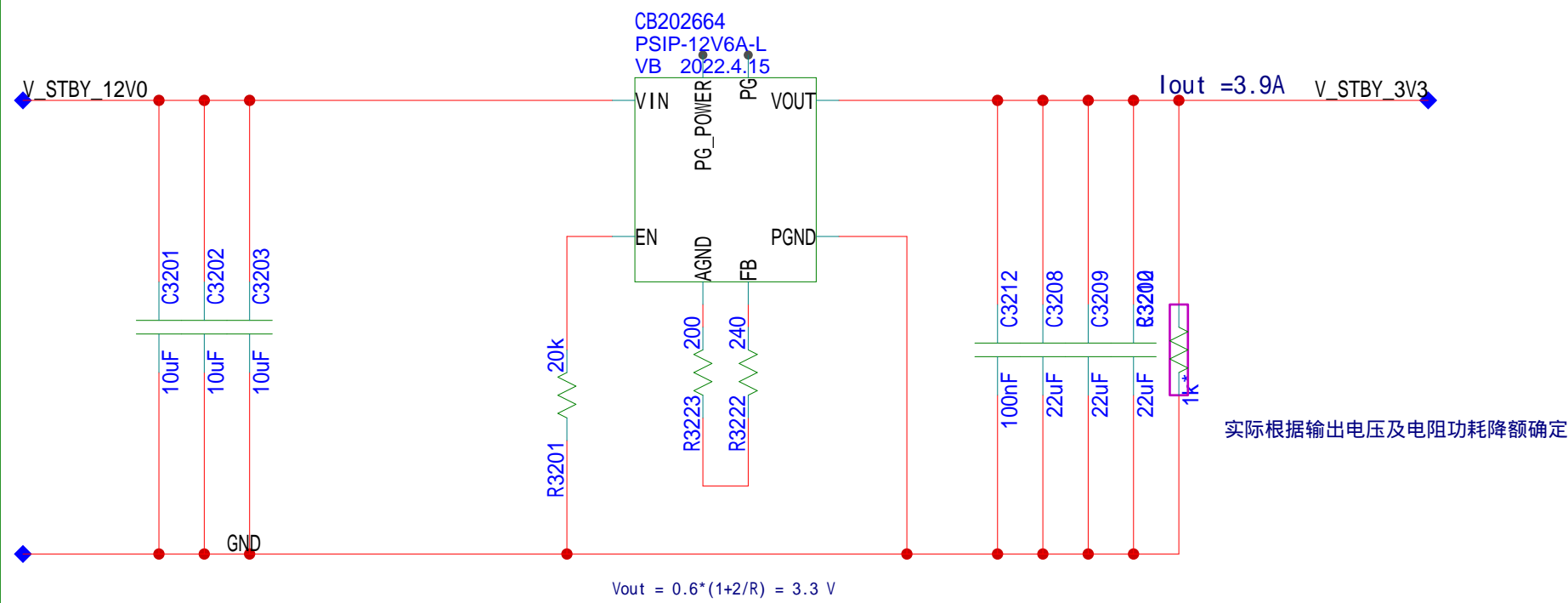


A

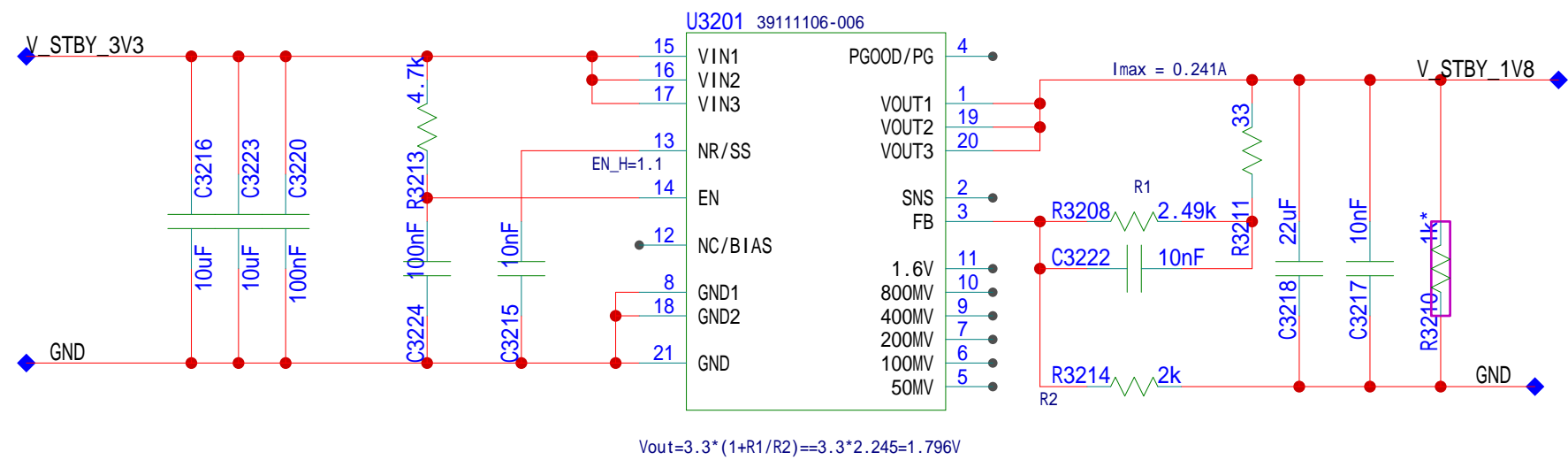




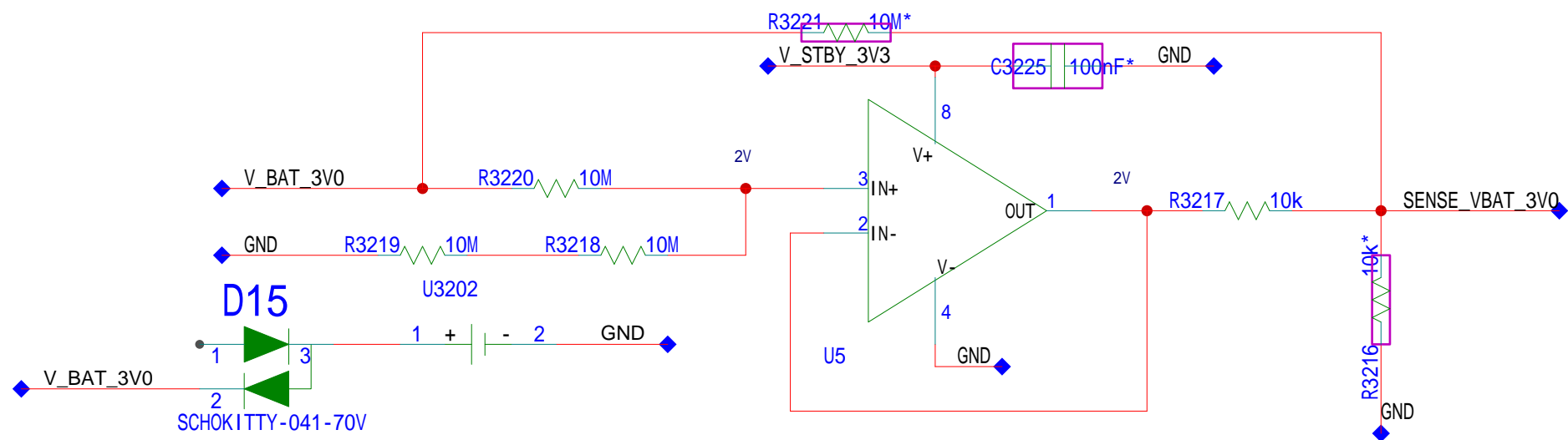
Power 12V to 3V3



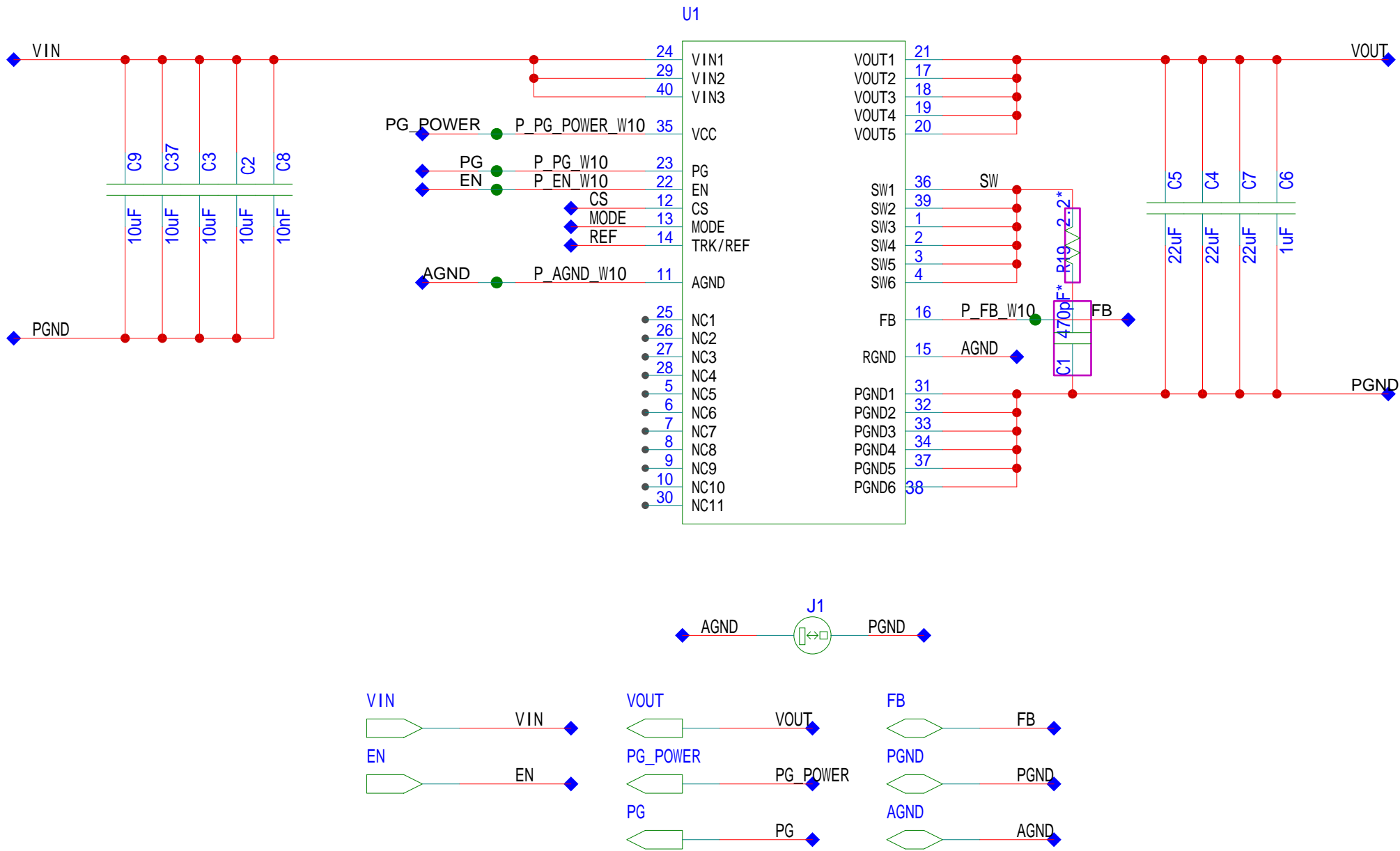
Power 3V3 to 1V8



RTC电源及电压检测



DC-DC CBB

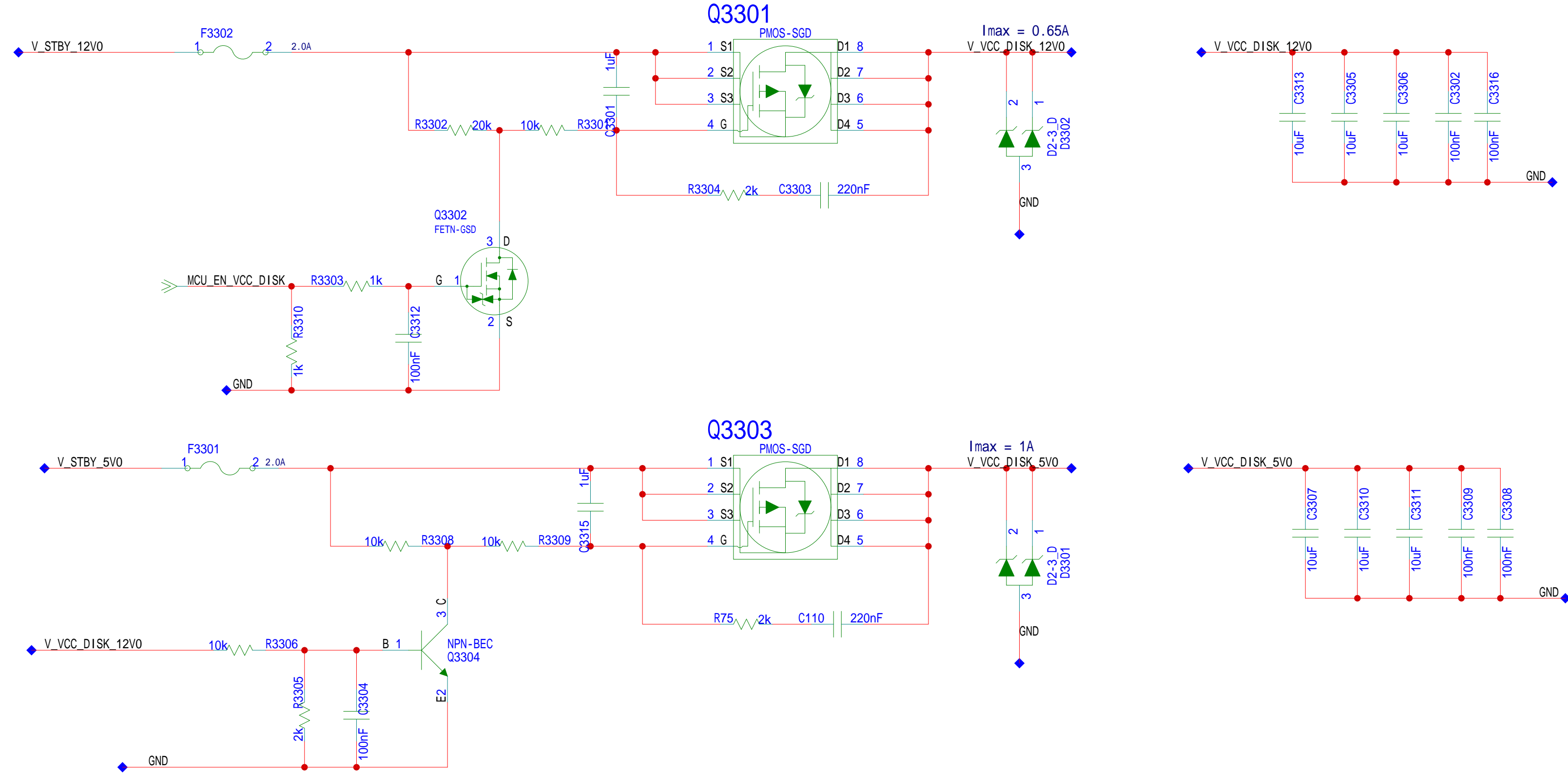


NOTE:详细资料参考应用设计指导书

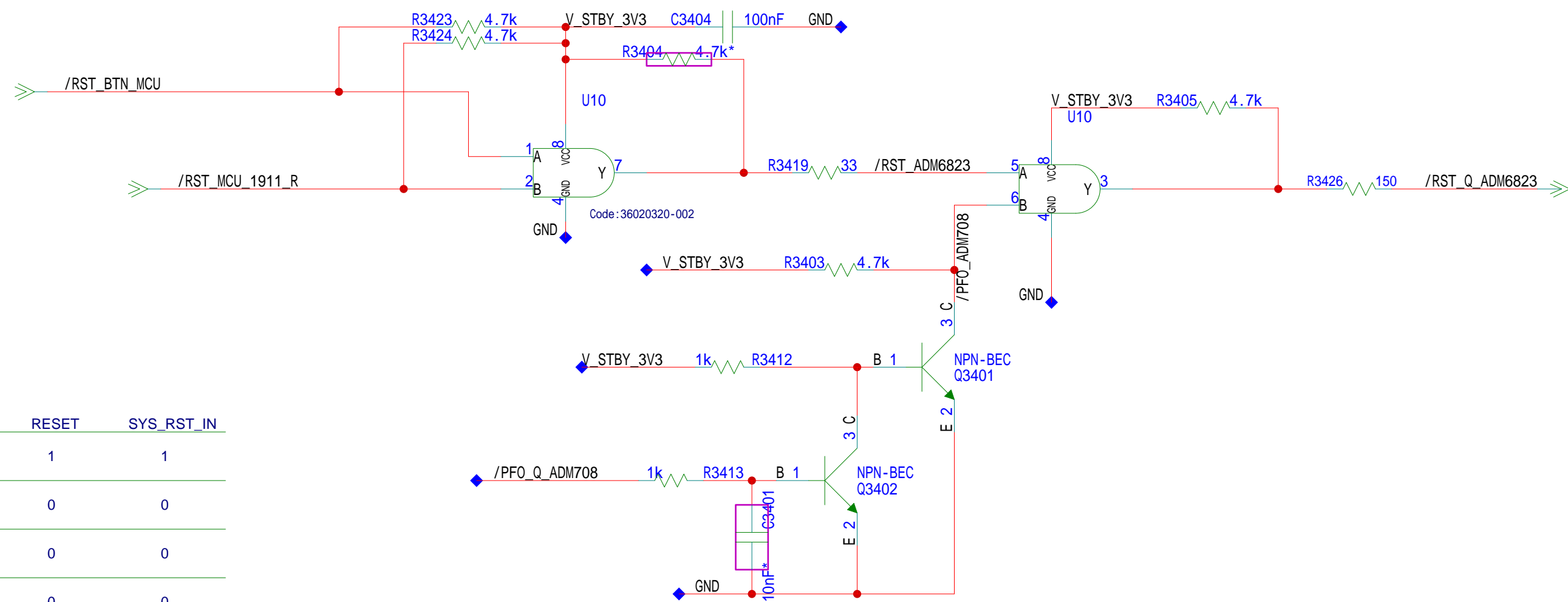
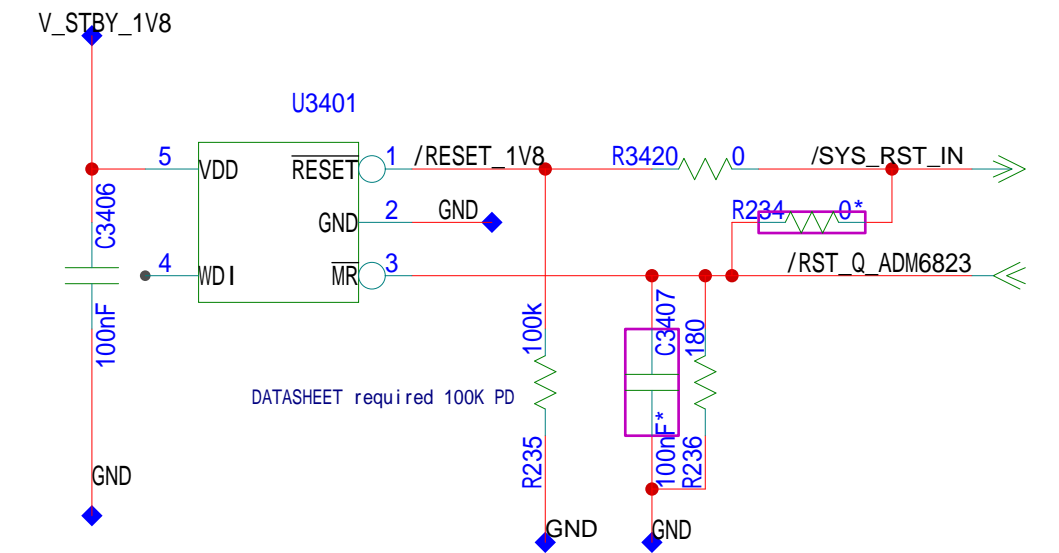
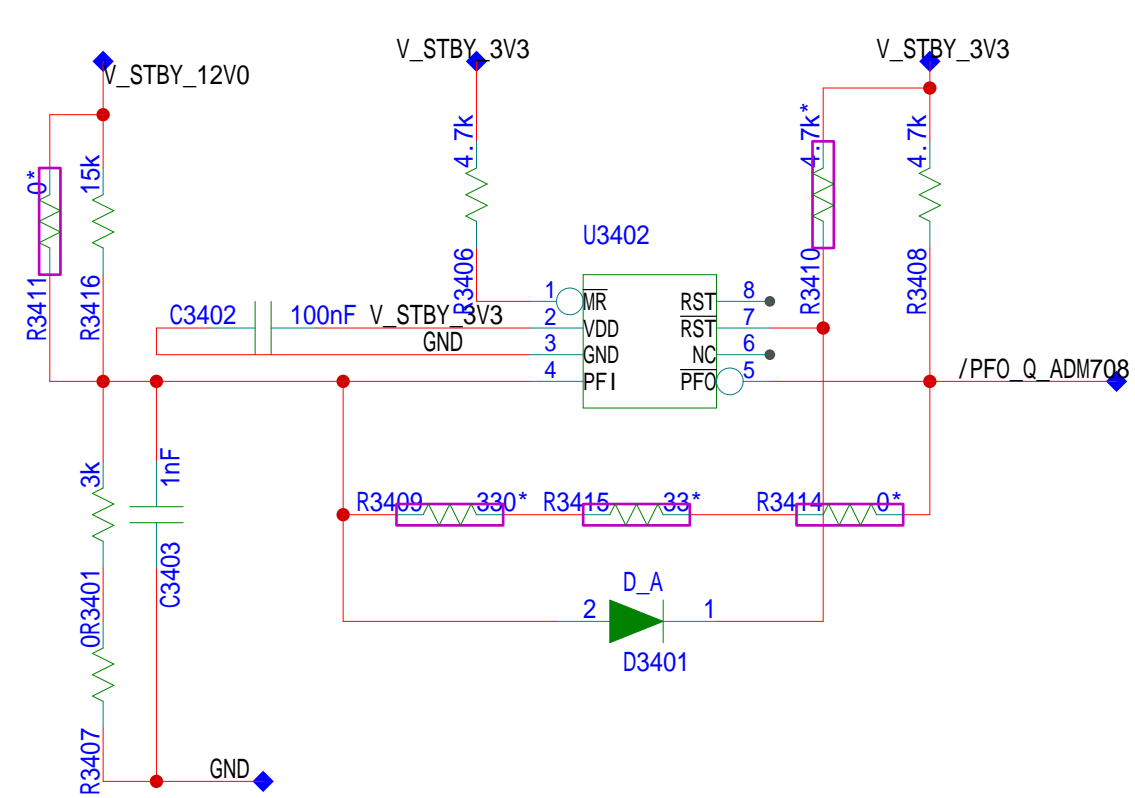
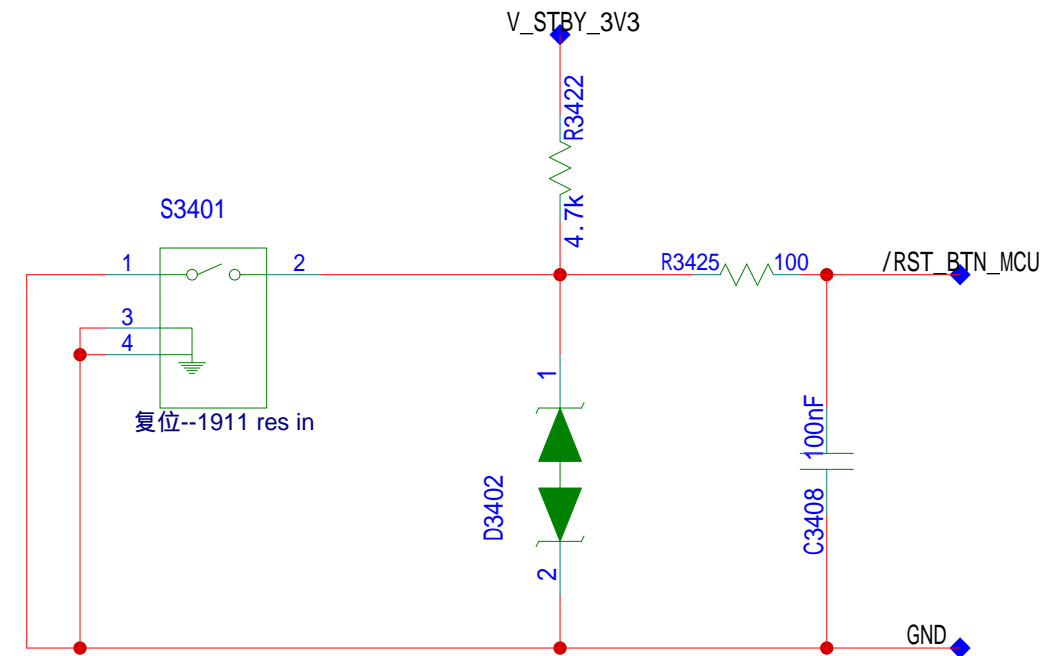
- 1、 Vin : Cin最小值为20uF+10nF瓷片电容；
- 2、 EN下拉电阻外置；在5V输出及以上场景时，CBB中EN下拉电阻R2001=17.4k（注：如要使用在5V输出以下场景，则需取R2001=20k）；该管脚不要外加电容
- 3、 VCC:默认悬空，使用PG时必须上拉到该管脚（3V）
- 4、 FB:输出调节，通过FB和RGND之间的电阻来调节输出电压，TRIM调节电阻R1和R2必须选择1%精度电阻。
- 5、 PG:不使用PG时悬空，使用时上拉大于等于3K电阻至VCC（3V），且串联一个1K电阻至I/O口，不推荐外部电源（小于3.6V）上拉，外部上拉在EN使能前会有一个0.6V电平；
- 6、 MODE:默认悬空，频率设定管脚
- 7、 CS:默认悬空，OCP点设定管脚，过流点电阻Rcs（59K）已内置
- 8、 Vout : Cout最小值为44uF瓷片电容；
- 9、 输出电压与输出电容配置见下表：输出电容选型，请与单板电源工程师讨论

输出电压	0.7V	1.2V	1.8V	3.3V	5.4V
输出电源	9*22UF	7*22UF	5*22UF	4*22UF	3*22UF

SATA Power



RST BTN



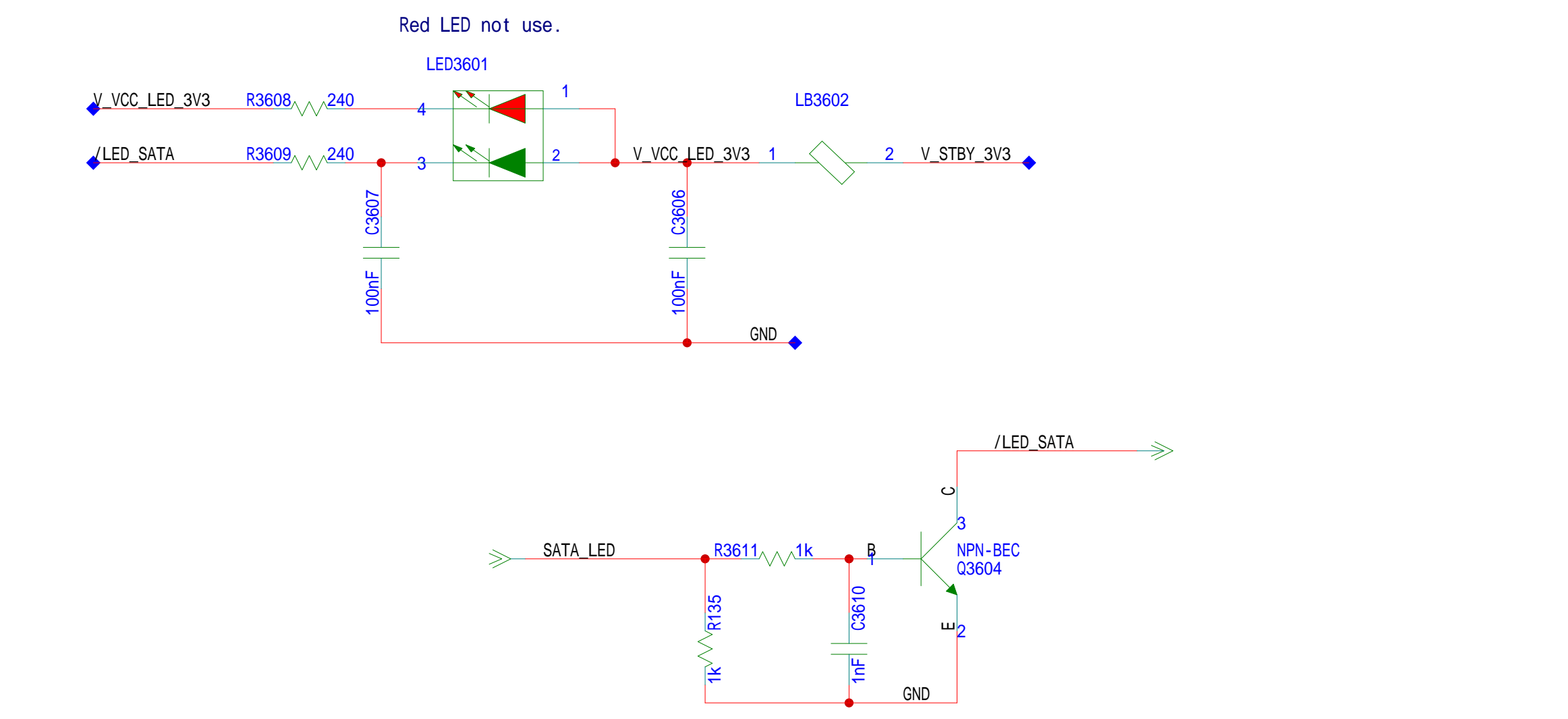
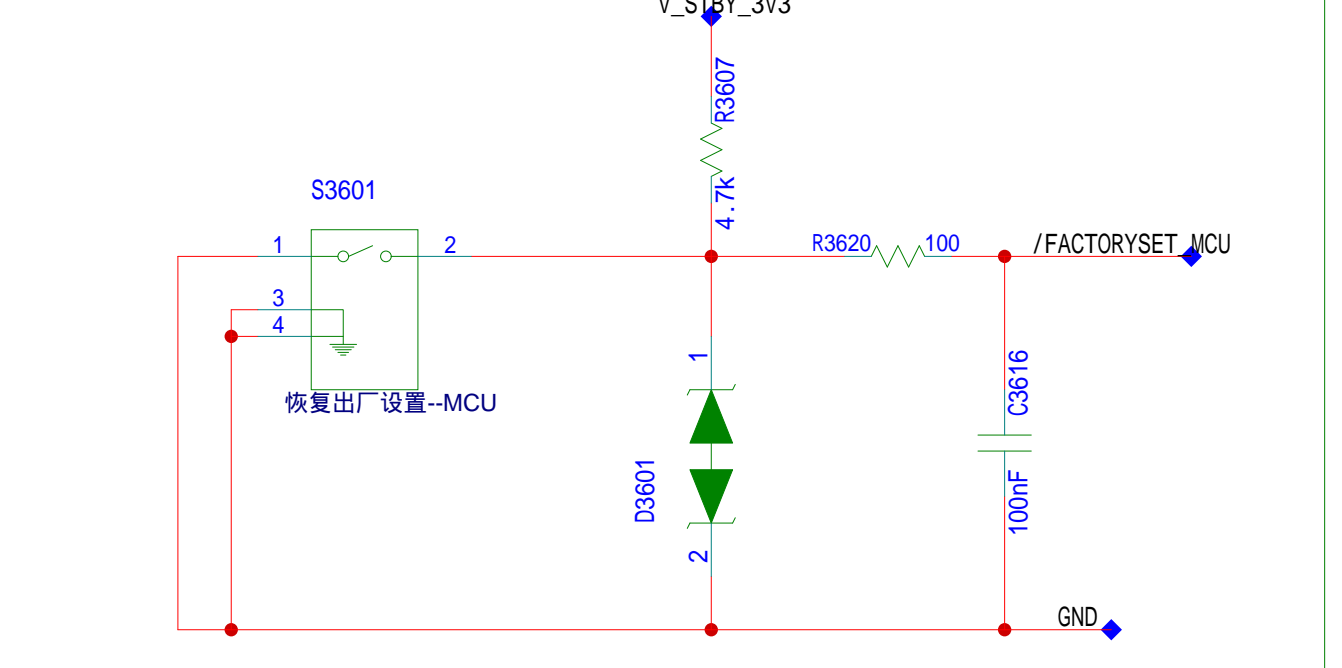
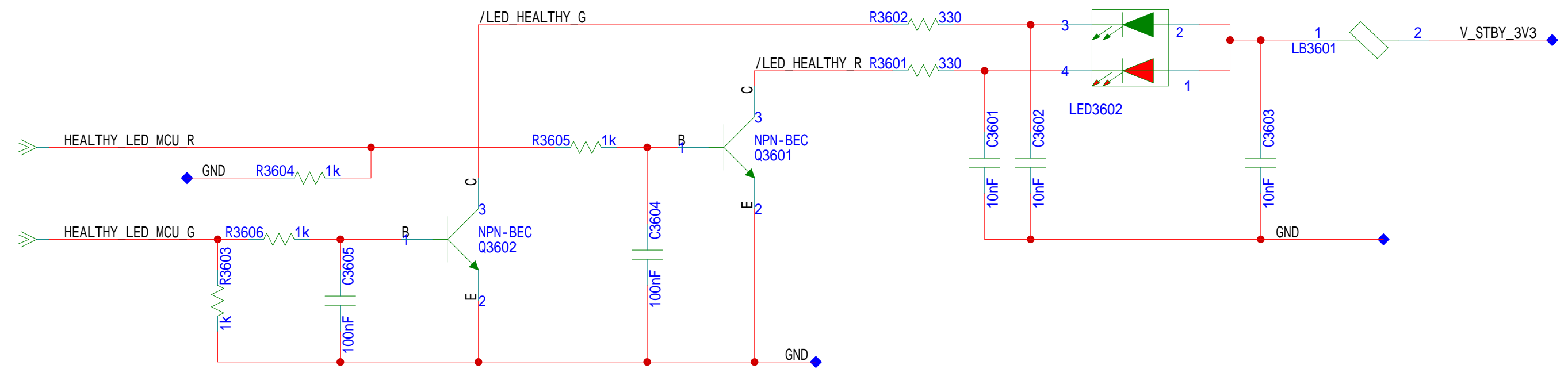
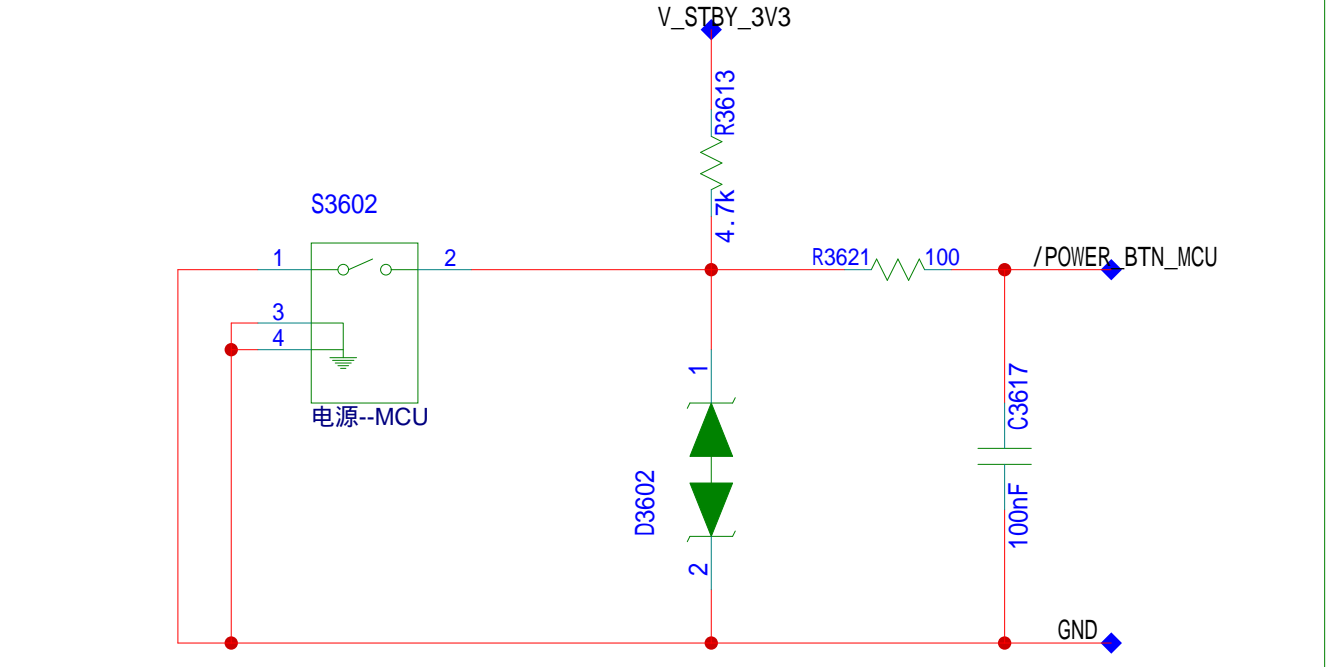
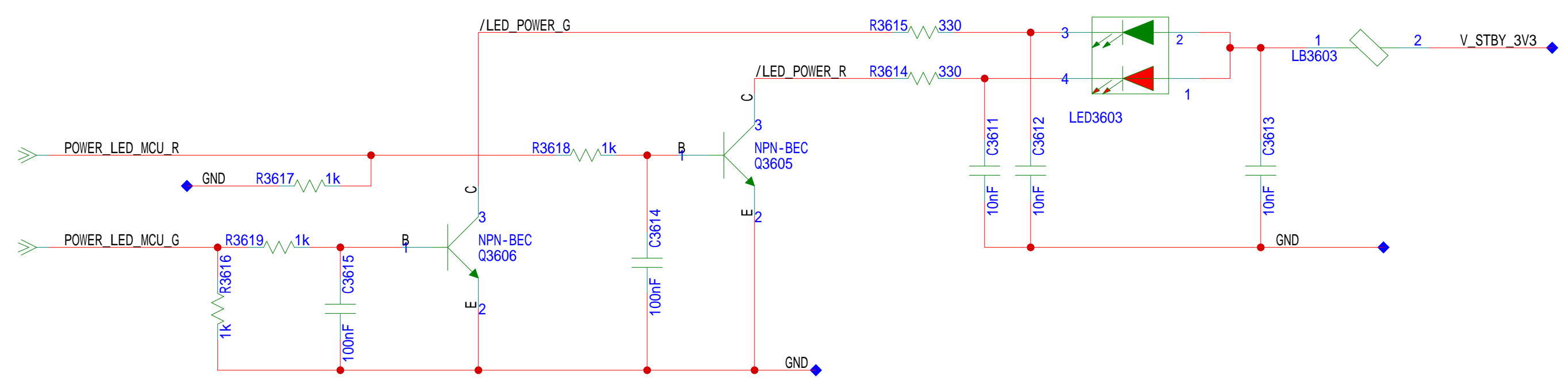
	BTN	MCU	PFO	RESET	SYS_RST_IN
Def	1	1	1	1	1
BTN	0	1	1	0	0
MCU	1	0	1	0	0
PFO	1	1	0	0	0

A



加热电阻随HUB选择不上件，两个HUB各使用7PCS加热电阻，共用2PCS

LED & Tact Switch



LED导光柱

